

MODEL NAME : **QBL00**

PCB NO : **QC:LA-7851P, DAA00003200**

DC:LA-7852P, DAA00003300

BOM P/N : **TBD**

Dell/Compal Confidential

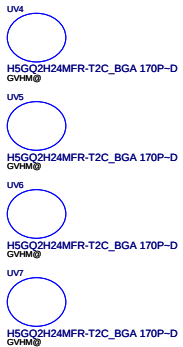
Schematic Document

Phantom(Chief River)

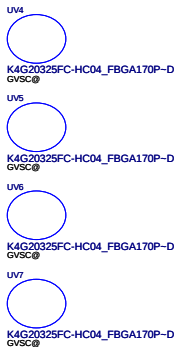
Ivy Bridge(BGA1224) + Panther Point

DISCRETE VGA N13P-GS(optimus)

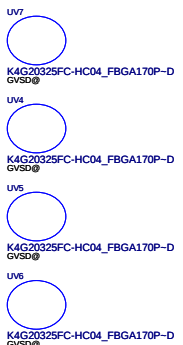
GV+Hyn M 1G R1



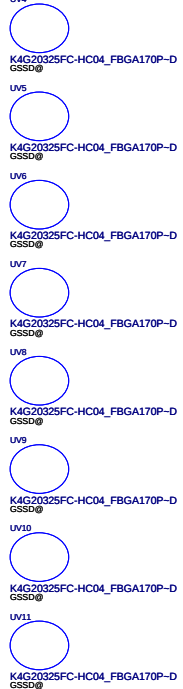
GV+SAM C 1G R1



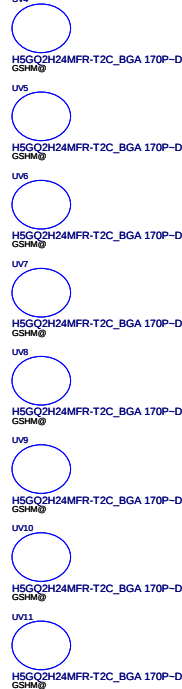
GV+SAM D 1G R1



GS+SAM D 2G R1



GS+Hyn M 2G R1



2011-08-02

Rev: 0.1 (X00)

@ : Nopop Component

CONN@ : Connector Component

DP1.2@ : DP output from DGPU

DP1.1A@ : DP output from iGPU

GV@ : GPU N13-GV

GS@ : GPU N13-GS

GVH@ :GV+Hynix VRAM

GVS@ : GV+Samsung VRAM

GSH@ : GS+Hynix VRAM

GSS@ : GS+Samsung VRAM

GVHA@ : GV+Hynix VRAM A-die

GVHM@ : GV+Hynix VRAM M-die

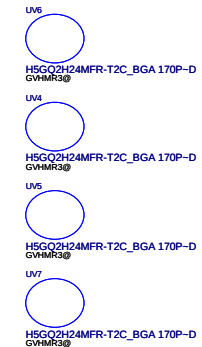
GVSC@ : GV+Samsung VRAM C-die

GVSD@ : GV+Samsung VRAM D-die

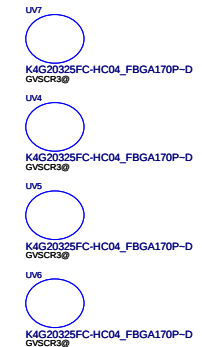
SB@ : Sandy bridge CPU

TPM@ : With TPM

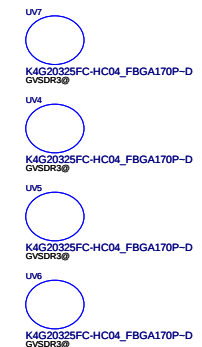
GV+Hyn M 1G R3



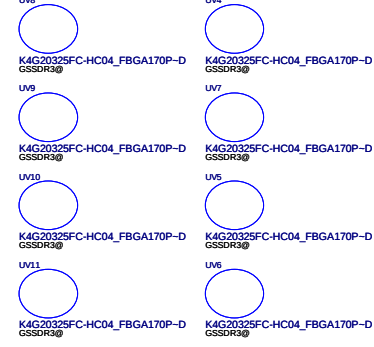
GV+SAM C 1G R3



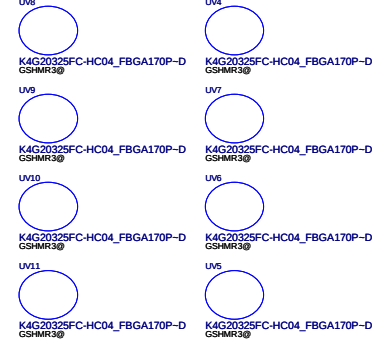
GV+SAM D 1G R3



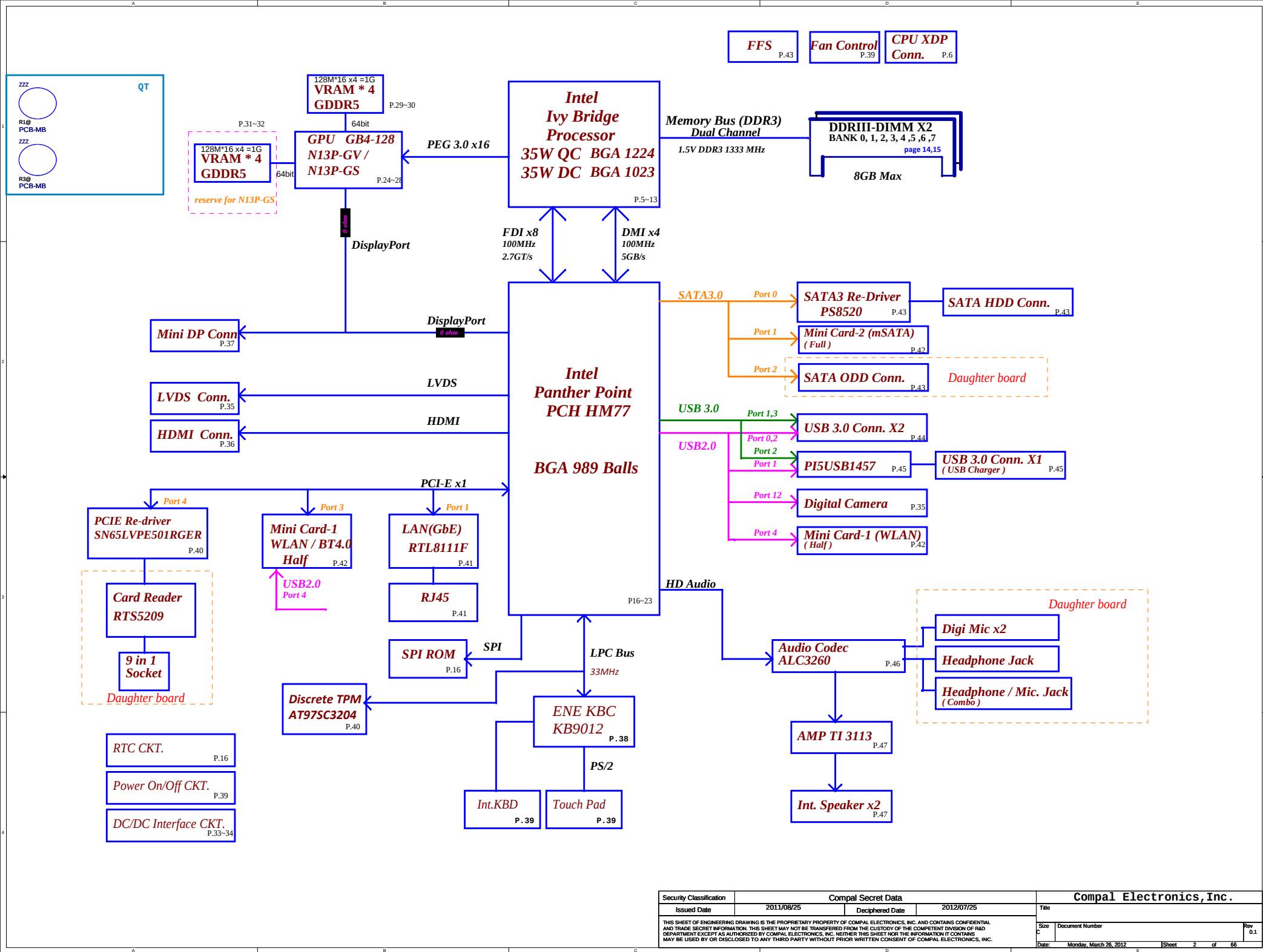
GS+SAM D 2G R3



GS+HYN M 2G R3



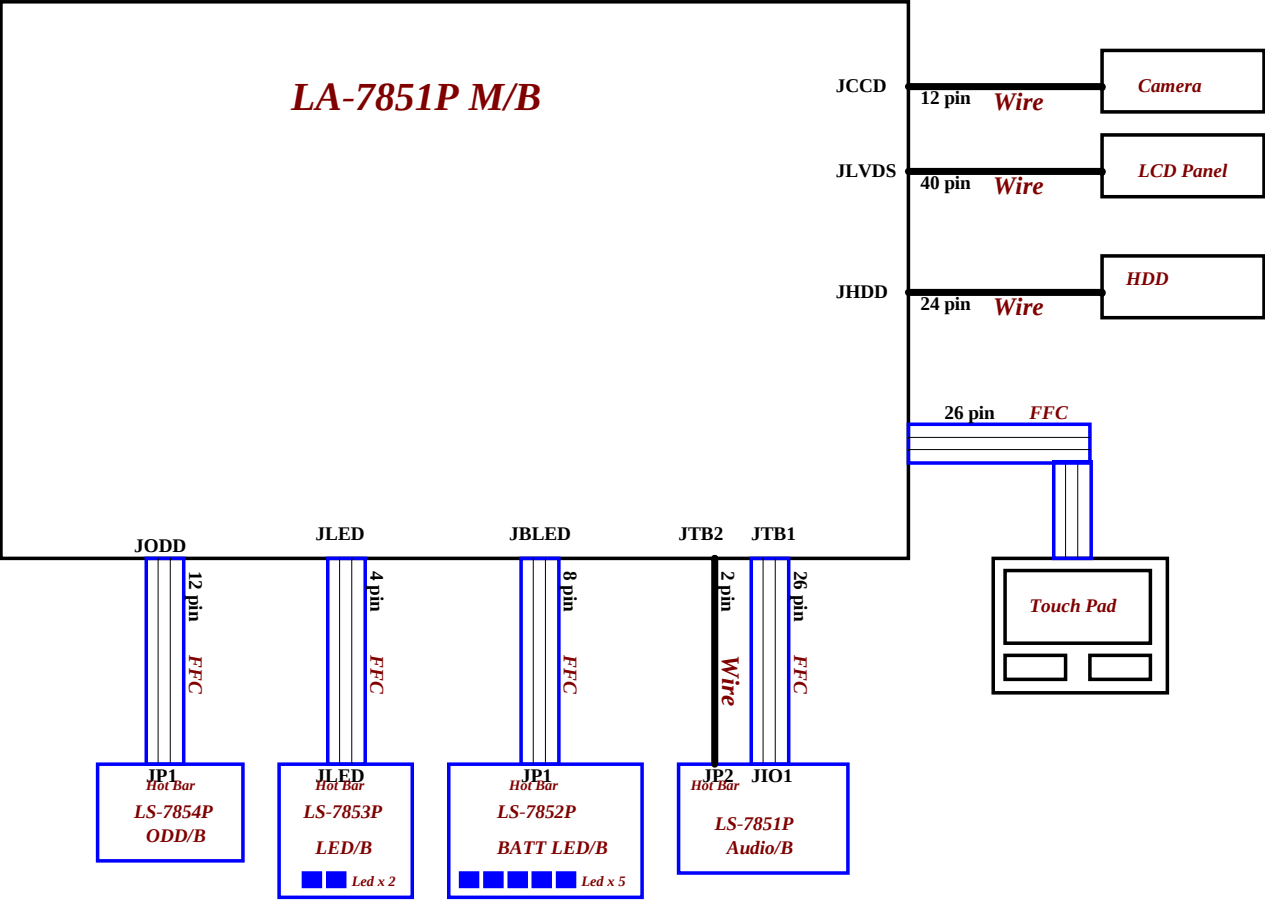
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Issued Date	2011/08/25	Deciphered Date	2011/08/25	Title	Cover Page	
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				Date	Monday, March 26, 2012	Sheet 1 of 65



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Project Code : QBL00

File Name : LA-7851P



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				Size	Document Number
				Date	Rev
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				Sheet	3 of 66

Board ID Table for AD channel

Vcc	3.3V +/- 5%				
Ra	100K +/- 5%				
Board ID	Rb	VAD_BID min	VAD_BID typ	VAD_BID max	EC_AD3
0	0	0 V	0 V	0.155 V	0x00-0x0C
1	8.2K +/- 5%	0.168 V	0.250 V	0.362 V	0x0D-0x1C
2	18K +/- 5%	0.375 V	0.503 V	0.621 V	0x1D-0x30
3	33K +/- 5%	0.634 V	0.819 V	0.945 V	0x31-0x49
4	56K +/- 5%	0.958 V	1.185 V	1.359 V	0x4A-0x69
5	100K +/- 5%	1.372 V	1.650 V	1.838 V	0x6A-0x8E
6	200K +/- 5%	1.851 V	2.200 V	2.420 V	0x8F-0xBB
7	NC	2.433 V	3.300 V	3.300 V	0xBC-0xFF

BOARD ID Table

Board ID	PCB Revision
0	0.1
1	0.2
2	0.3
3	0.4
4	1.0
5	
6	
7	

PCI EXPRESS	DESTINATION
Lane 1	10/100/1G LAN
Lane 2	None
Lane 3	MINI CARD-1 WLAN
Lane 4	CARD READER
Lane 5	None
Lane 6	None
Lane 7	None
Lane 8	None

SATA	DESTINATION
SATA0	HDD
SATA1	SSD
SATA2	ODD
SATA3	None
SATA4	None
SATA5	None

CLKOUT	DESTINATION
PCI0	PCH_LOOPBACK
PCI1	EC LPC
PCI2	None
PCI3	None
PCI4	None

PCH	USB PORT#	DESTINATION
	0	USB Conn 1
	1	USB Conn 3 (Power share)
	2	USB Conn 2
	3	None
	4	JMINI1 (WLAN)
	5	None
	6	None
	7	None
	8	None
	9	None
	10	None
	11	None
	12	CAMERA
	13	None

USB3	DESTINATION
1	USB Conn 1
2	USB Conn 3 (Power share)
3	USB Conn 2
4	None

CLK	DIFFERENTIAL	DESTINATION	FLEX CLOCKS	DESTINATION
	CLKOUT_PCIE0	None	CLKOUTFLEX0	CLK_PCI_TPM
	CLKOUT_PCIE1	10/100/1G LAN	CLKOUTFLEX1	None
	CLKOUT_PCIE2	None	CLKOUTFLEX2	LAN_25M
	CLKOUT_PCIE3	MINI CARD-1 WLAN	CLKOUTFLEX3	None
	CLKOUT_PCIE4	CARD READER		
	CLKOUT_PCIE5	None		
	CLKOUT_PCIE6	None		
	CLKOUT_PCIE7	None		
	CLKOUT_PEG_B	None		

Symbol Note :



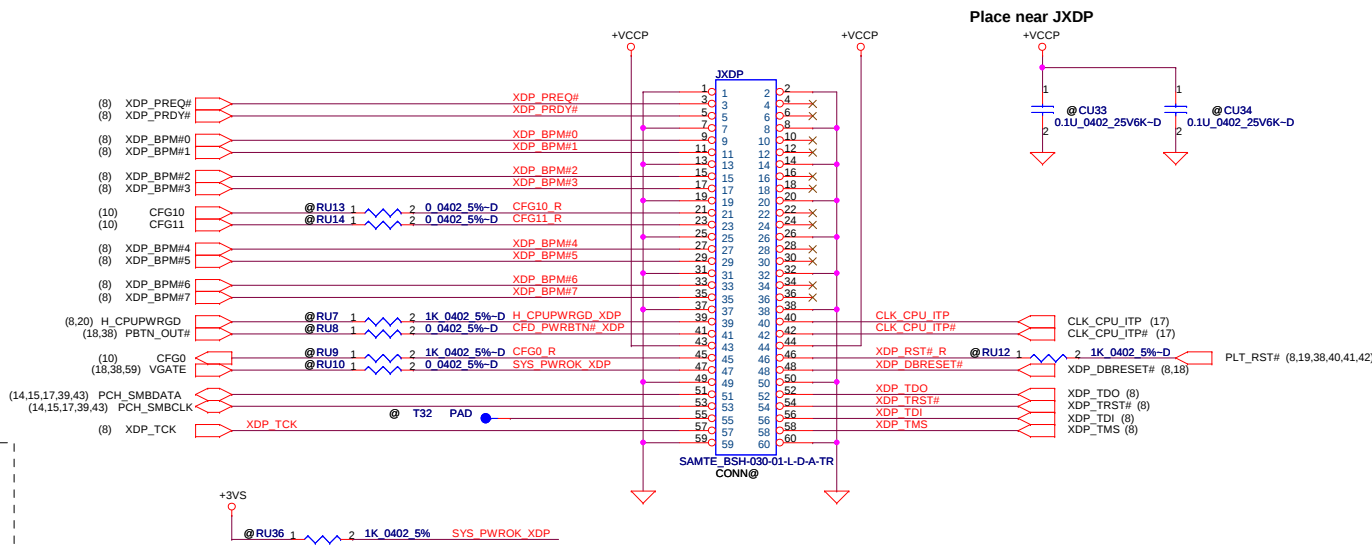
: means Digital Ground



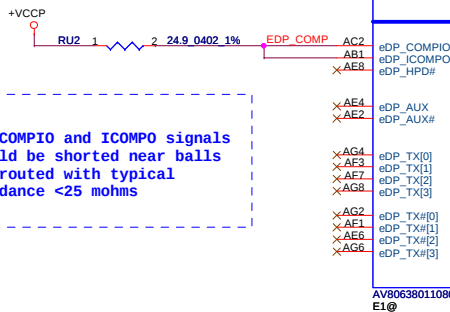
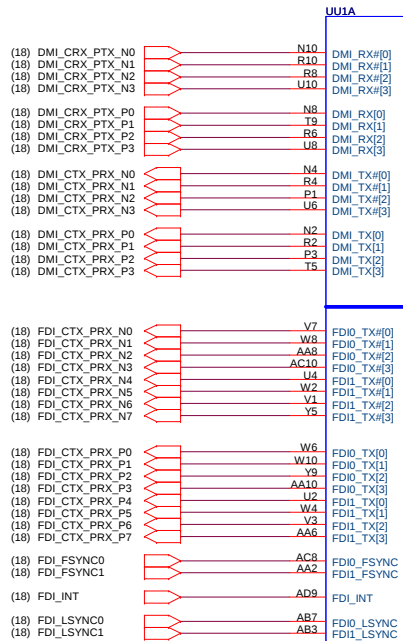
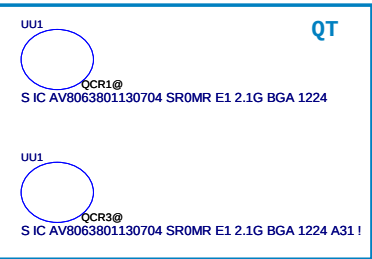
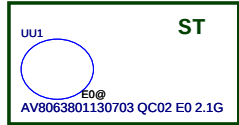
: means Analog Ground

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XDP CONN

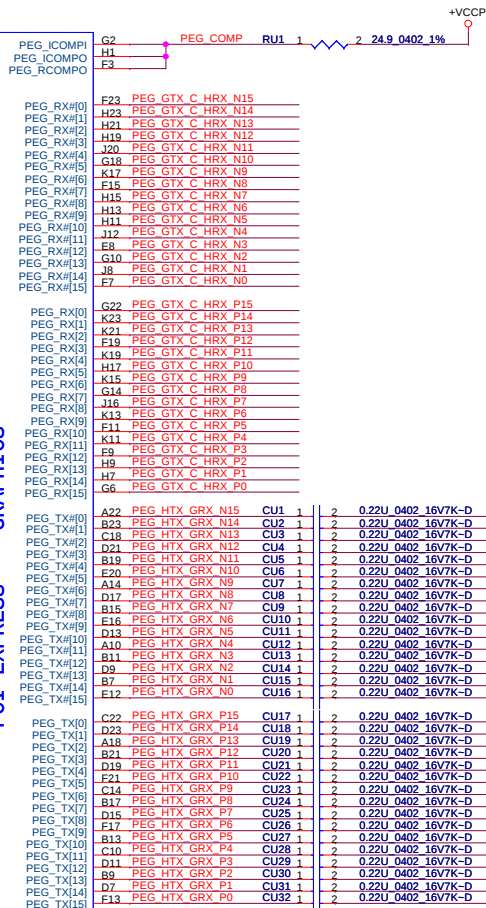


The resistor for HOOK2 should be placed such that the stub is very small on CFG0 net



eDP_COMPPIO and ICOMPO signals should be shorted near balls and routed with typical impedance <25 mohms

DMI
FDI (R) Internal
PCI EXPRESS -- GRAPHICS

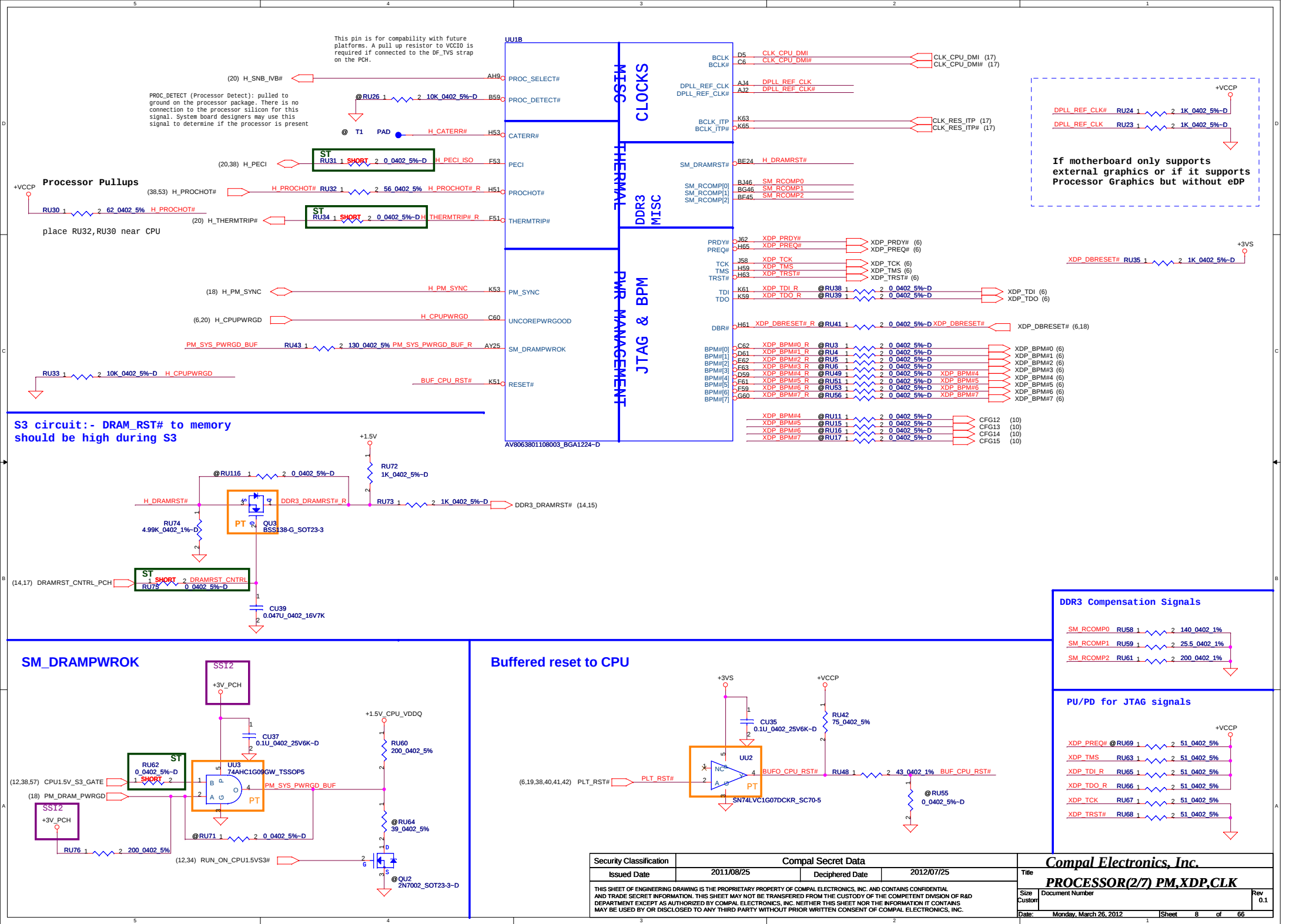


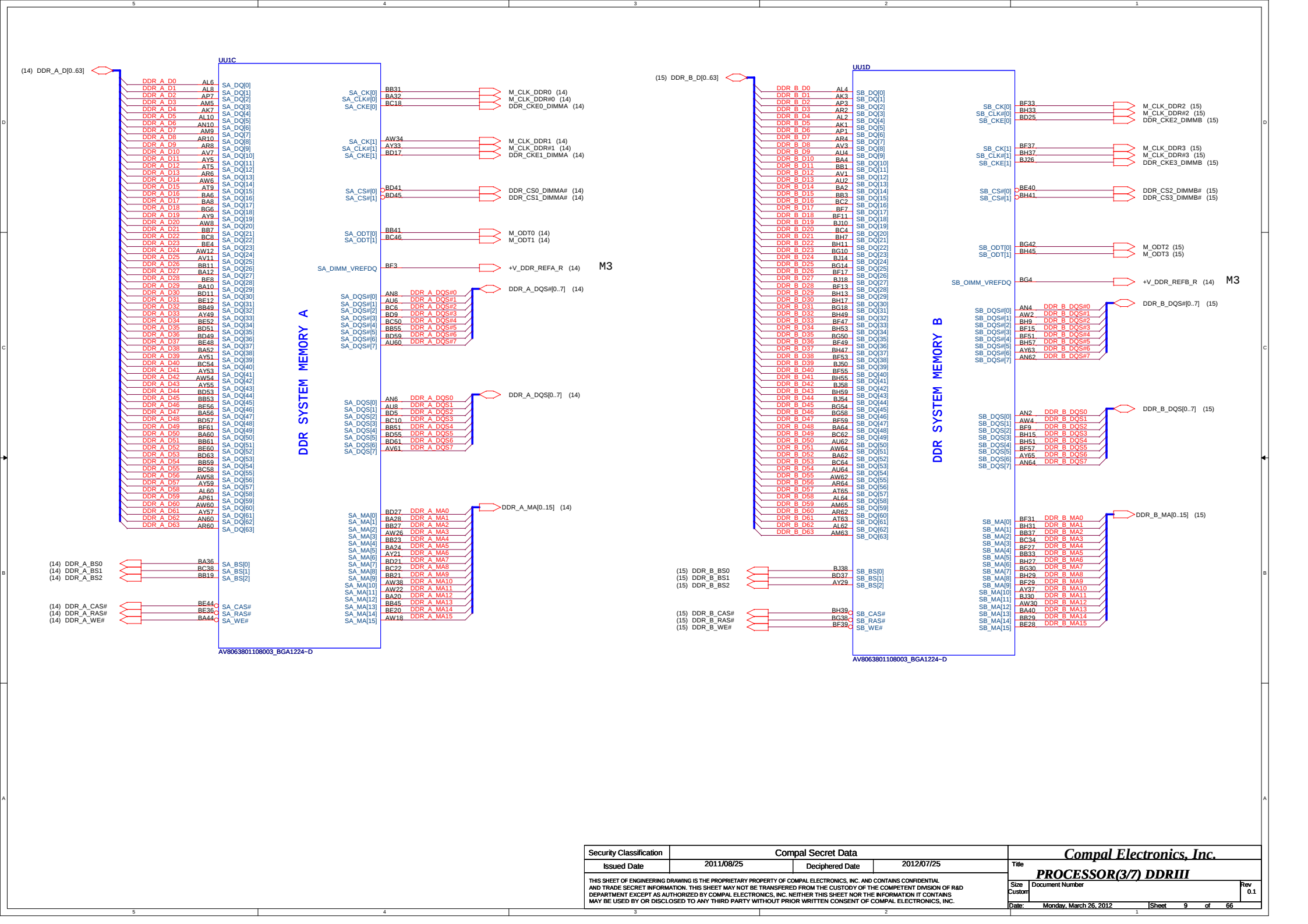
PEG_ICOMPI and RCOMPO signals should be shorted and routed with - max length = 500 mils - typical impedance = 43 mohms
PEG_ICOMPO signals should be routed with - max length = 500 mils - typical impedance = 14.5 mohms



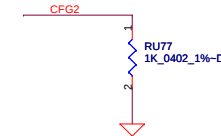
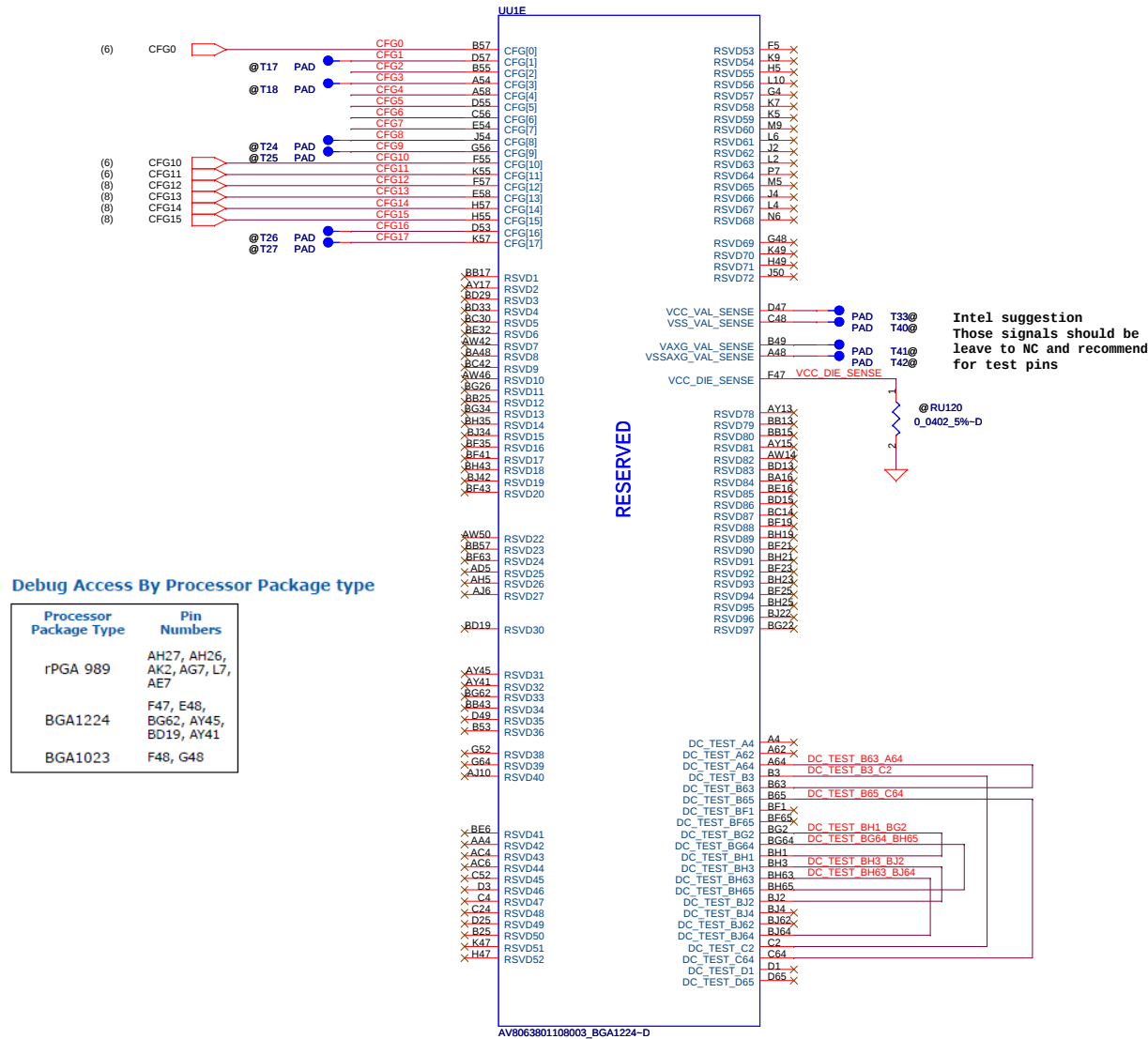
Typ- suggest 220nF. The change in AC capacitor value from 100nF to 220nF is to enable compatibility with future platforms having PCIE Gen3 (8GT/s)

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Deciphered Date				2012/07/25				Rev 0.1			
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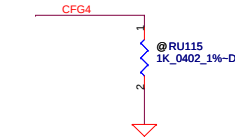




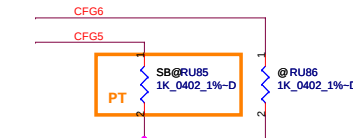
CFG Straps for Processor



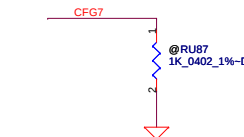
PEG Static Lane Reversal - CF62 is for the 16x	
CFG2	1: Normal Operation; Lane # definition matches socket pin map definition * 0: Lane Reversed



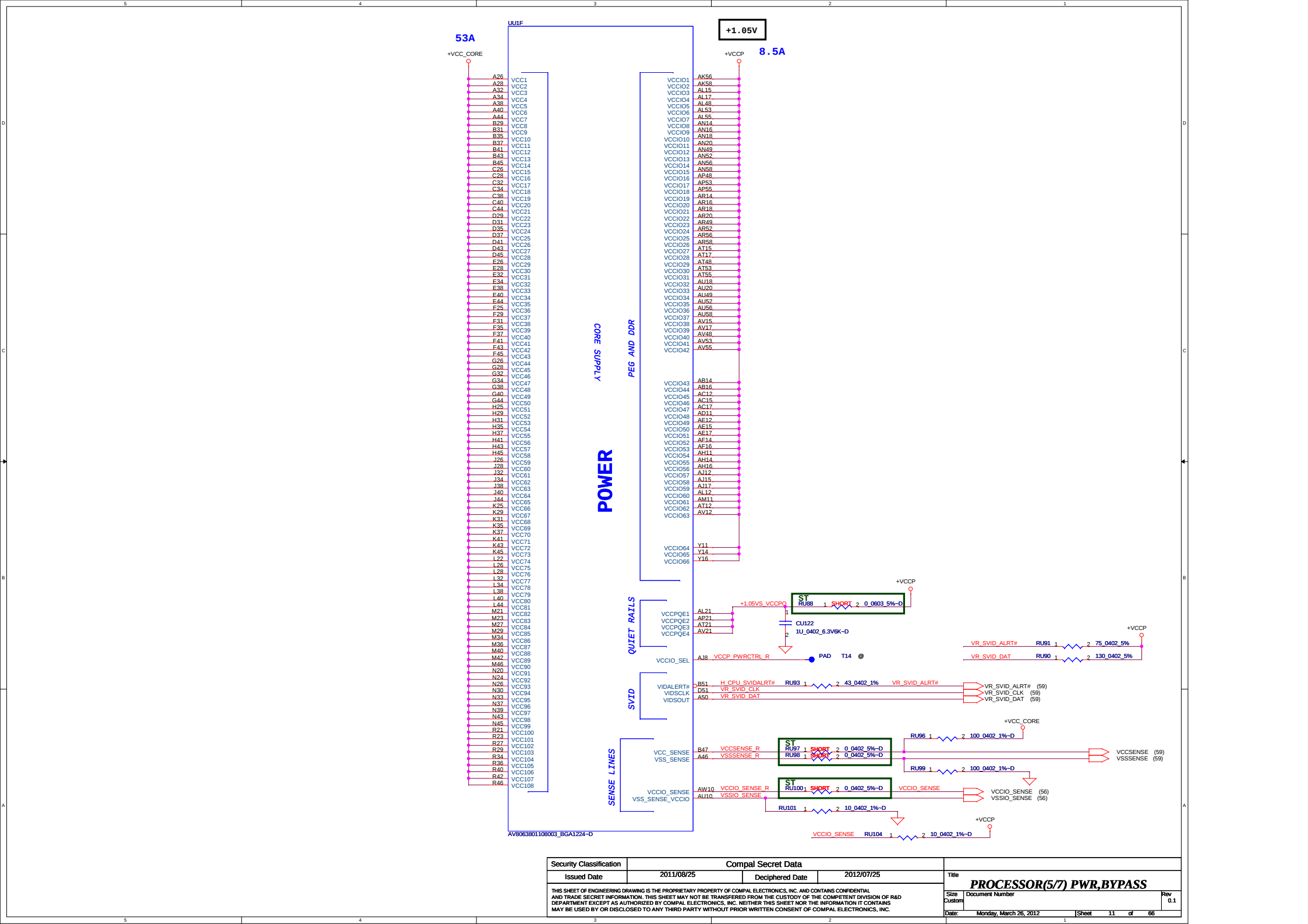
Display Port Presence Strap	
CFG4	* 1 : Disabled; No Physical Display Port attached to Embedded Display Port 0 : Enabled; An external Display Port device is connected to the Embedded Display Port

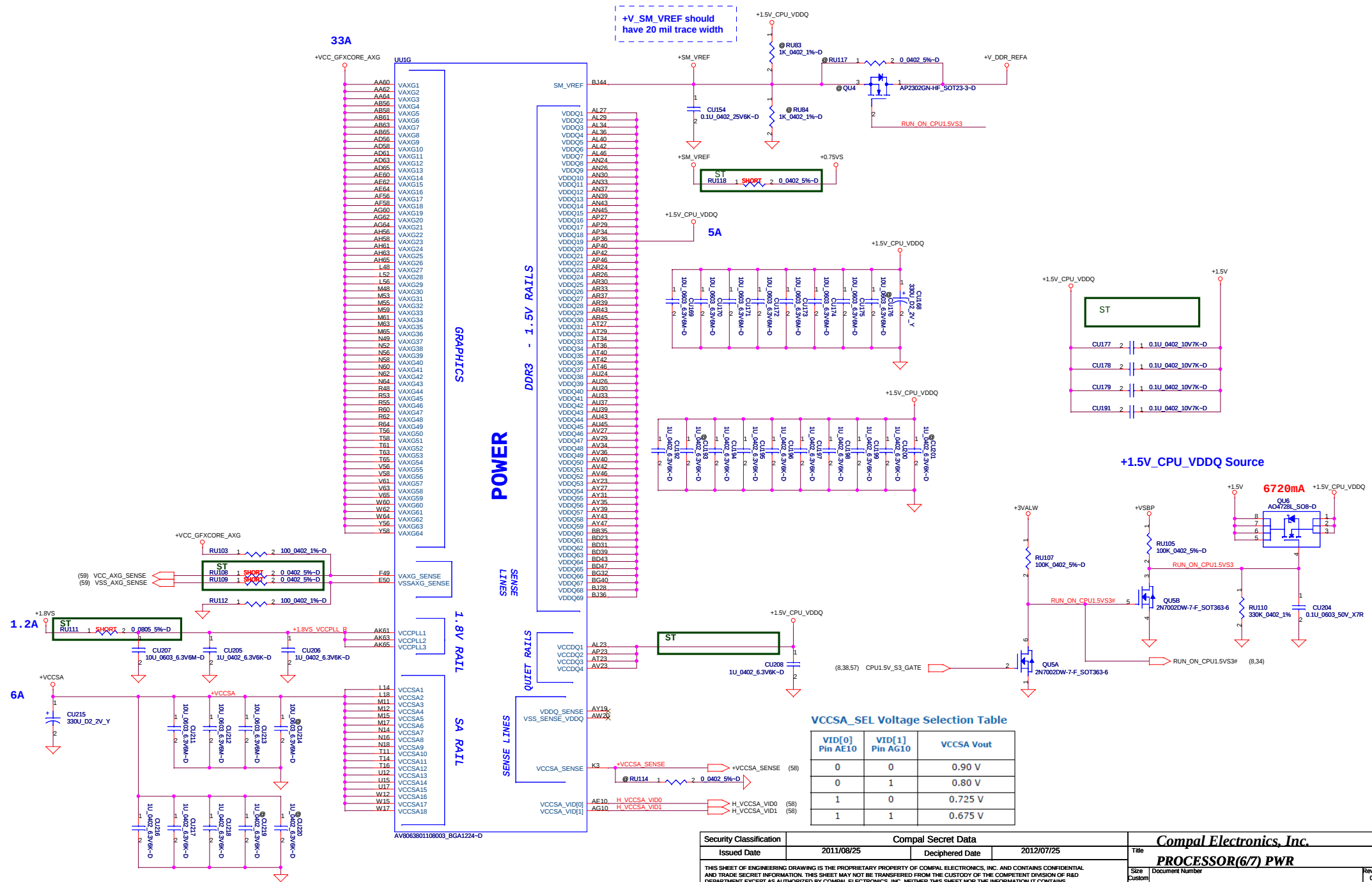


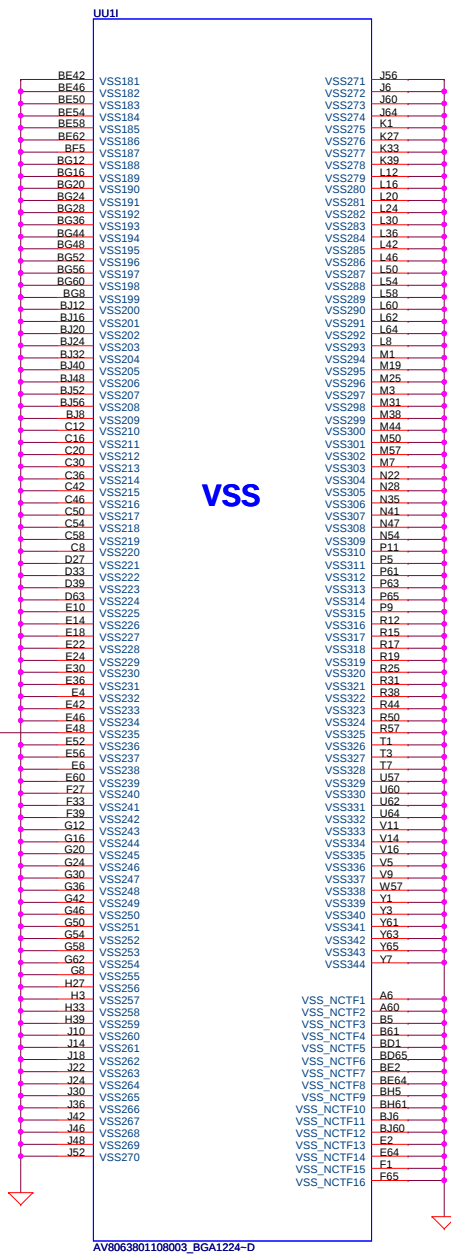
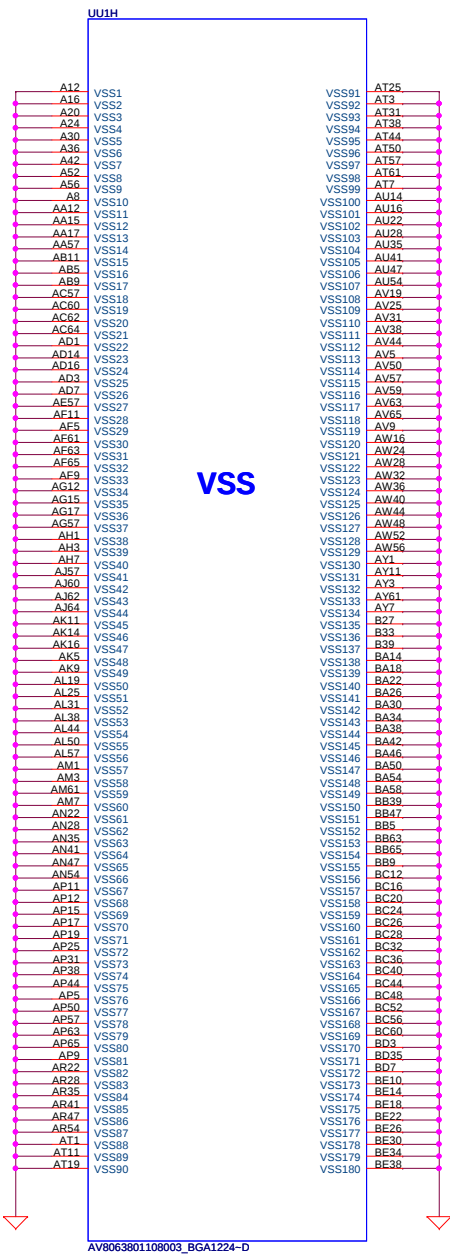
PCIe Port Bifurcation Straps	
CFG[6:5]	* 11: (Default) x16 - Device 1 functions 1 and 2 disabled 10: x8, x8 - Device 1 function 1 enabled ; function 2 disabled 01: Reserved - (Device 1 function 1 disabled ; function 2 enabled) 00: x8,x4,x4 - Device 1 functions 1 and 2 enabled



PEG DEFER TRAINING	
CFG7	1: (Default) PEG Train immediately following xxRESETB de assertion 0: PEG Wait for BIOS for training

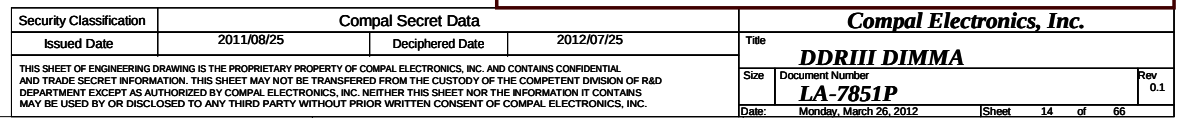
[illegible]





Debug Access By Processor Package type

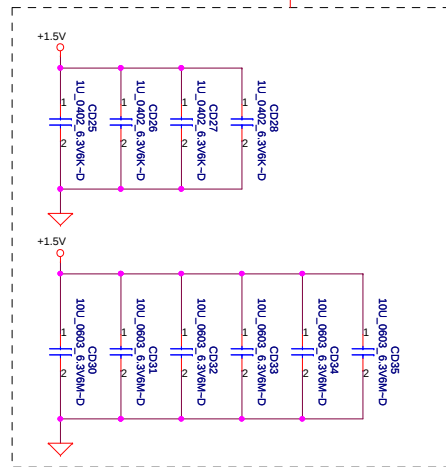
Processor Package Type	Pin Numbers
rPGA 989	AH27, AH26, AK2, AG7, L7, AE7
BGA1224	F47, E48, BG62, AY45, BD19, AY41
BGA1023	F48, G48



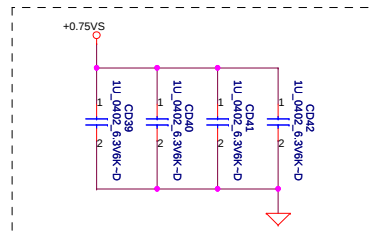
(9) DDR_B_DQS#(0..7)
(9) DDR_B_DQS(0..7)
(9) DDR_B_D(0..63)
(9) DDR_B_MA(0..15]

Layout Note:
Place near JDIMMB

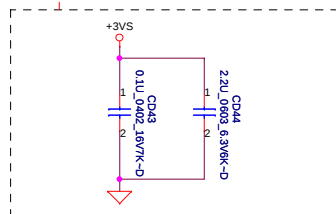
All VREF traces should
have 10 mil trace width



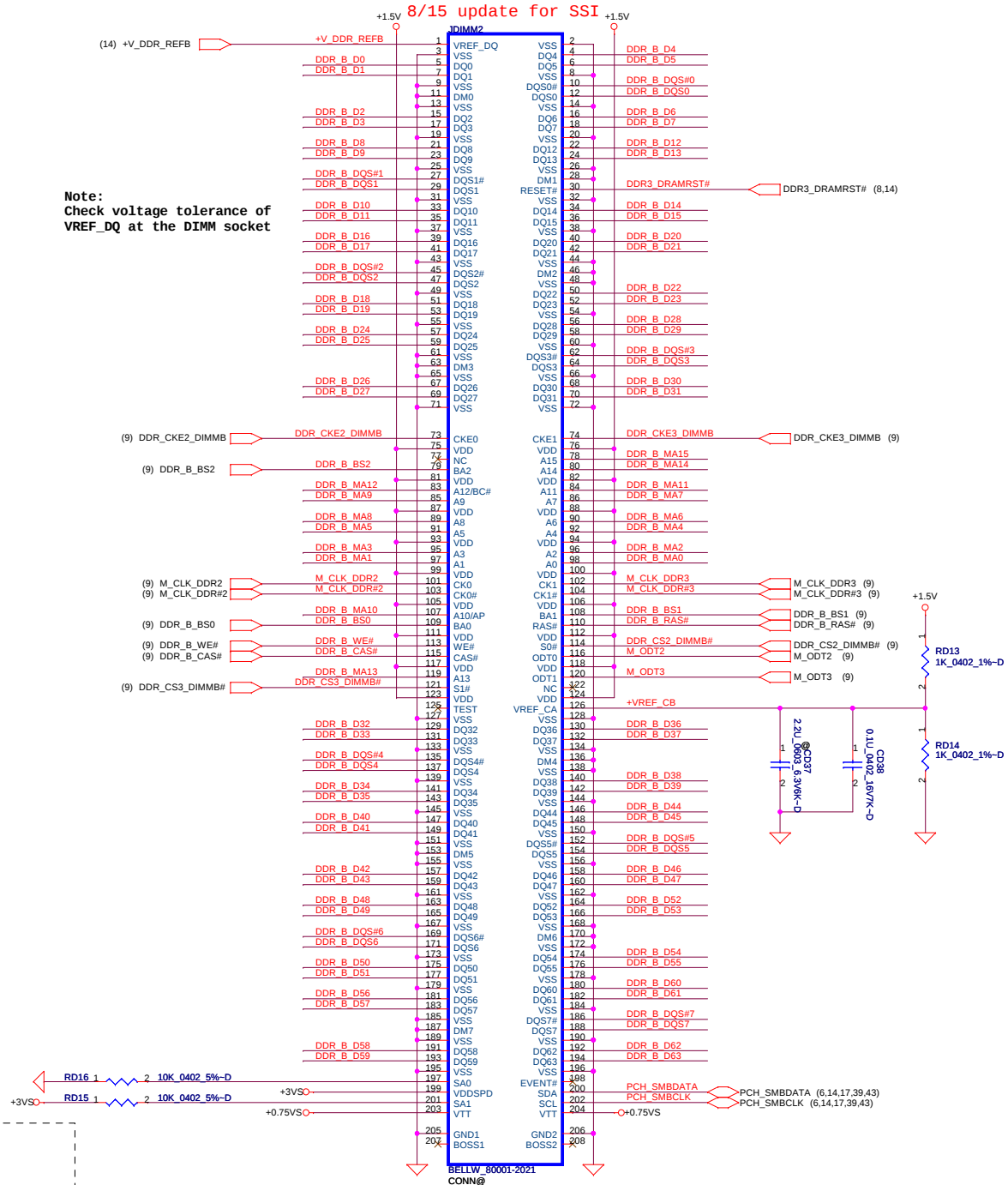
Layout Note:
Place near JDIMMB.203,204



Layout Note:
Place near JDIMMB.199

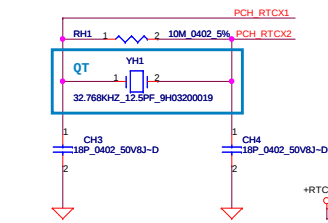


Note:
Check voltage tolerance of
VREF_DQ at the DIMM socket



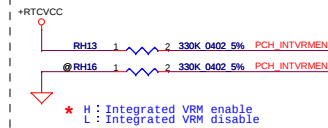
Security Classification				Compal Secret Data				Compal Electronics, Inc.			
Issued Date		2011/08/25		Deciphered Date		2012/07/25		Title			
								DDRIII DIMMB			
								Size		Document Number	
										LA-7851P	
										Rev	
										0.1	
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RTC CRYSTAL

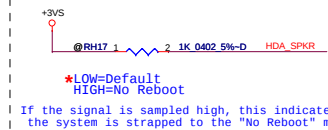


PCH Strap PIN

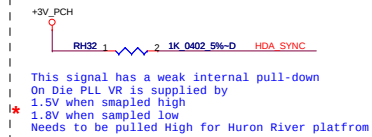
INTVRMEN Integrated 1.05V VRM Enable/Disable



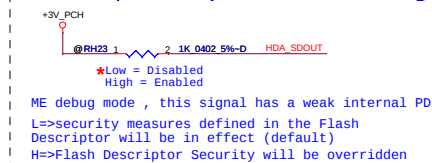
SPKR No Reboot



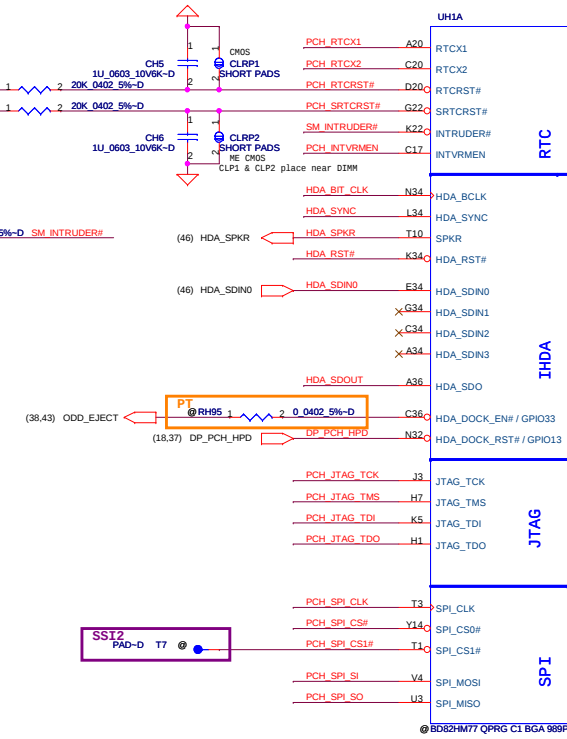
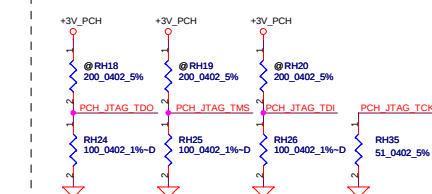
HDA_SYNC On-Die PLL Voltage Regulator Voltage Select



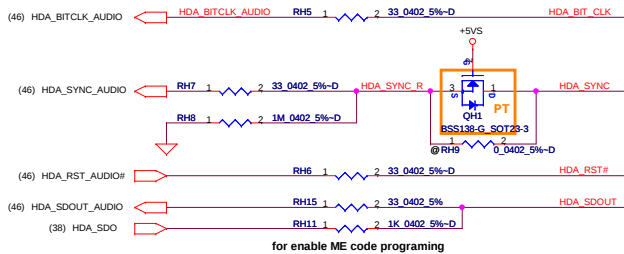
HDA_SDO Flash Descriptor Security Override/Intel ME Debug Mode



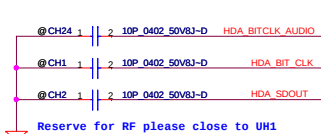
JTAG



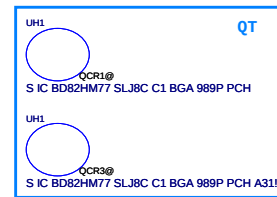
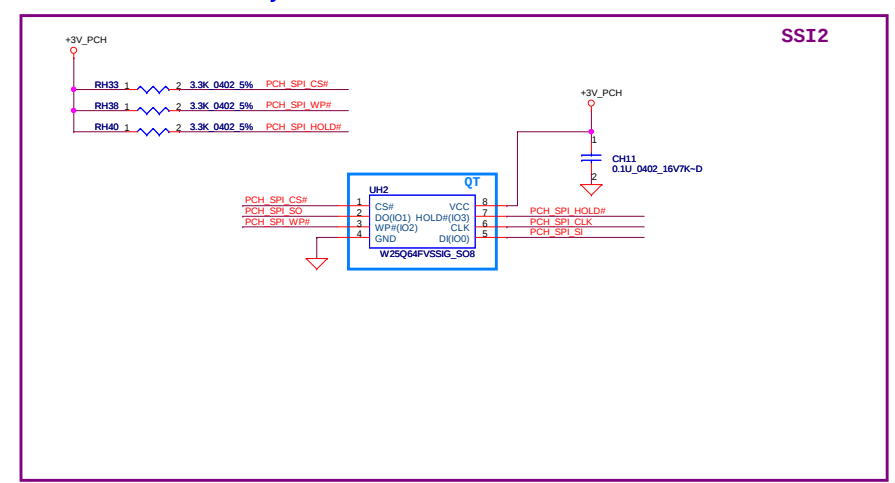
HD Audio



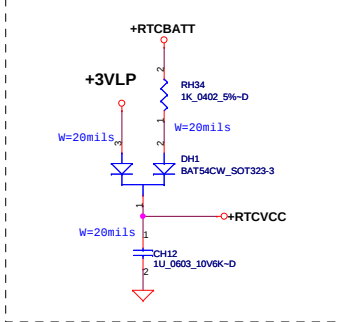
Reserve for EMI



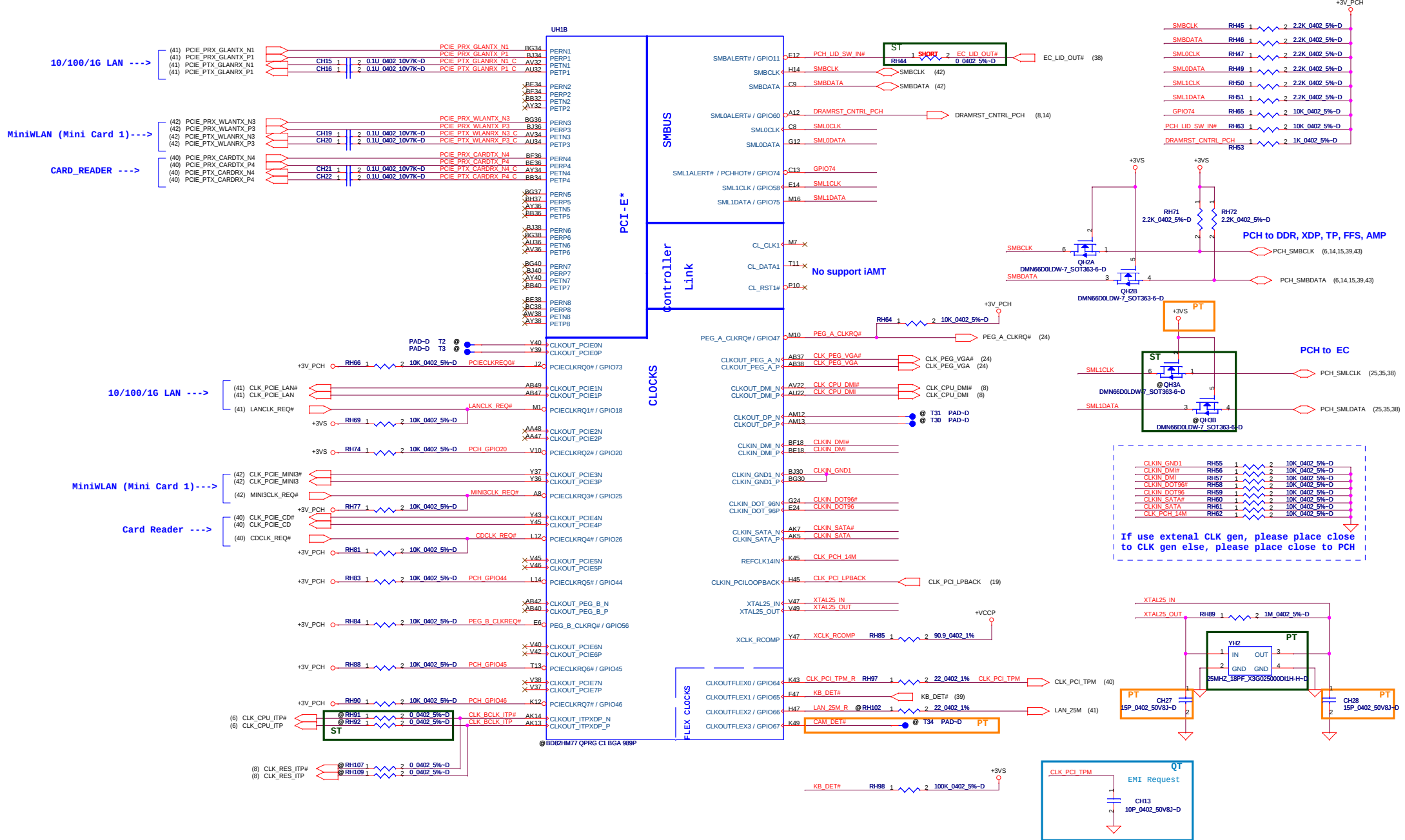
SPI ROM FOR ME (8MByte)



RTC Battery

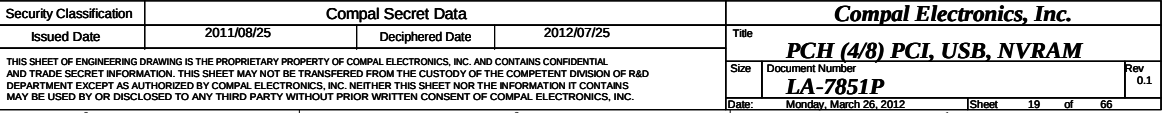


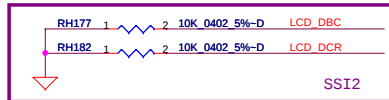
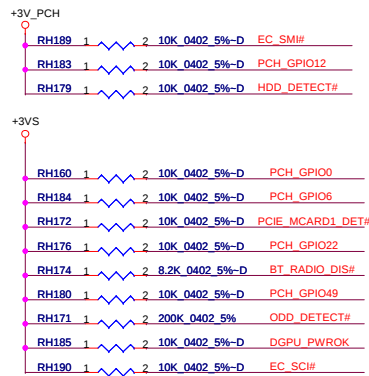
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PCH Strap PIN

GPIO15 TLS Confidentiality

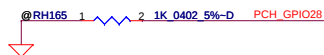
Low - Intel ME Crypto Transport Layer Security (TLS) cipher suite with no confidentiality
High - Intel ME Crypto Transport Layer Security (TLS) cipher suite with confidentiality



GPIO28 On-Die PLL Voltage Regulator

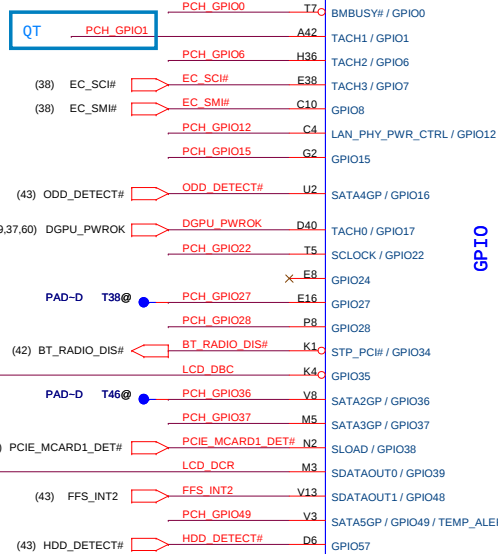
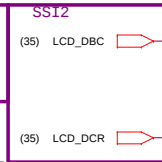
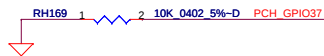
This signal has a weak internal pull up

★ H : On-Die voltage regulator enable
L : On-Die PLL Voltage Regulator disable



SATA3GP/GPIO37 Reserved

When Unused as GPIO or SATA*GP -
Use 8.2K-10K pull-down to ground

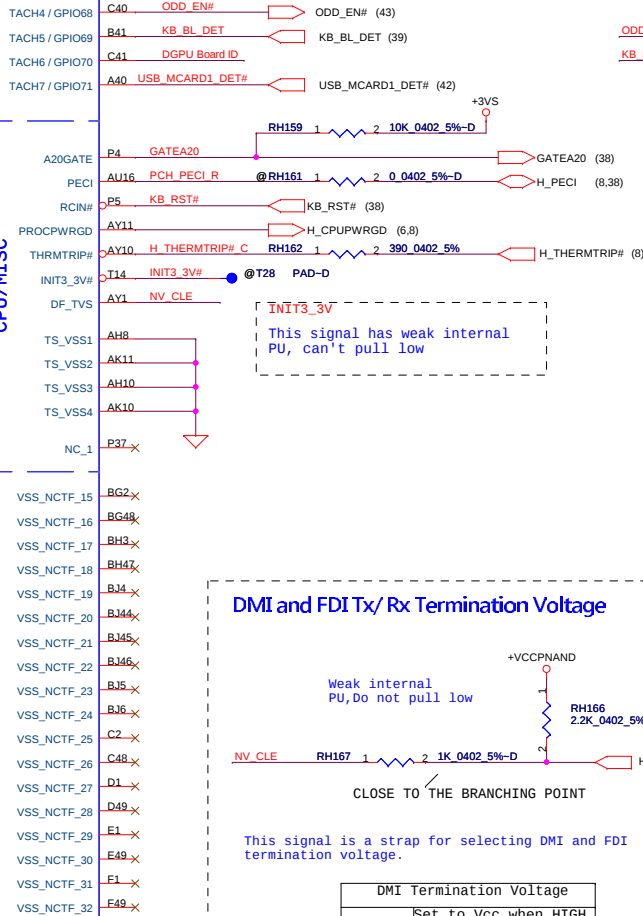


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GPIO

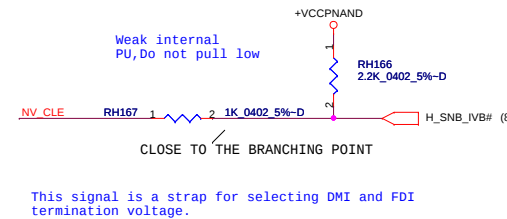
NCTF

CPU/MISC



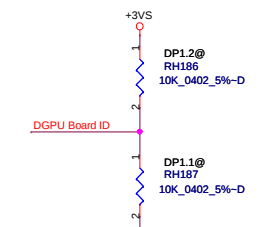
INIT3_3V
This signal has weak internal
PU, can't pull low

DMI and FDI Tx/ Rx Termination Voltage

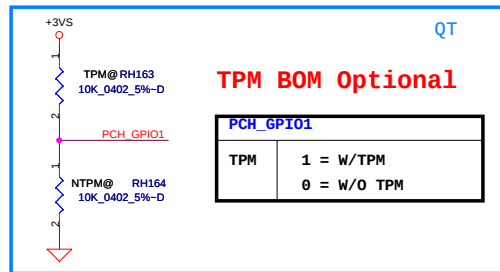


DMI Termination Voltage	
NV_CLE	Set to Vcc when HIGH Set to Vss when LOW

DGPU Board ID Optional



DGPU Board ID	
Graphics N13P	0 = GV(DP1.1@) 1 = GS(DP1.2@)



TPM BOM Optional

PCH_GPIO1	
TPM	1 = W/TPM 0 = W/O TPM

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				LA-7851P	

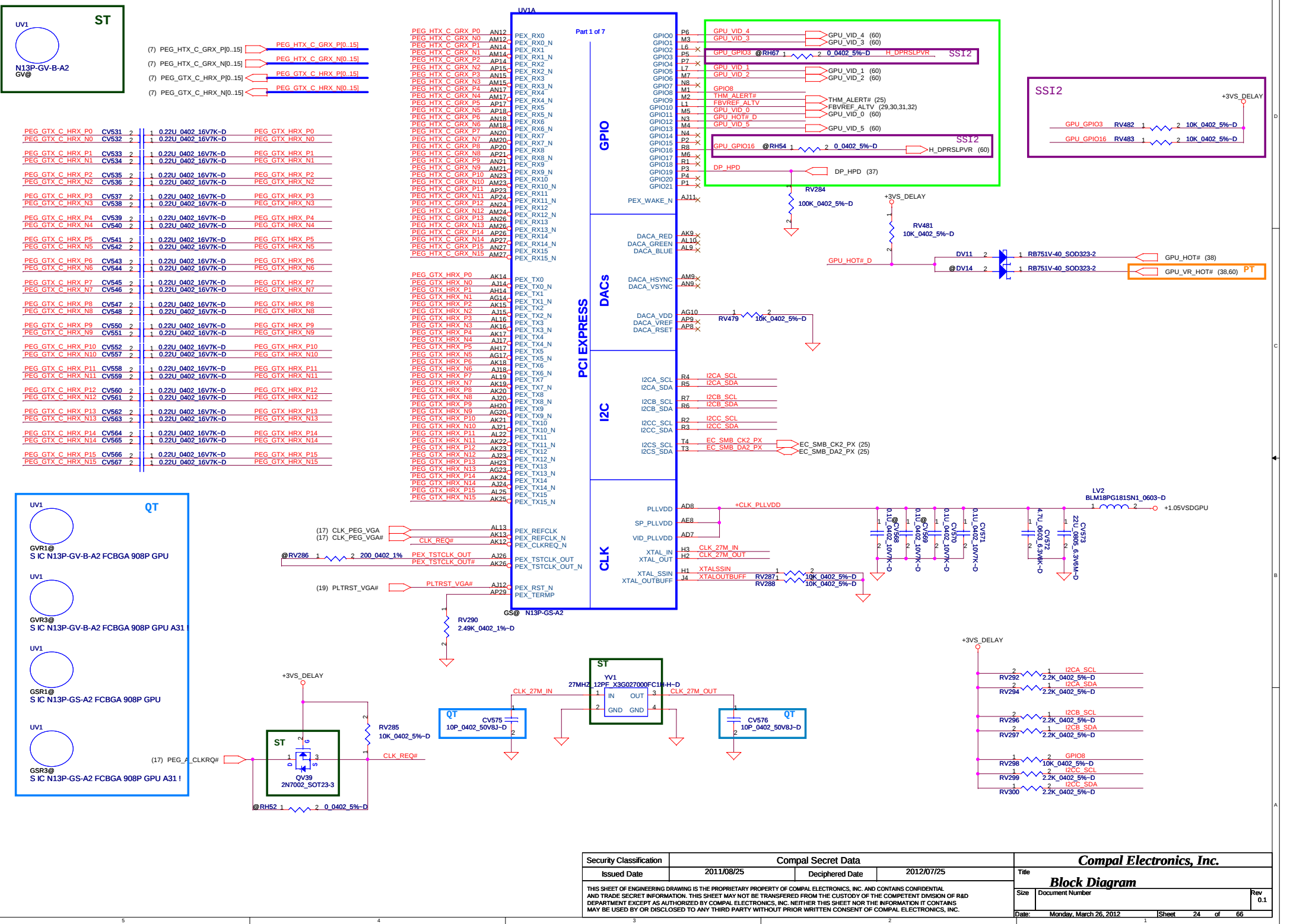
UH1H		
H5	VSS[0]	
AA17	VSS[1]	VSS[80] AK38
AA2	VSS[2]	VSS[81] AK4
AA3	VSS[3]	VSS[82] AK42
AA33	VSS[4]	VSS[83] AK45
AA34	VSS[5]	VSS[84] AK8
AB11	VSS[6]	VSS[85] AL16
AB14	VSS[7]	VSS[86] AL17
AB39	VSS[8]	VSS[87] AL19
AB4	VSS[9]	VSS[88] AL2
AB43	VSS[10]	VSS[89] AL21
AB5	VSS[11]	VSS[90] AL23
AB7	VSS[12]	VSS[91] AL26
AC19	VSS[13]	VSS[92] AL27
AC2	VSS[14]	VSS[93] AL31
AC21	VSS[15]	VSS[94] AL33
AC24	VSS[16]	VSS[95] AL34
AC33	VSS[17]	VSS[96] AL40
AC34	VSS[18]	VSS[97] AM11
AC48	VSS[19]	VSS[98] AM14
AD10	VSS[20]	VSS[99] AM36
AD11	VSS[21]	VSS[100] AM39
AD12	VSS[22]	VSS[101] AM43
AD13	VSS[23]	VSS[102] AM45
AD19	VSS[24]	VSS[103] AM46
AD24	VSS[25]	VSS[104] AM7
AD26	VSS[26]	VSS[105] AN2
AD27	VSS[27]	VSS[106] AN29
AD33	VSS[28]	VSS[107] AN3
AD34	VSS[29]	VSS[108] AP12
AD36	VSS[30]	VSS[109] AP19
AD37	VSS[31]	VSS[110] AP19
AD38	VSS[32]	VSS[111] AP28
AD39	VSS[33]	VSS[112] AP30
AD4	VSS[34]	VSS[113] AP32
AD40	VSS[35]	VSS[114] AP38
AD42	VSS[36]	VSS[115] AP4
AD43	VSS[37]	VSS[116] AP42
AD45	VSS[38]	VSS[117] AP42
AD46	VSS[39]	VSS[118] AP8
AD8	VSS[40]	VSS[119] AR2
AE2	VSS[41]	VSS[120] AR48
AE3	VSS[42]	VSS[121] AT11
AF10	VSS[43]	VSS[122] AT11
AF12	VSS[44]	VSS[123] AT18
AD14	VSS[45]	VSS[124] AT22
AD16	VSS[46]	VSS[125] AT26
AF16	VSS[47]	VSS[126] AT28
AF19	VSS[48]	VSS[127] AT30
AF24	VSS[49]	VSS[128] AT32
AF26	VSS[50]	VSS[129] AT34
AF27	VSS[51]	VSS[130] AT39
AF29	VSS[52]	VSS[131] AT42
AF31	VSS[53]	VSS[132] AT46
AF38	VSS[54]	VSS[133] AT7
AF4	VSS[55]	VSS[134] AU24
AF42	VSS[56]	VSS[135] AU30
AF46	VSS[57]	VSS[136] AV16
AF5	VSS[58]	VSS[137] AV20
AF7	VSS[59]	VSS[138] AV24
AF8	VSS[60]	VSS[139] AV30
AG19	VSS[61]	VSS[140] AV38
AG2	VSS[62]	VSS[141] AV4
AG31	VSS[63]	VSS[142] AV43
AG48	VSS[64]	VSS[143] AV8
AH11	VSS[65]	VSS[144] AW14
AH3	VSS[66]	VSS[145] AW18
AH36	VSS[67]	VSS[146] AW2
AH39	VSS[68]	VSS[147] AW22
AH40	VSS[69]	VSS[148] AW26
AH42	VSS[70]	VSS[149] AW28
AH46	VSS[71]	VSS[150] AW32
AH7	VSS[72]	VSS[151] AW34
AJ19	VSS[73]	VSS[152] AW36
AJ21	VSS[74]	VSS[153] AW40
AJ24	VSS[75]	VSS[154] AW48
AJ33	VSS[76]	VSS[155] AV11
AJ34	VSS[77]	VSS[156] E18
AK12	VSS[78]	VSS[157] E26
AK3	VSS[79]	VSS[158] E28

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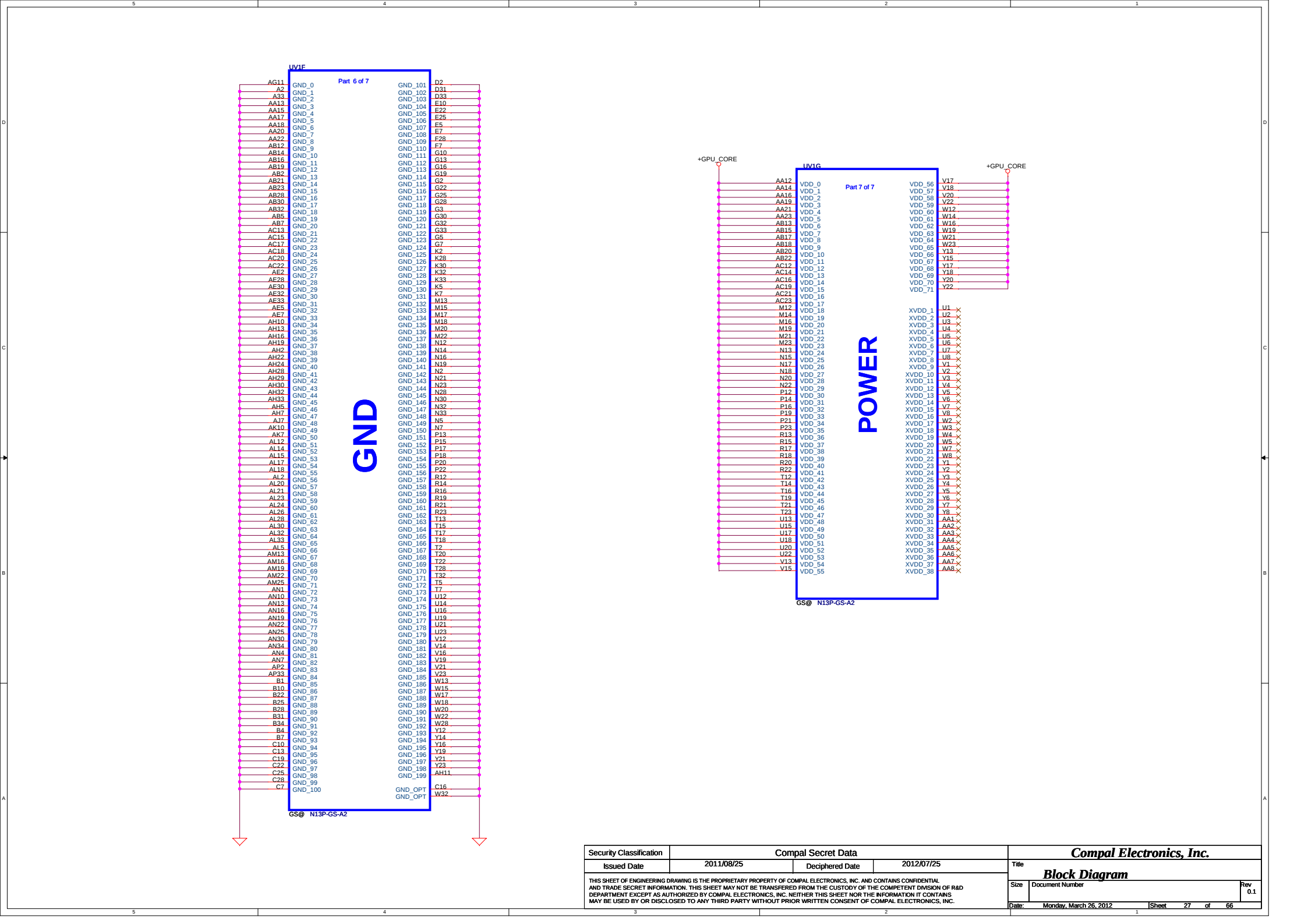
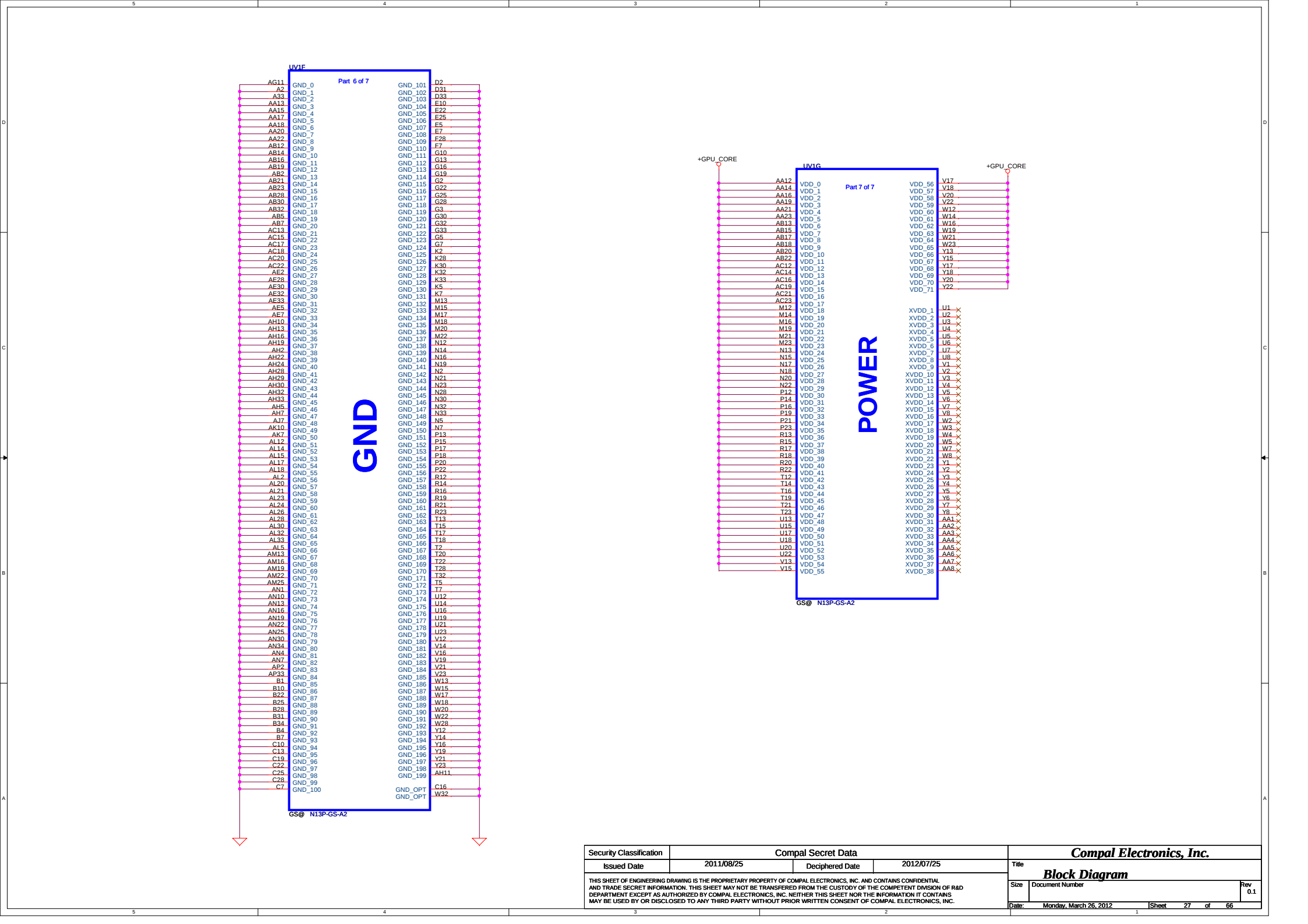
UH1I		
	VSS[159]	VSS[259] H46
AY4	VSS[160]	VSS[260] K18
AY42	VSS[161]	VSS[261] K26
AY46	VSS[162]	VSS[262] K39
AY8	VSS[163]	VSS[263] K46
B11	VSS[164]	VSS[264] K7
B15	VSS[165]	VSS[265] L18
B19	VSS[166]	VSS[266] L2
B23	VSS[167]	VSS[267] L20
B27	VSS[168]	VSS[268] L26
B31	VSS[169]	VSS[269] L36
B35	VSS[170]	VSS[270] L48
B39	VSS[171]	VSS[271] M12
B7	VSS[172]	VSS[272] M18
F45	VSS[173]	VSS[273] M22
B812	VSS[174]	VSS[274] M24
B816	VSS[175]	VSS[275] M30
BB20	VSS[176]	VSS[276] M32
BB22	VSS[177]	VSS[277] M34
BB24	VSS[178]	VSS[278] M38
BB28	VSS[179]	VSS[279] M42
BB30	VSS[180]	VSS[280] M46
BB38	VSS[181]	VSS[281] M8
BB4	VSS[182]	VSS[282] N18
BB46	VSS[183]	VSS[283] N24
BC14	VSS[184]	VSS[284] P30
BC18	VSS[185]	VSS[285] P47
BC2	VSS[186]	VSS[286] P7
BC22	VSS[187]	VSS[287] R2
BC26	VSS[188]	VSS[288] R48
BC32	VSS[189]	VSS[289] T12
BC34	VSS[190]	VSS[290] T31
BC36	VSS[191]	VSS[291] T37
BC40	VSS[192]	VSS[292] T4
BC42	VSS[193]	VSS[293] W34
BC48	VSS[194]	VSS[294] W46
BD4	VSS[195]	VSS[295] T8
BE22	VSS[196]	VSS[296] V11
BE26	VSS[197]	VSS[297] V17
BE40	VSS[198]	VSS[298] V27
BE42	VSS[199]	VSS[299] V29
BF10	VSS[200]	VSS[300] V31
BF12	VSS[201]	VSS[301] V38
BF16	VSS[202]	VSS[302] V43
BF20	VSS[203]	VSS[303] V7
BF22	VSS[204]	VSS[304] W17
BF24	VSS[205]	VSS[305] W19
BF26	VSS[206]	VSS[306] W2
BF28	VSS[207]	VSS[307] W27
BD3	VSS[208]	VSS[308] W48
BF38	VSS[209]	VSS[309] Y12
BF40	VSS[210]	VSS[310] Y38
BF48	VSS[211]	VSS[311] Y4
BG17	VSS[212]	VSS[312] Y46
BG21	VSS[213]	VSS[313] Y8
BG33	VSS[214]	VSS[314] BG29
BG44	VSS[215]	VSS[315] N24
BH11	VSS[216]	VSS[316] A13
BH15	VSS[217]	VSS[317] AD47
BH17	VSS[218]	VSS[318] B43
BH19	VSS[219]	VSS[319] BE10
H10	VSS[220]	VSS[320] BG41
BH27	VSS[221]	VSS[321] G14
BH31	VSS[222]	VSS[322] H16
BH33	VSS[223]	VSS[323] T36
BH35	VSS[224]	VSS[324] BG22
BH39	VSS[225]	VSS[325] BG24
BH43	VSS[226]	VSS[326] C22
BH7	VSS[227]	VSS[327] AP13
D3	VSS[228]	VSS[328] M14
D12	VSS[229]	VSS[329] AP3
D18	VSS[230]	VSS[330] AP1
D16	VSS[231]	VSS[331] BE16
D22	VSS[232]	VSS[332] BC16
D24	VSS[233]	VSS[333] BG28
D26	VSS[234]	VSS[334] J28
D30	VSS[235]	VSS[335]
D32	VSS[236]	VSS[336]
D34	VSS[237]	VSS[337]
D38	VSS[238]	VSS[338]
D42	VSS[239]	VSS[339]
D46	VSS[240]	VSS[340]
D8	VSS[241]	VSS[341]
E18	VSS[242]	VSS[342]
E26	VSS[243]	VSS[343]
G18	VSS[244]	VSS[344]
G20	VSS[245]	VSS[345]
G26	VSS[246]	VSS[346]
G28	VSS[247]	VSS[347]
G36	VSS[248]	VSS[348]
H12	VSS[249]	VSS[349]
H18	VSS[250]	VSS[350]
H22	VSS[251]	VSS[351]
H24	VSS[252]	VSS[352]
H26	VSS[253]	
H30	VSS[254]	
H32	VSS[255]	
H34	VSS[256]	
F3	VSS[257]	
	VSS[258]	

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				Size	Document Number
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The diagram illustrates the power and ground connections for a GPU. It is divided into two main sections: GND (Ground) and POWER. The GND section (left) shows a large blue box labeled 'GND' with a 'Part 6 of 7' label. It contains a list of ground pins (GND_0 to GND_100) and their corresponding pin numbers (D2 to D32). The POWER section (right) shows a large blue box labeled 'POWER' with a 'Part 7 of 7' label. It contains a list of power pins (VDD_0 to VDD_55) and their corresponding pin numbers (AA12 to AA23). The diagram also includes a 'GPU_CORE' label and a 'GPU_CORE' label. The diagram is labeled 'GS@ N13P-GS-A2' at the bottom left and 'GS@ N13P-GS-A2' at the bottom right. The diagram is labeled 'POWER' in the center of the right section. The diagram is labeled 'GND' in the center of the left section. The diagram is labeled 'Part 6 of 7' and 'Part 7 of 7'.

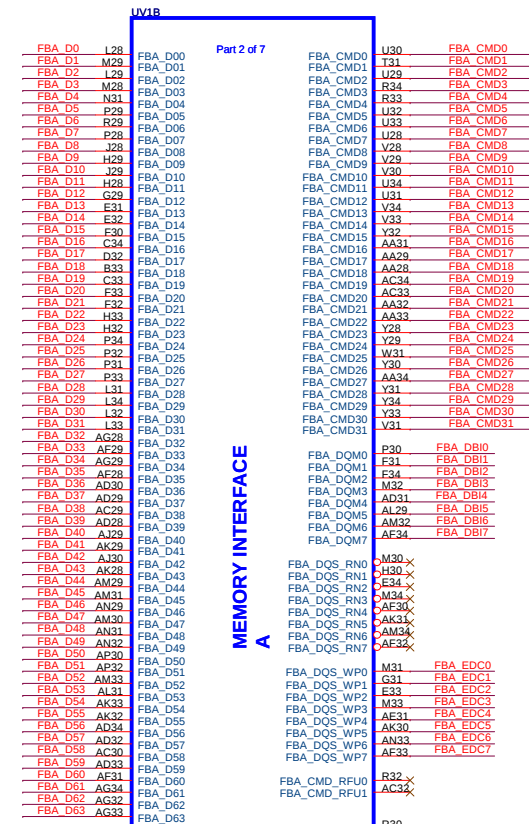
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				Size	Document Number
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GDDR5 CMD Mapping Table

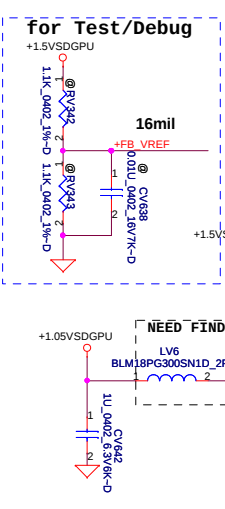
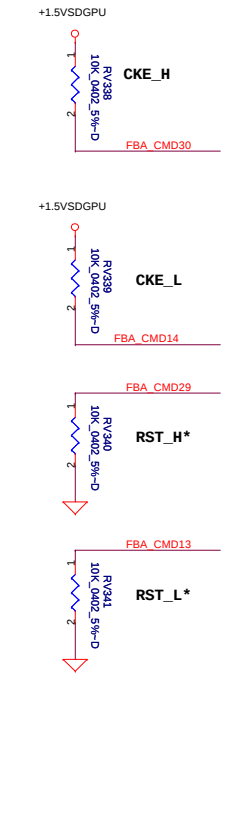
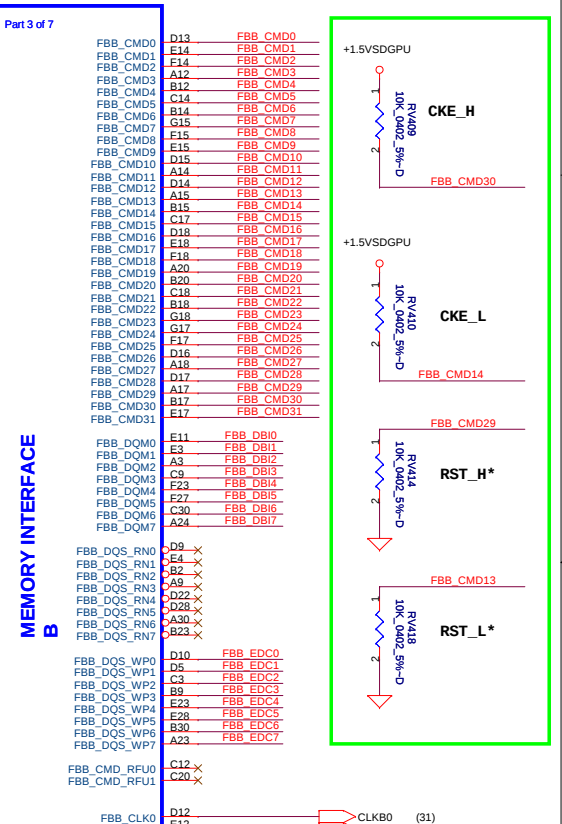
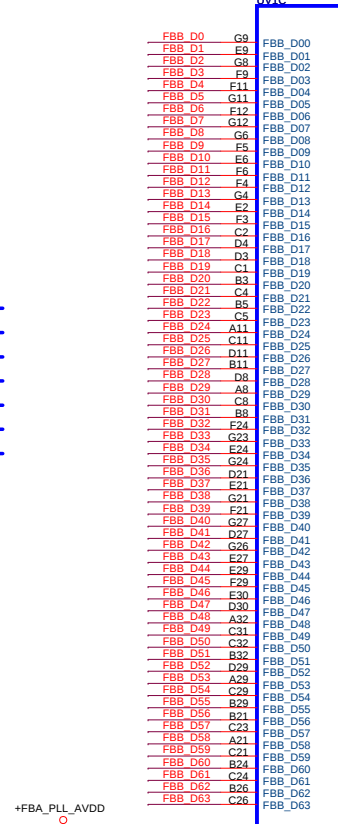
CHANNEL-B NOT TO USE, NEED TO BE DISABLED

(29) FBA_D[0..31]	FBA_D[0..31]
(30) FBA_D[32..63]	FBA_D[32..63]
(29,30) FBA_CMD[0..31]	FBA_CMD[0..31]
(30) FBA_DB[4..7]	FBA_DB[4..7]
(29) FBA_DB[0..3]	FBA_DB[0..3]
(30) FBA_EDC[4..7]	FBA_EDC[4..7]
(29) FBA_EDC[0..3]	FBA_EDC[0..3]

<0..31>	<32..63>	Memory
CMD12	CMD28	RAS#
CMD15	CMD31	CAS#
CMD16	CMD32	WE#
CMD18	CMD16	CS#
CMD8	CMD24	ABT#
CMD10	CMD26	A0 A10
CMD11	CMD27	A1 A9
CMD2	CMD18	A2 BA0
CMD1	CMD17	A3 BA3
CMD3	CMD19	A4 BA1
CMD5	CMD20	A5 BA1
CMD7	CMD23	A6 A11
CMD6	CMD22	A7 A8
CMD9	CMD25	A12 FRU
CMD14	CMD30	CKE#
CMD13	CMD29	RESET#

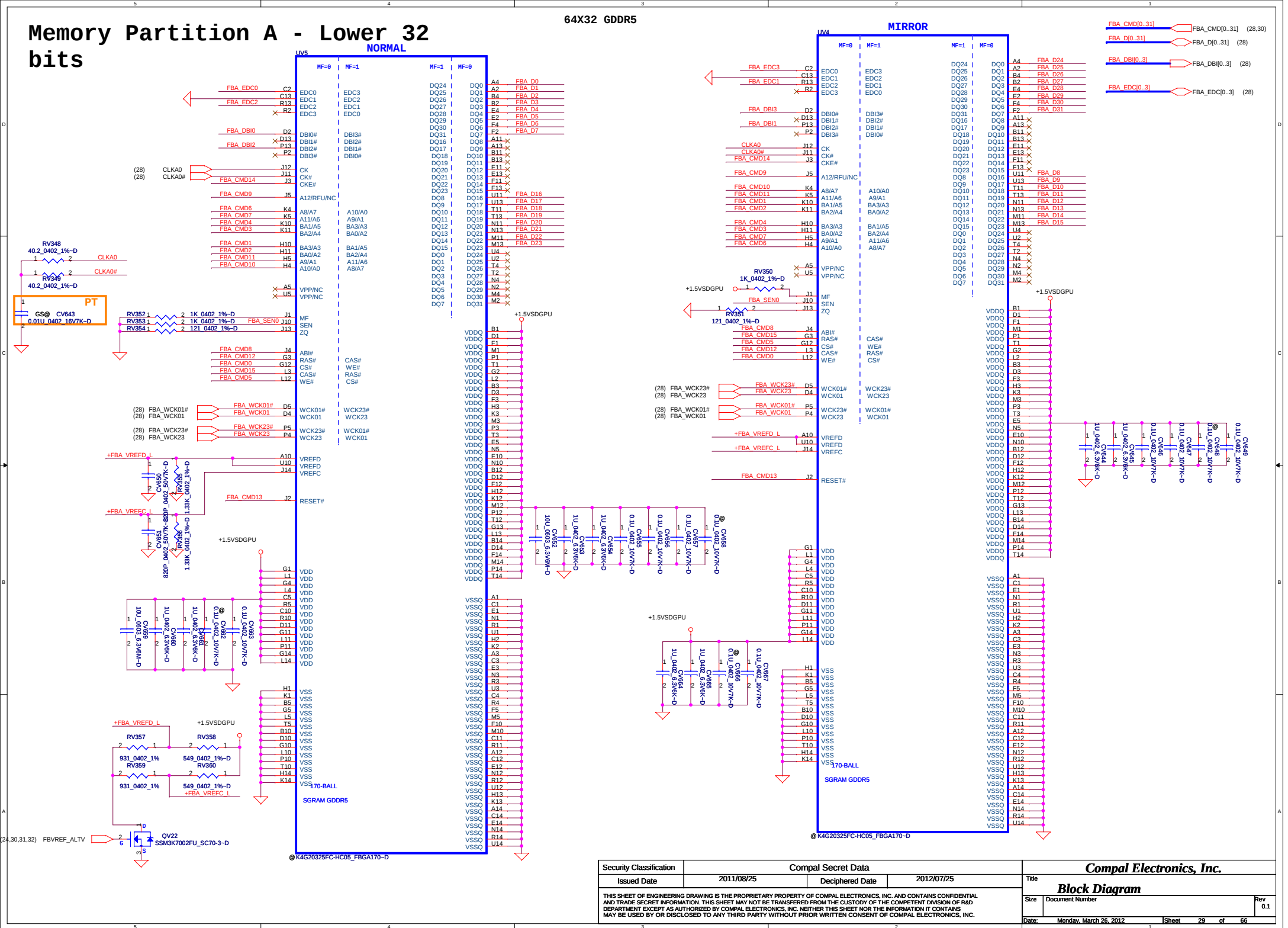


(31) FBB_D[0..31]	FBB_D[0..31]
(32) FBB_D[32..63]	FBB_D[32..63]
(31,32) FBB_CMD[0..31]	FBB_CMD[0..31]
(32) FBB_DB[4..7]	FBB_DB[4..7]
(31) FBB_DB[0..3]	FBB_DB[0..3]
(32) FBB_EDC[4..7]	FBB_EDC[4..7]
(31) FBB_EDC[0..3]	FBB_EDC[0..3]



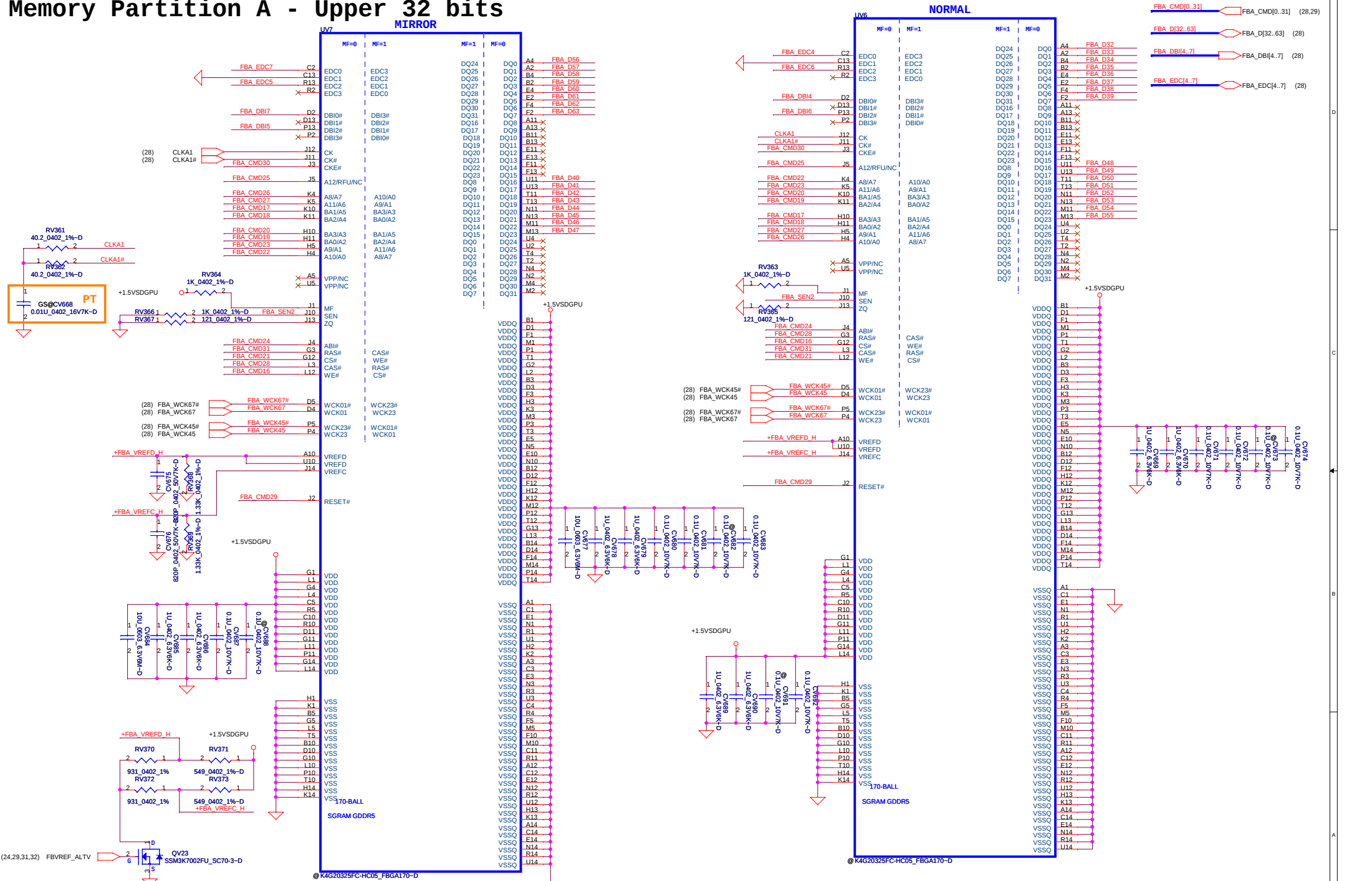
Memory Partition A - Lower 32 bits

64X32 GDDR5



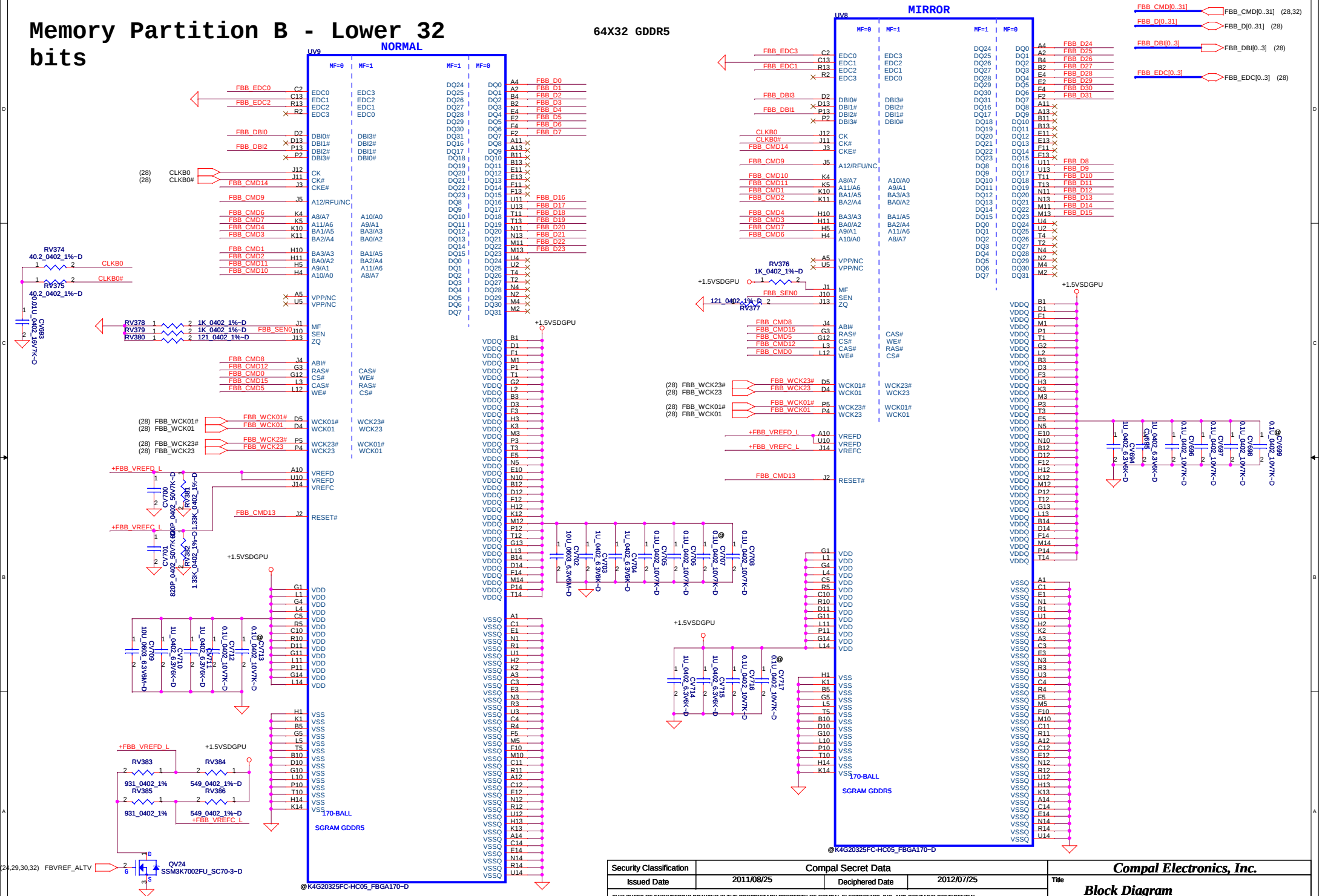
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Title			
Block Diagram			
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Memory Partition A - Upper 32 bits



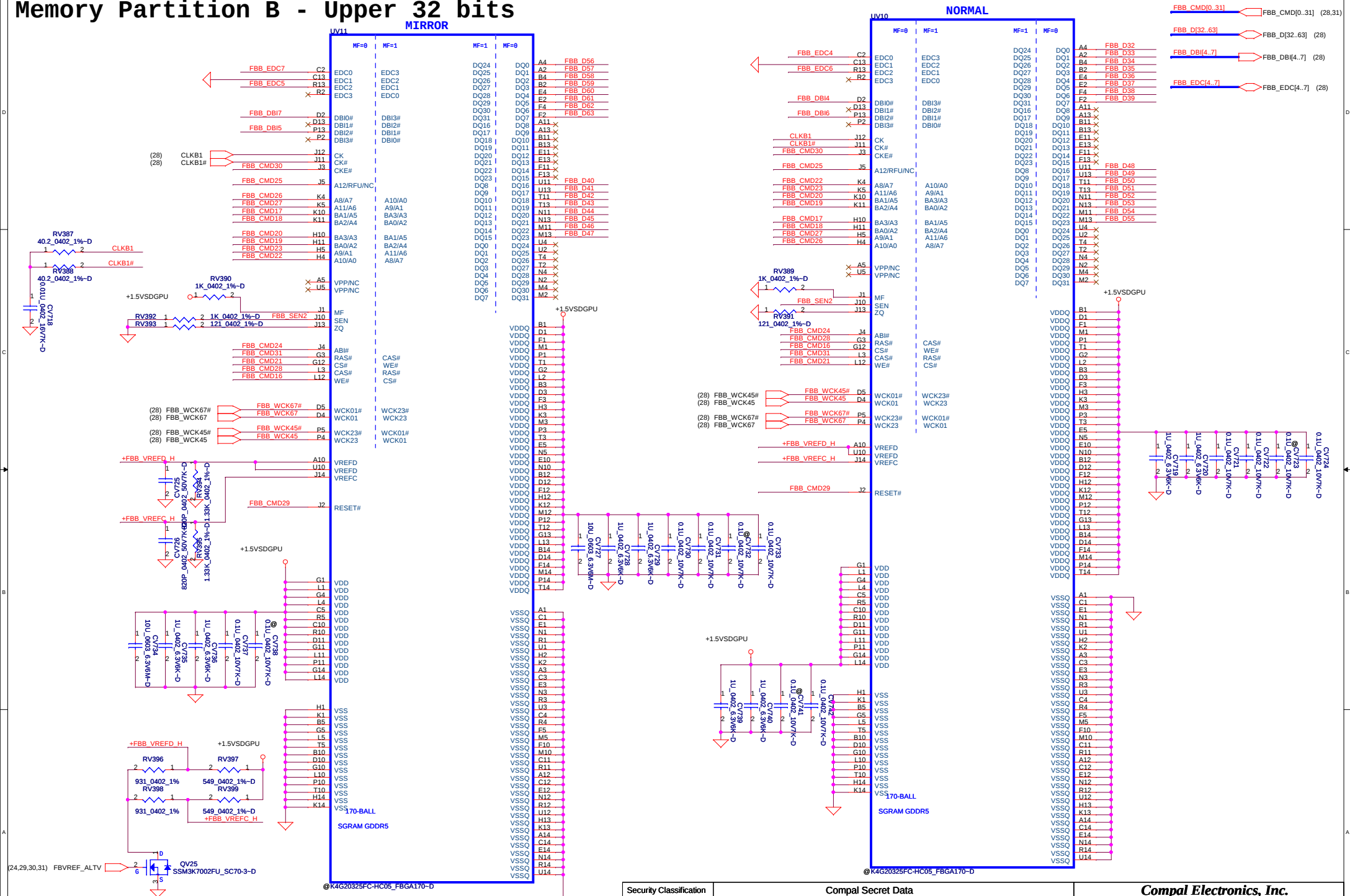
Memory Partition B - Lower 32 bits

64X32 GDDR5



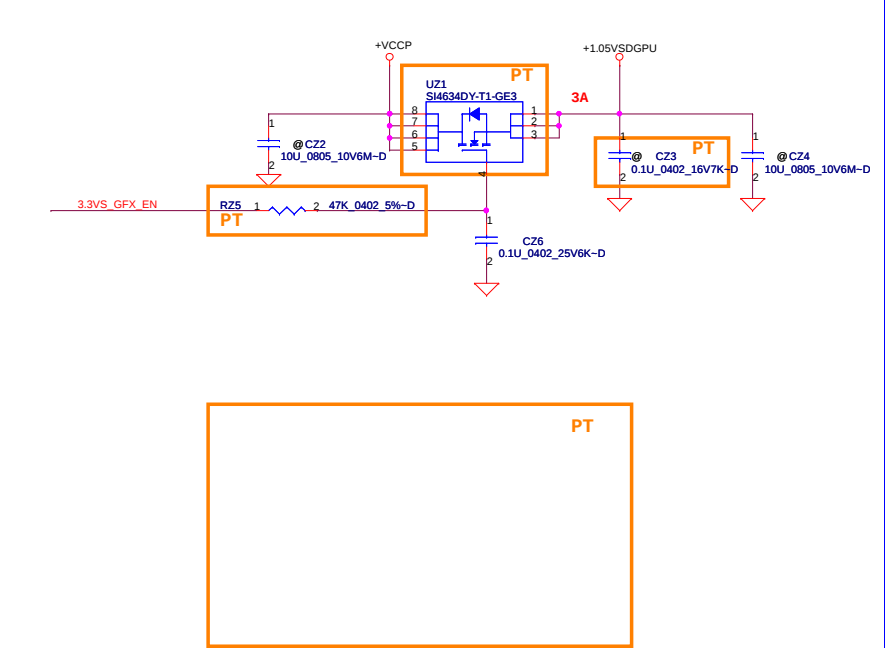
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Memory Partition B - Upper 32 bits

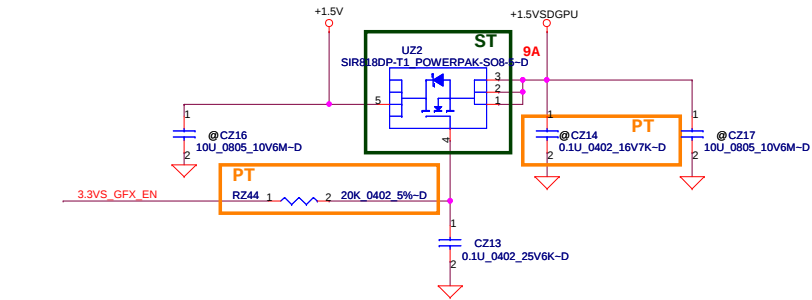


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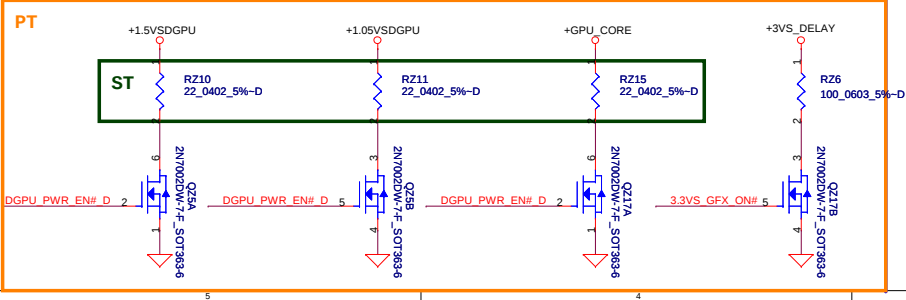
+1.05VS to +1.05VSDGPU



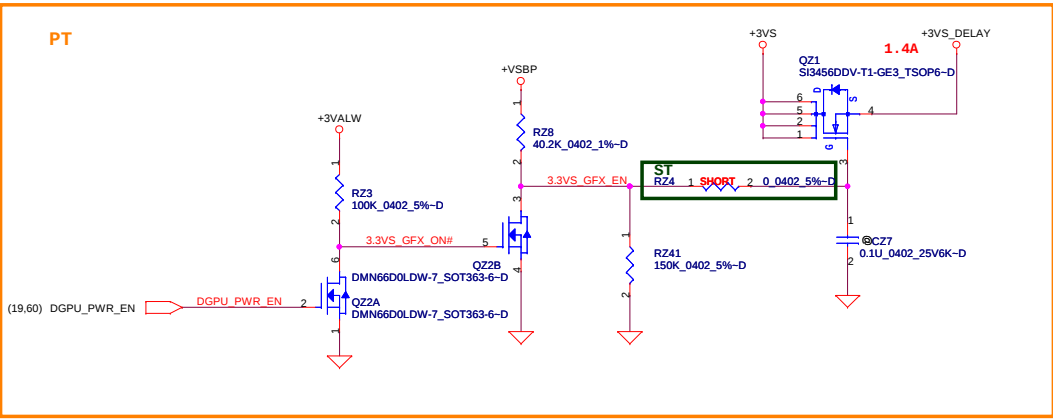
+1.5V to +1.5VSDGPU



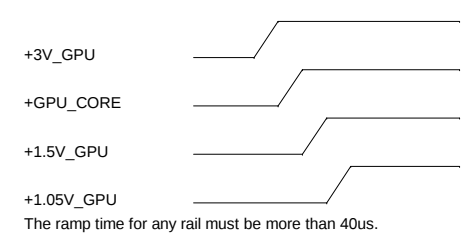
Discharge



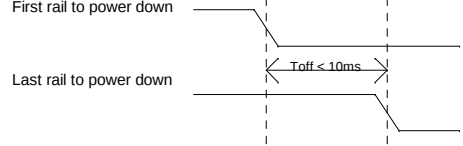
+3VS to +3VS_DELAY



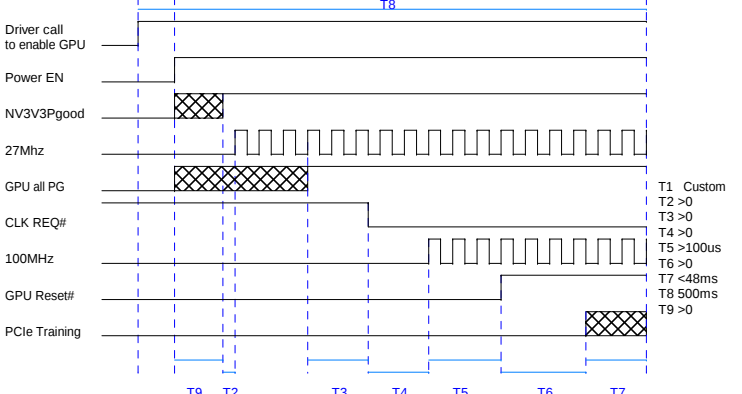
GPU Power Up Power Rail Sequence



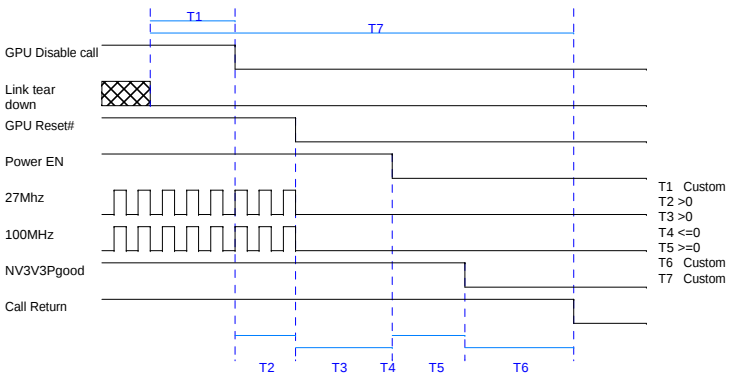
GPU Power Down Sequence



GPU Power Up Sub-system Sequence

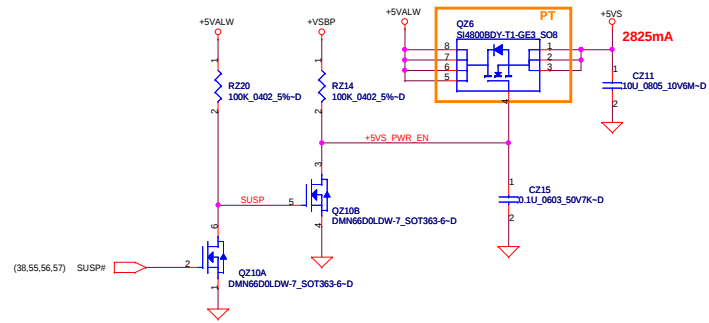


GPU Power Down Sub-system Sequence

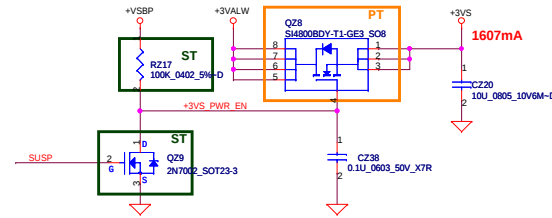


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				Size	Document Number	Rev
						0.1
				Date:	Monday, March 26, 2012	Sheet 33 of 66

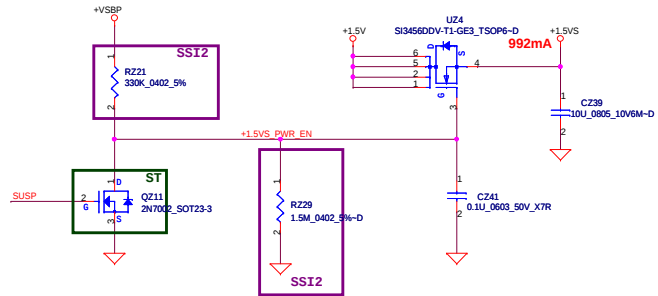
+5VALW to +5VS



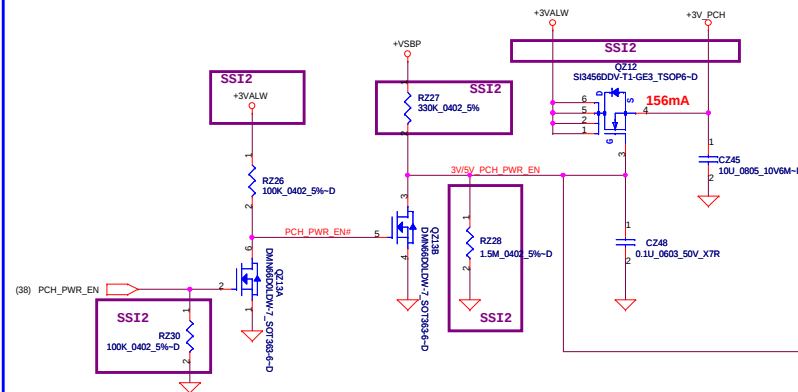
+3VALW to +3VS



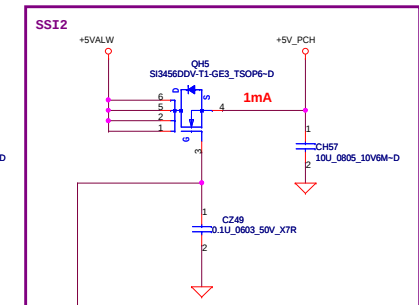
+1.5V To +1.5VS



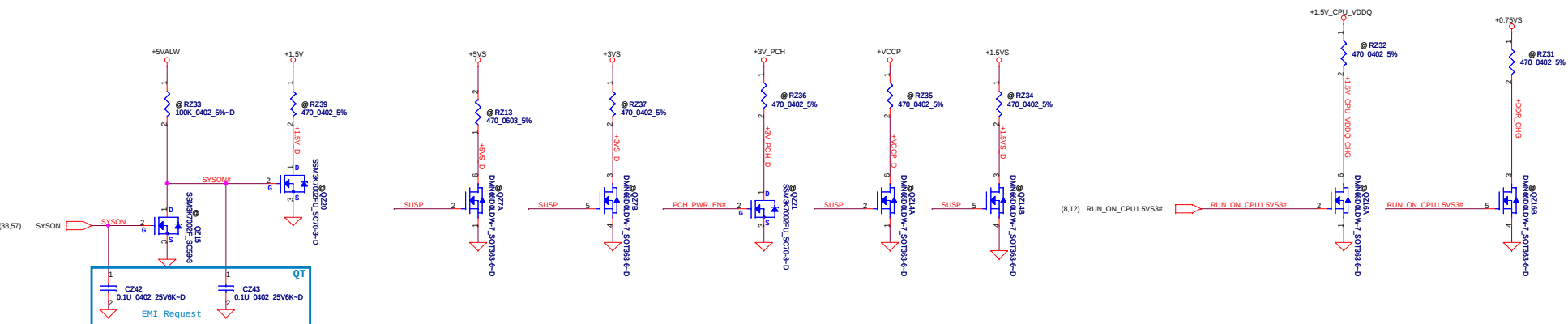
+3VALW to +3V_PCH



+5VALW to +5V_PCH



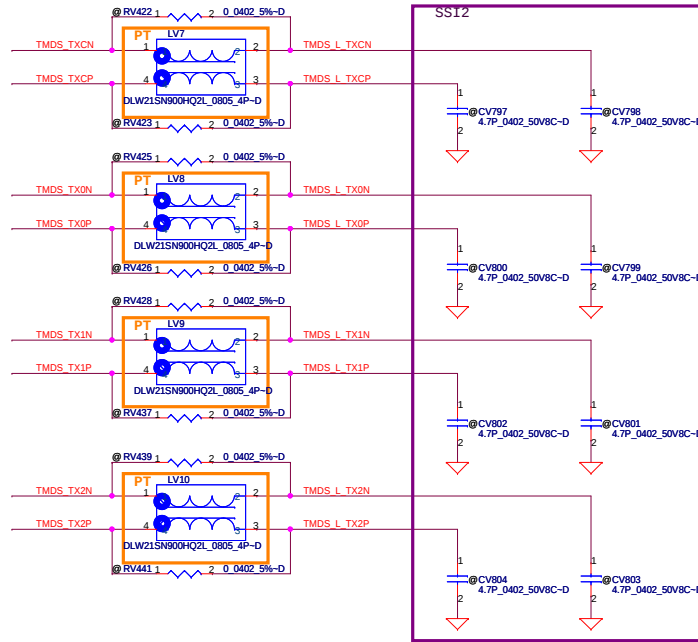
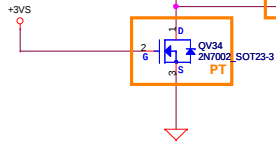
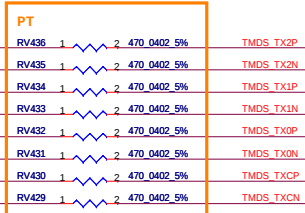
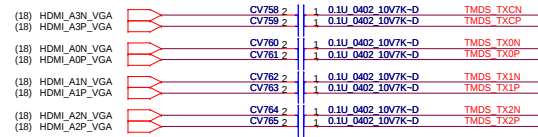
Discharge



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				Size
				LA-7851P
				Rev
				0.1
				Date
				Monday, March 26, 2012
				Sheet
				34 of 66

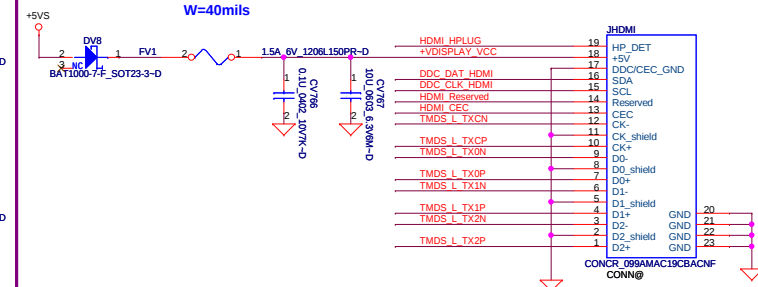
HDMI Cost Reduce type

Place close to JHDMI1

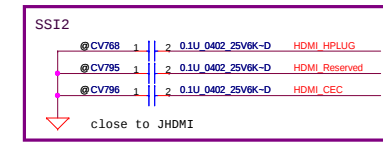


For EMI

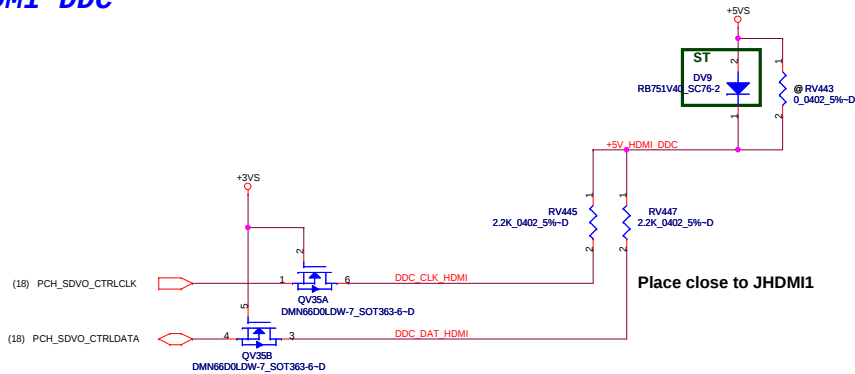
8/26 JHDMI change to XPS14 CIS Symbol
8/16 update for SSI



For EMI Reserve

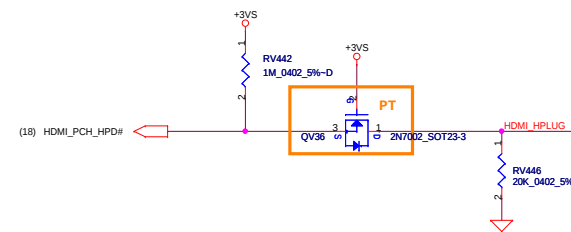


HDMI DDC

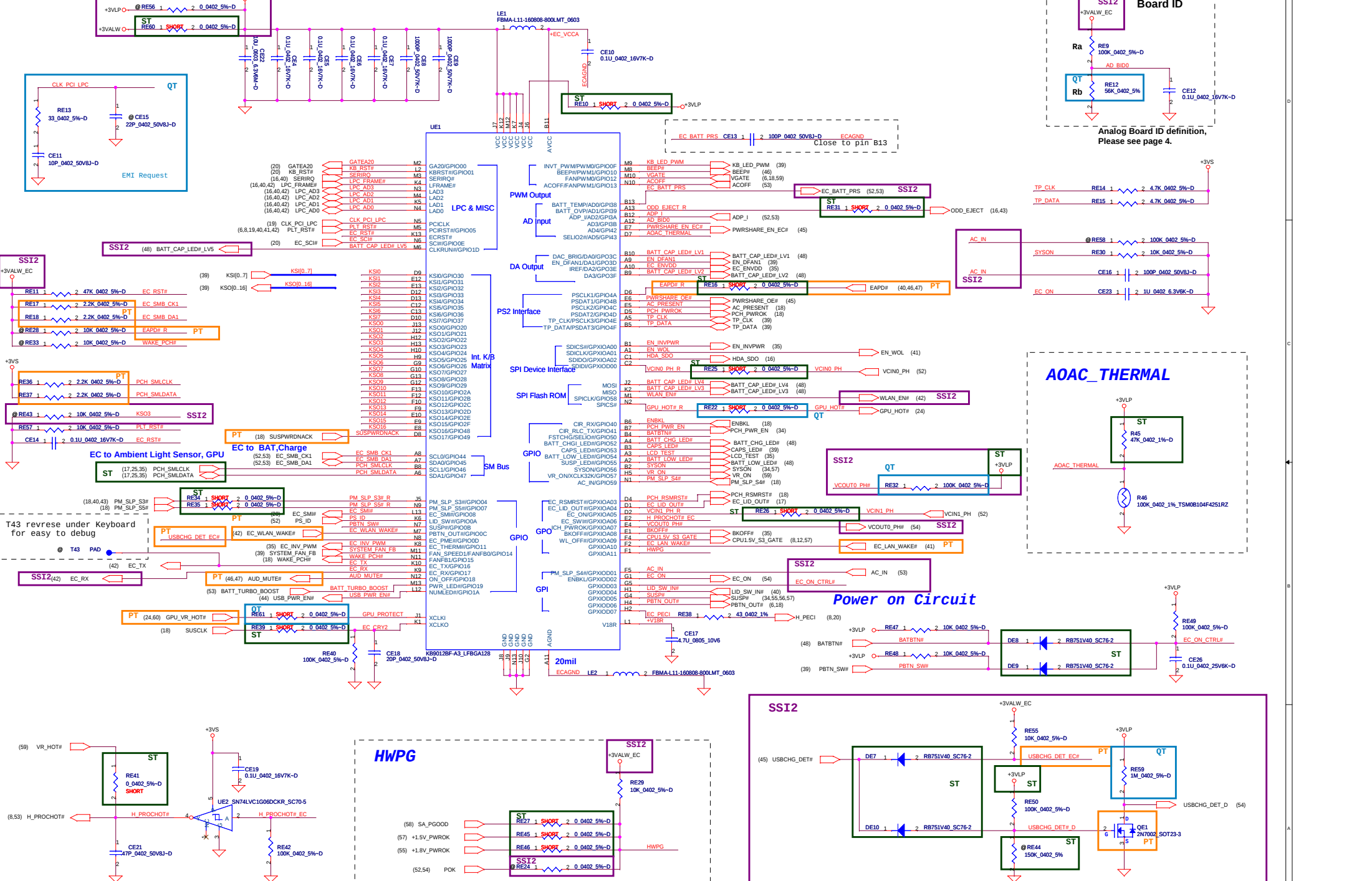


Place close to JHDMI1

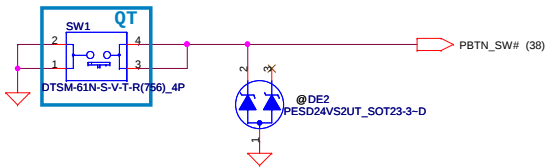
HDMI HPD



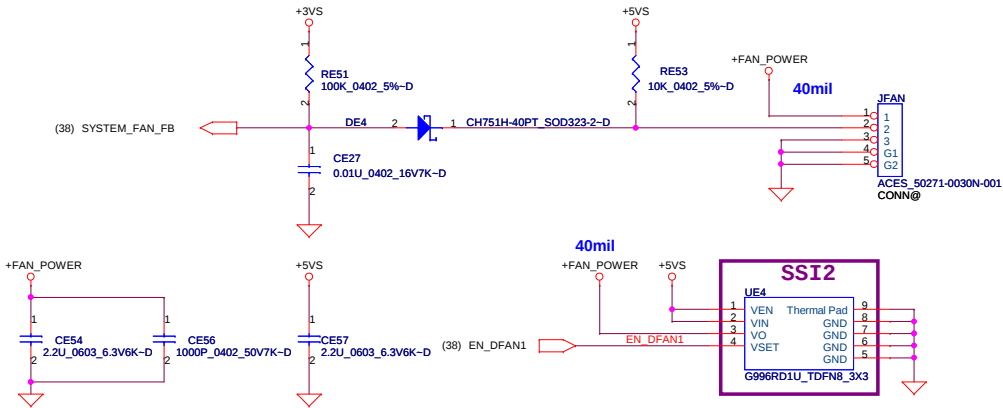
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Issued Date	2011/08/25	Deciphered Date	2012/07/25	Title	
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				Rev	0.1



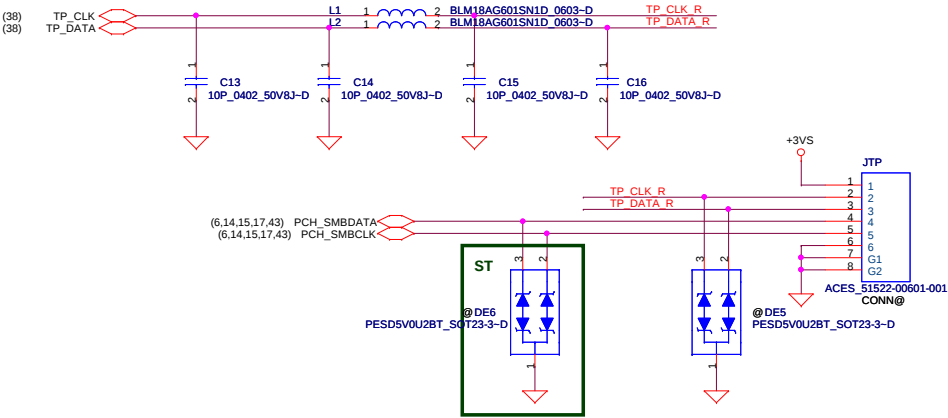
Power on Button



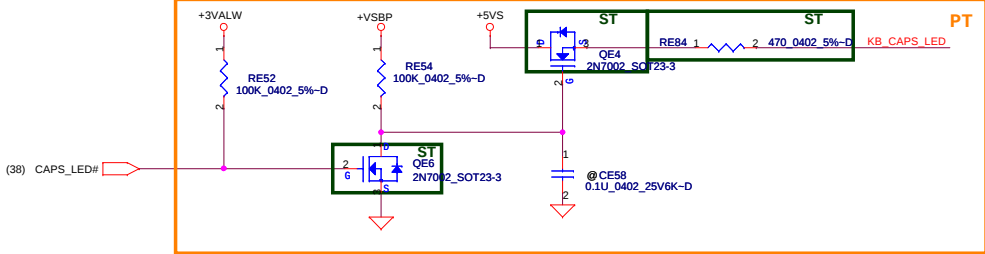
FAN Control



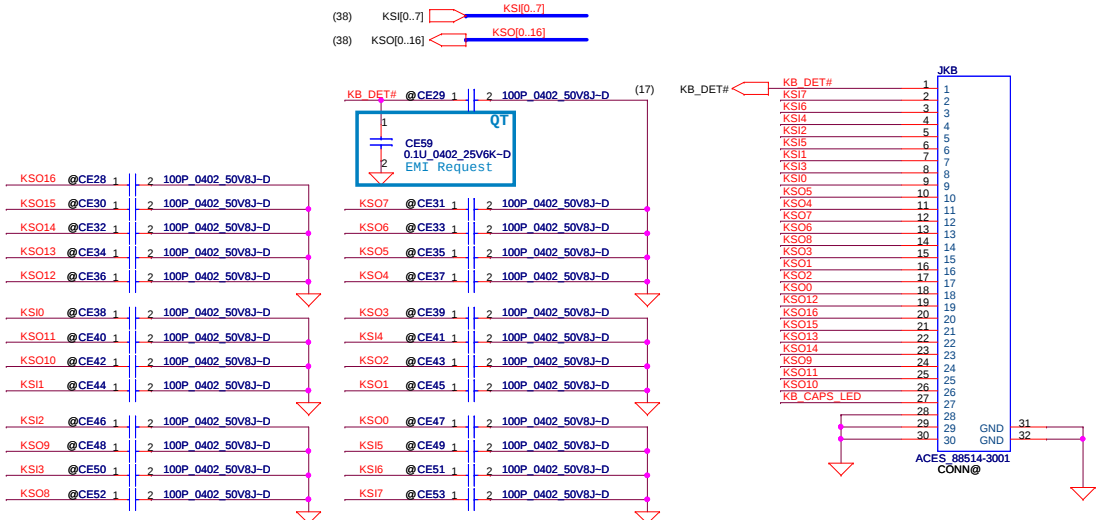
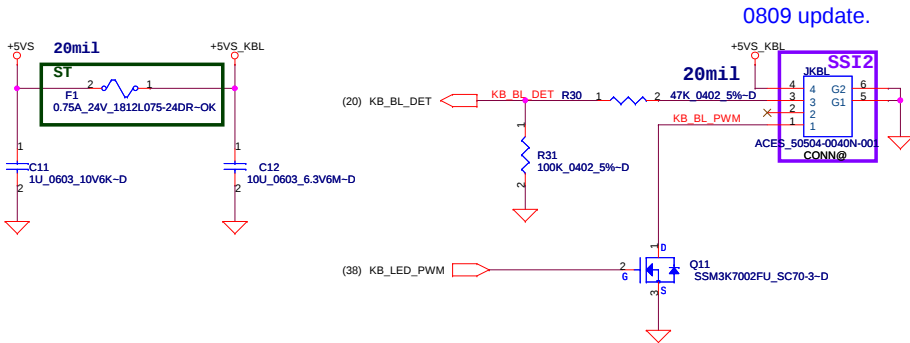
Touch pad



INT_KBD CONN

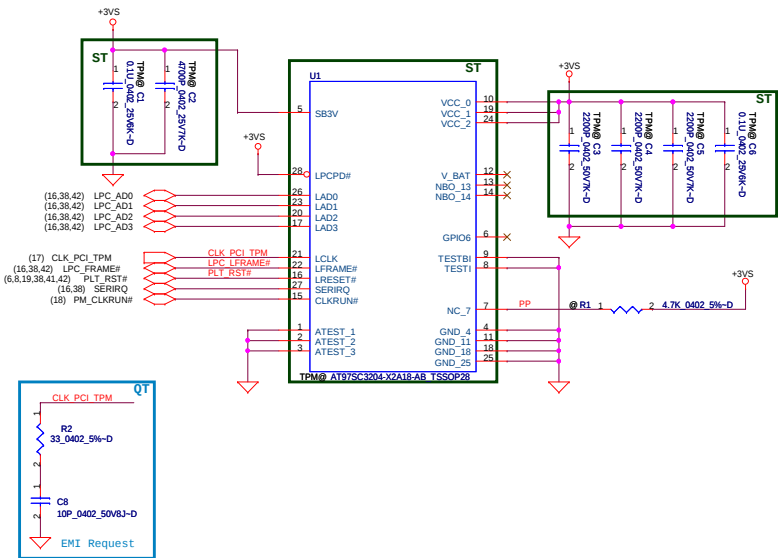


Keyboard back light

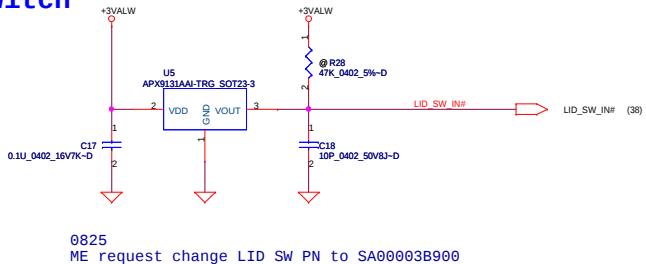


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Issued Date	2011/08/25	Deciphered Date	2012/07/25	Title	SW/TP/SCREW	
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				Custom	0.1	
				Document Number		
				LA-7851P		
Date:		Monday, March 26, 2012		Sheet	39 of 66	

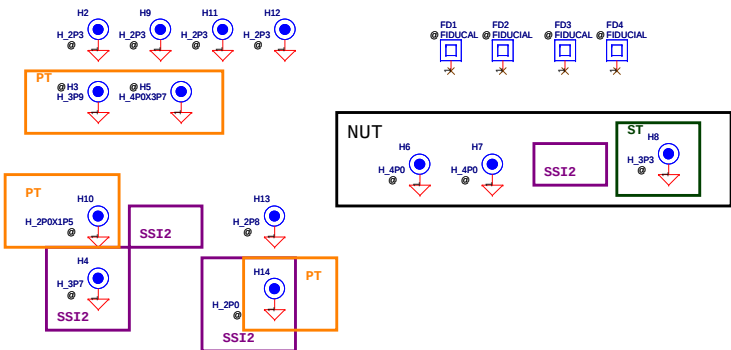
ATMEL TPM



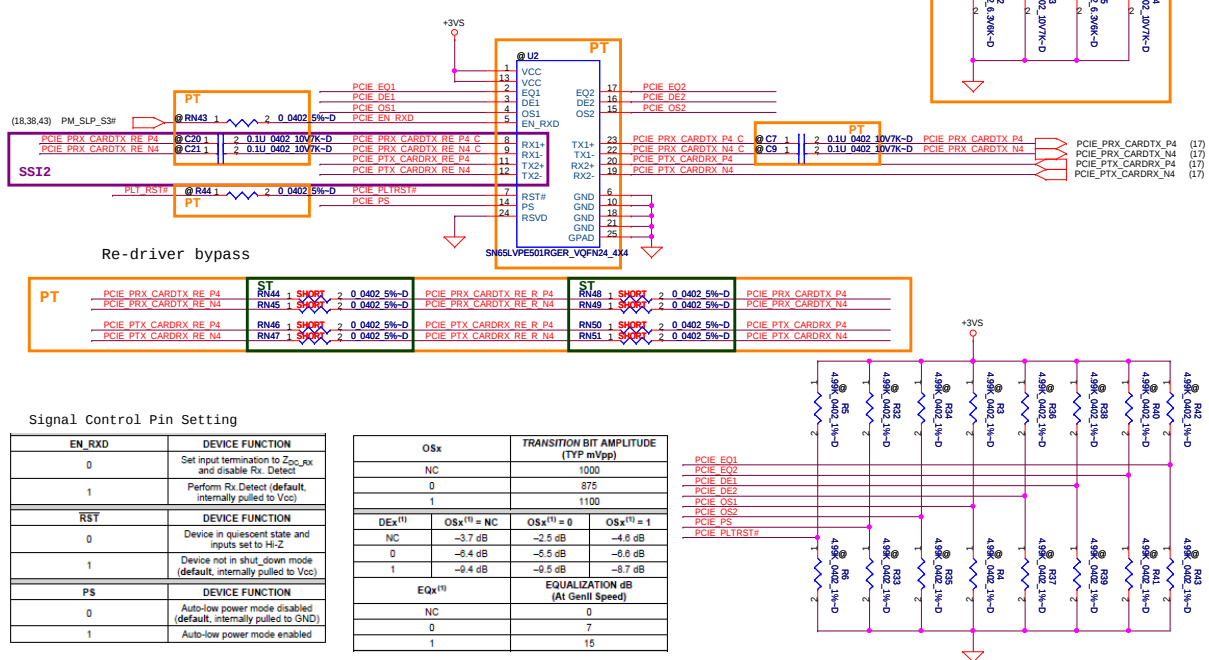
Lid Switch



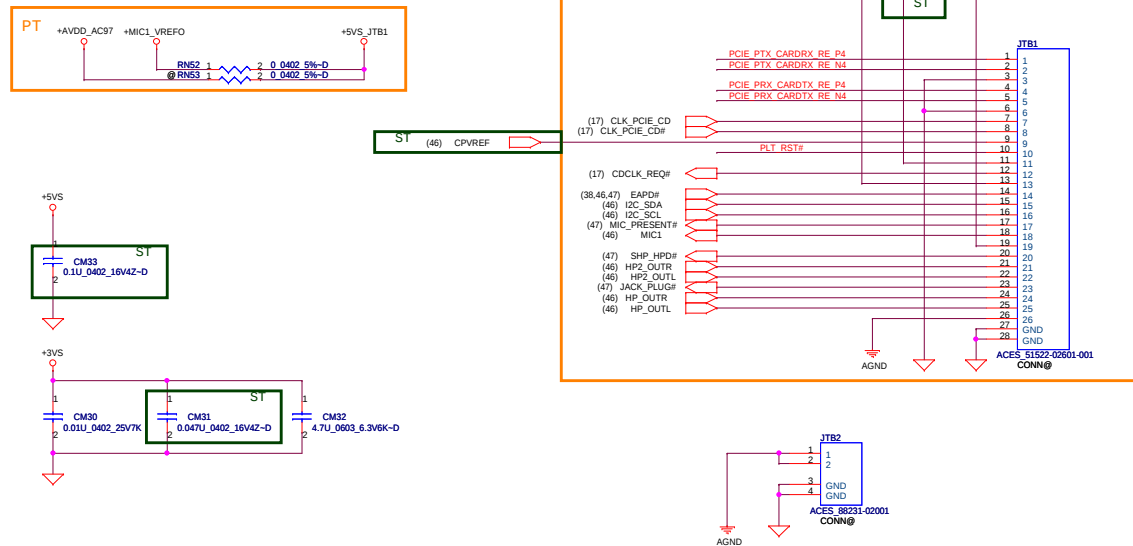
Screw Hole



PCIe Re-driver for Cardreader

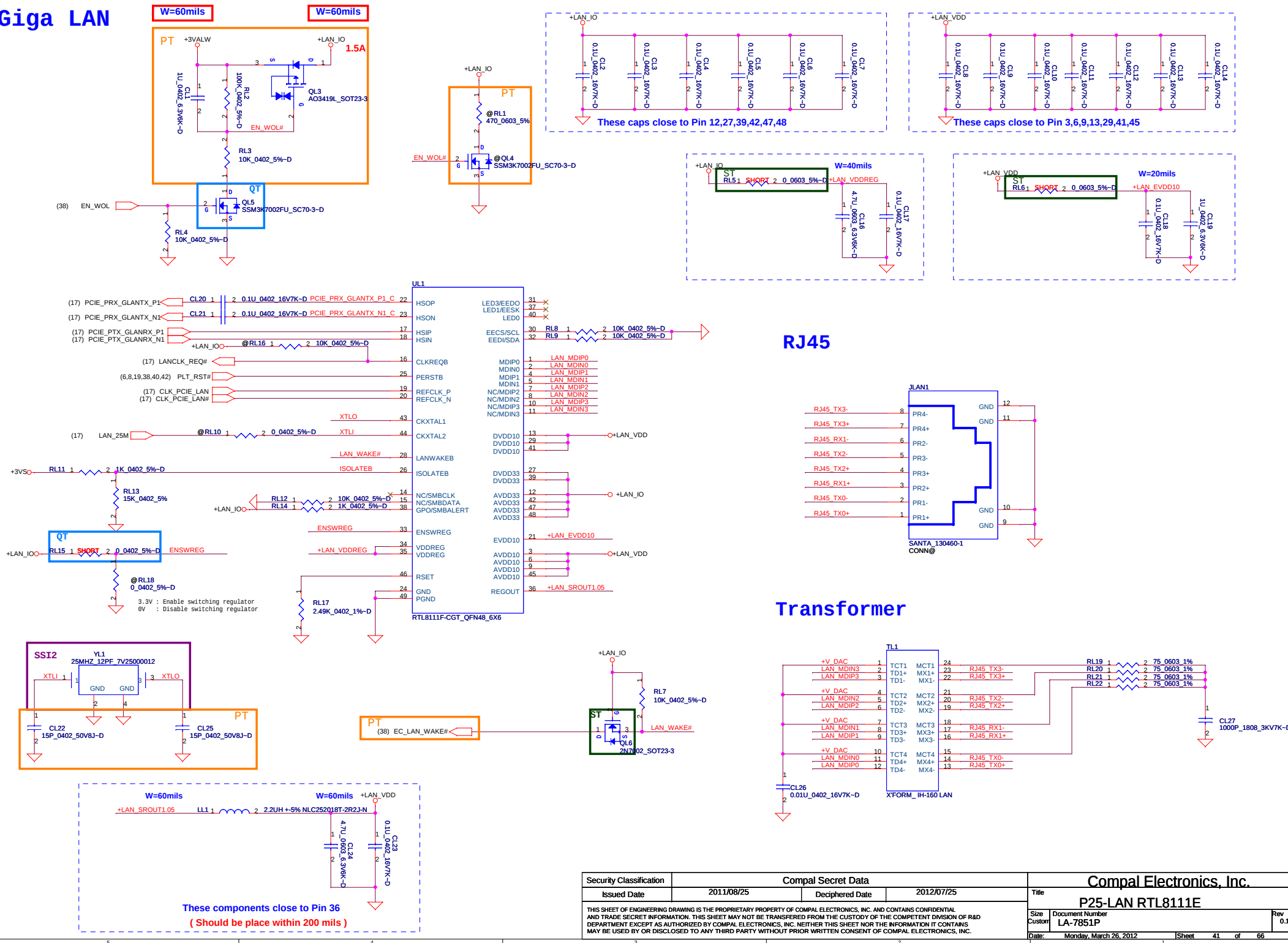


M/B to D/B conn.



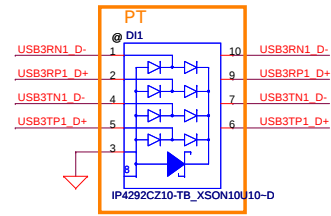
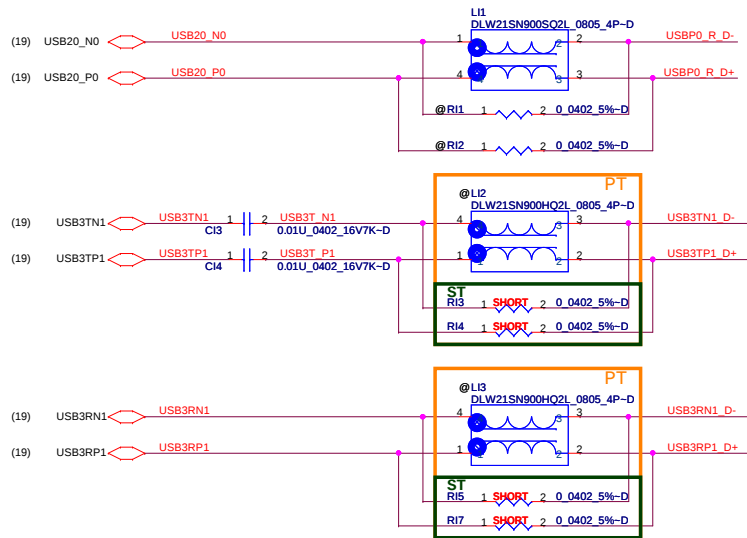
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Issued Date	2011/08/25	Deciphered Date	2012/07/25	Title	CONN & LID	
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Giga LAN

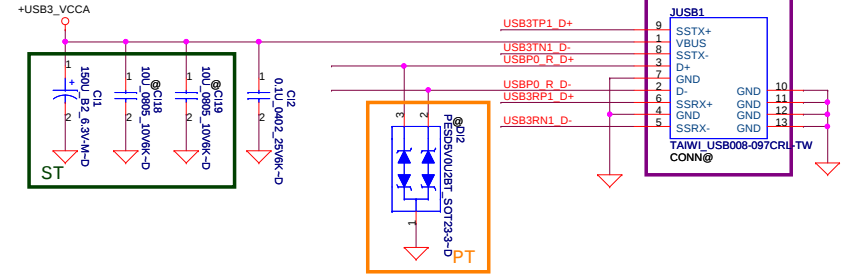


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				Customer	LA-7851P
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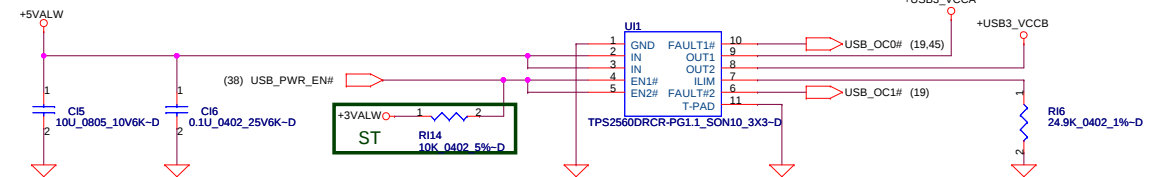
USB3.0 / USB2.0



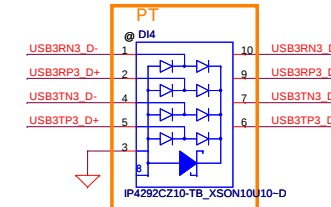
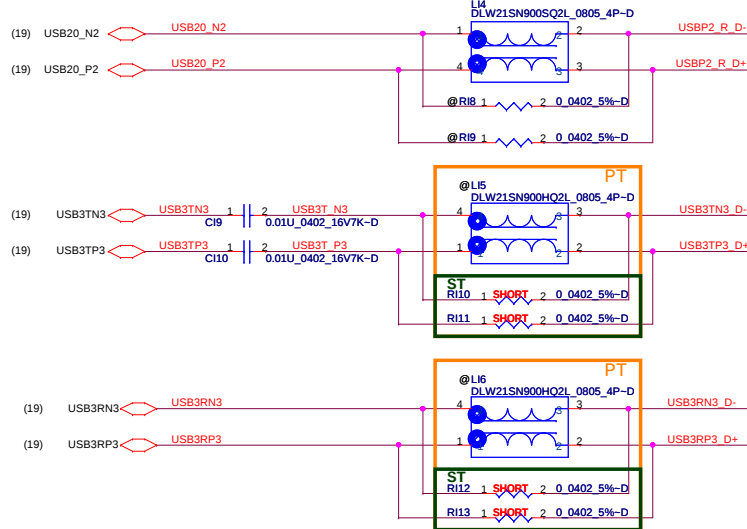
Place close to JUSB1



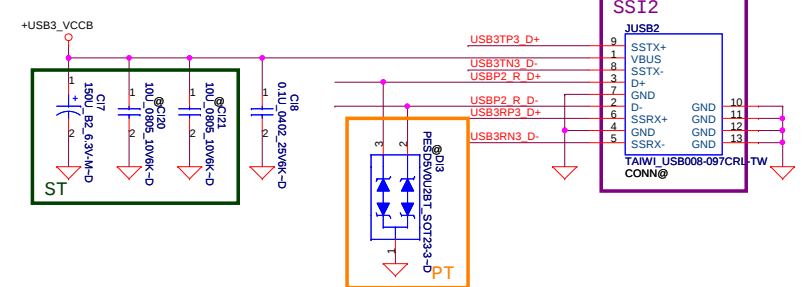
2.5A / Channel



USB3.0 / USB2.0



Place close to JUSB2



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Issued Date	2011/08/25	Deciphered Date	2012/07/25	USB conn.	
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				Date:	Monday, March 26, 2012
				Sheet	44 of 66
				Rev	0.1
				LA-7851P	

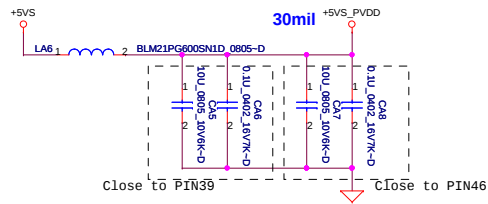
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USB3.0 / USB2.0

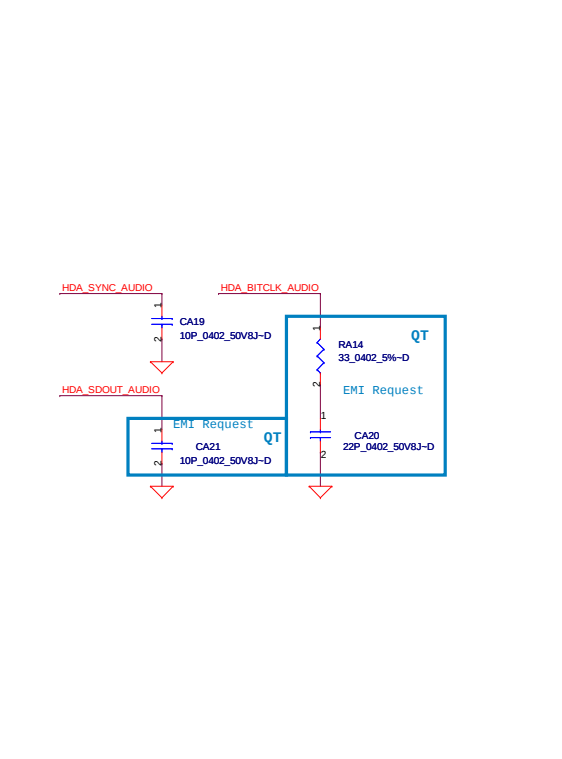
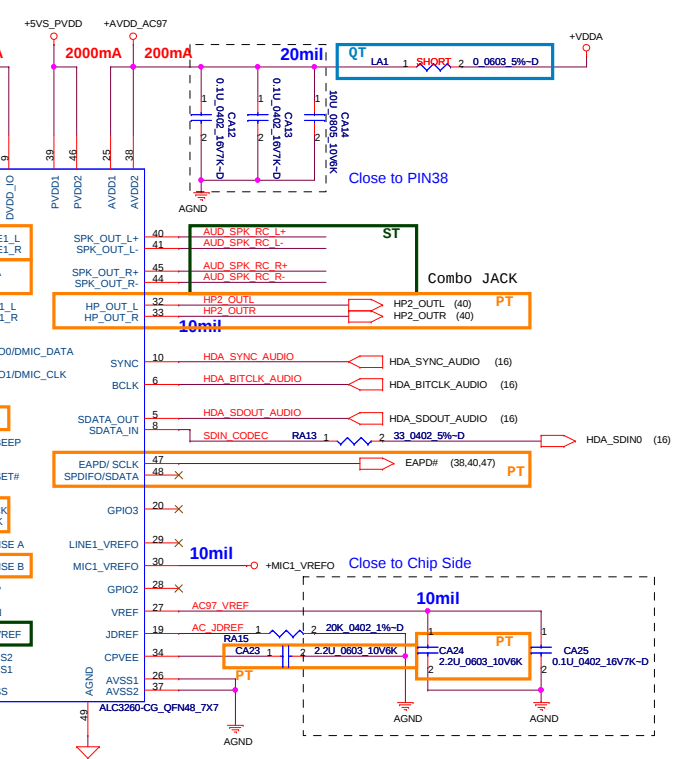
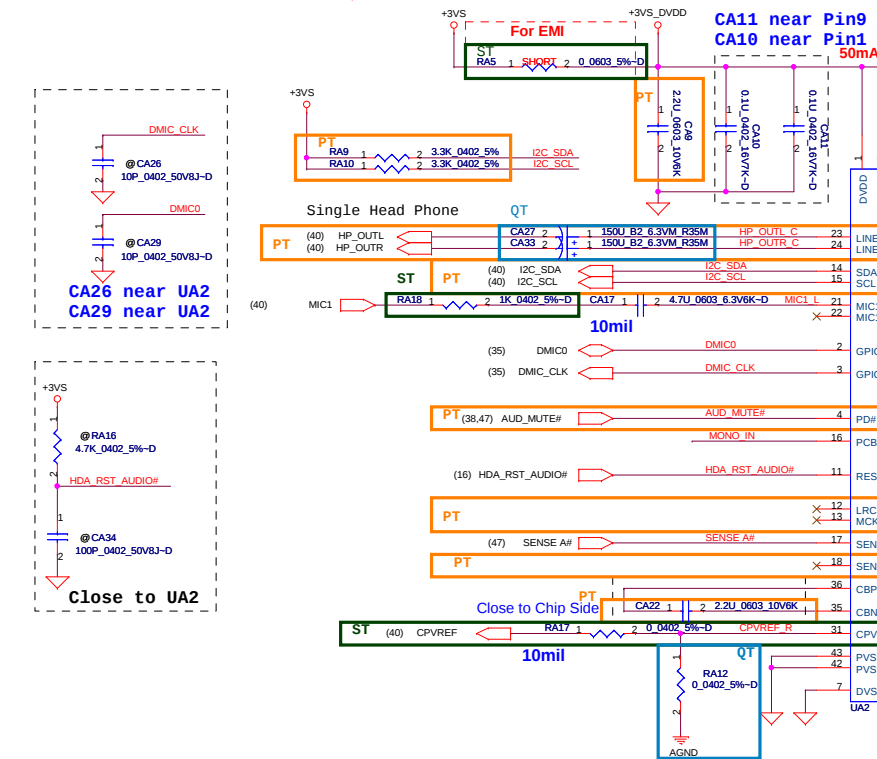
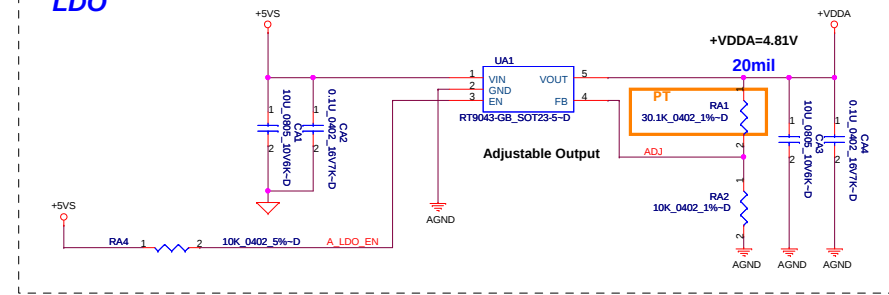
Place close to JUSB3

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				Date: Monday, March 26, 2012 Sheet 45 of 66	

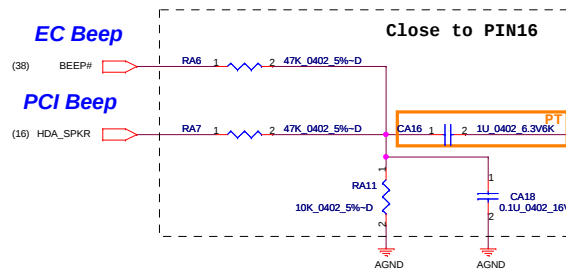
HD Audio Codec



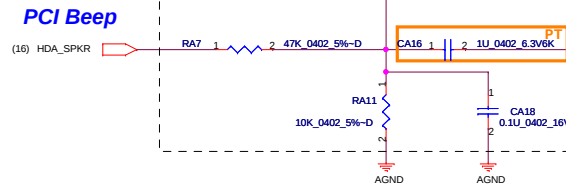
LDO



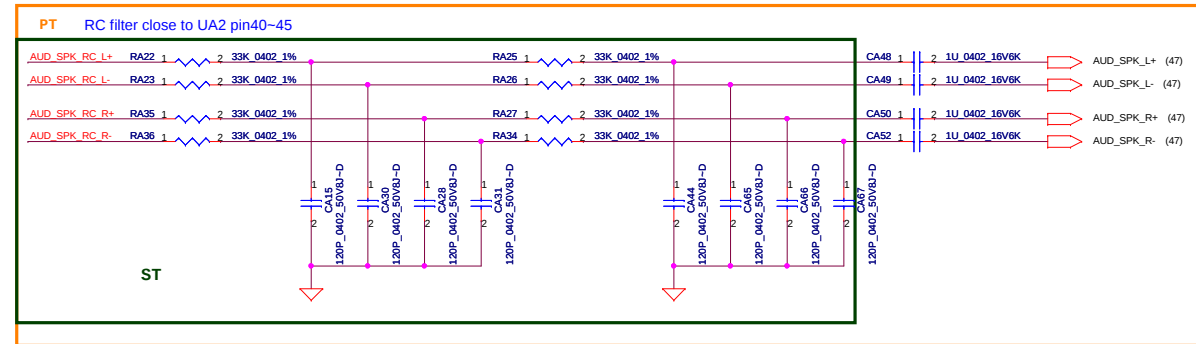
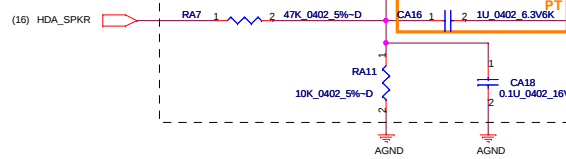
Beep sound



EC Beep

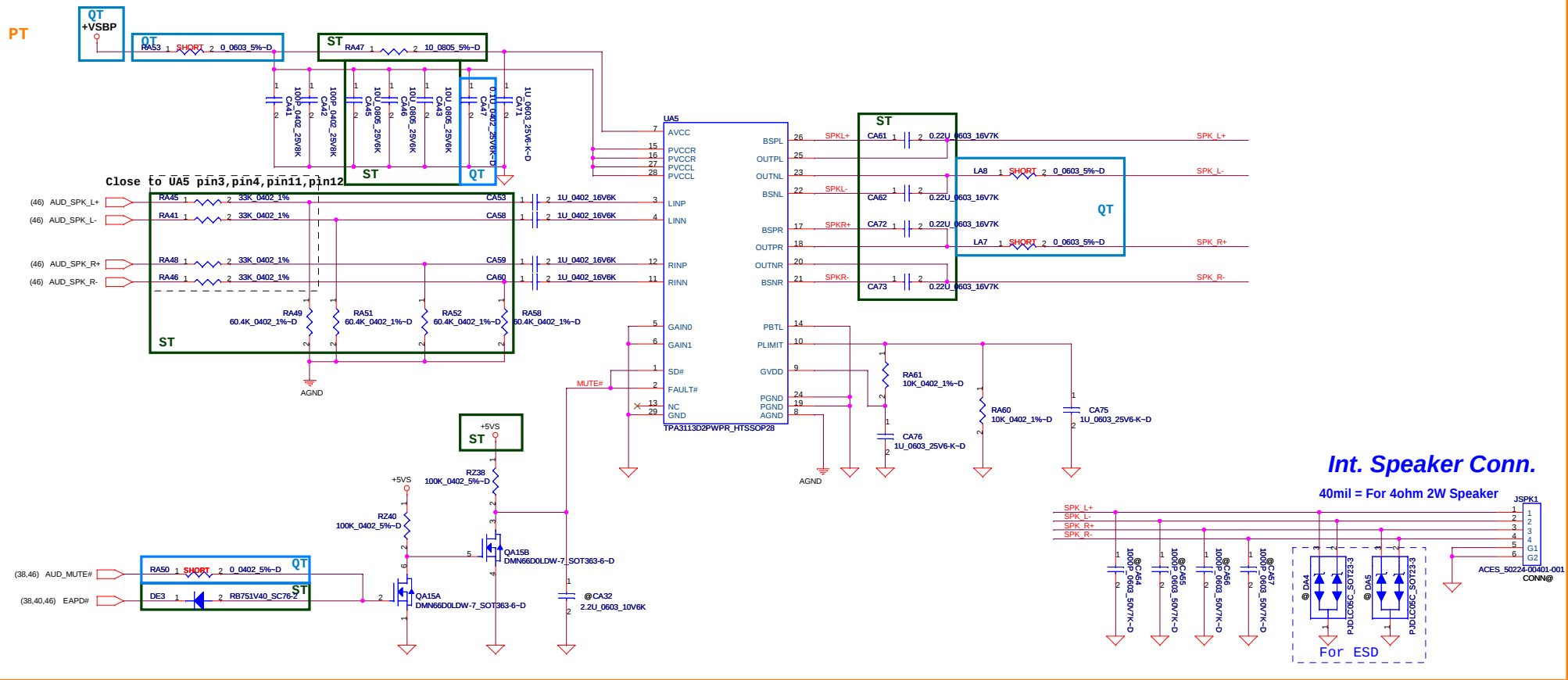


PCI Beep

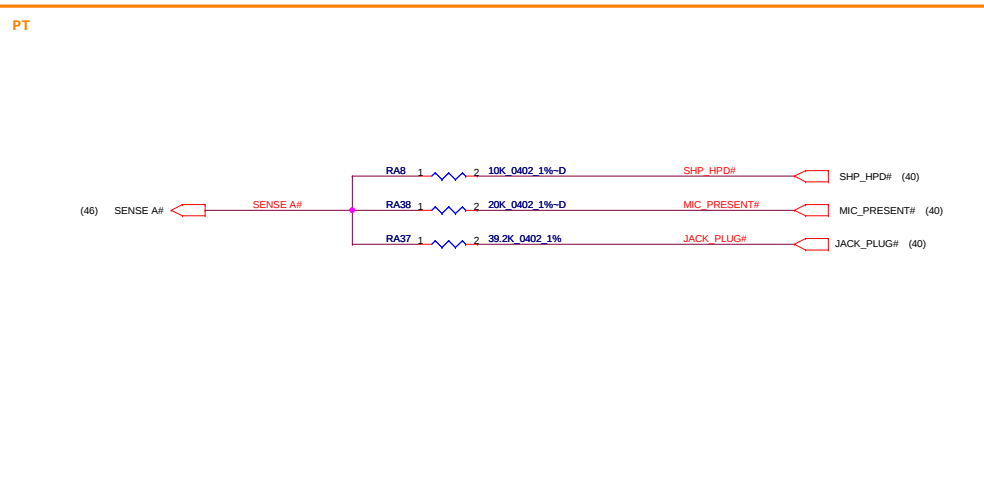


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Size	Document Number	Rev	Sheet	46	of 66

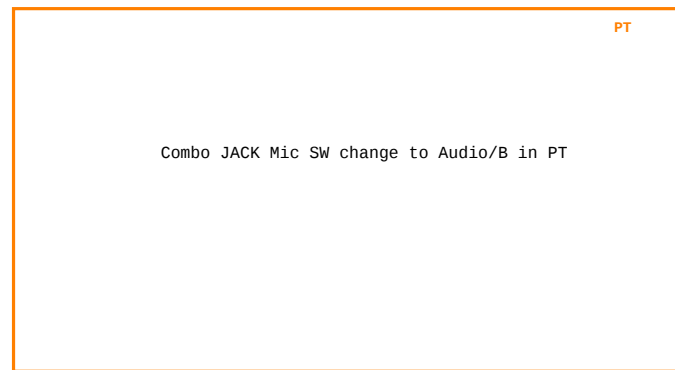
Audio AMP



SENSE PIN



Combo JACK Mic SW



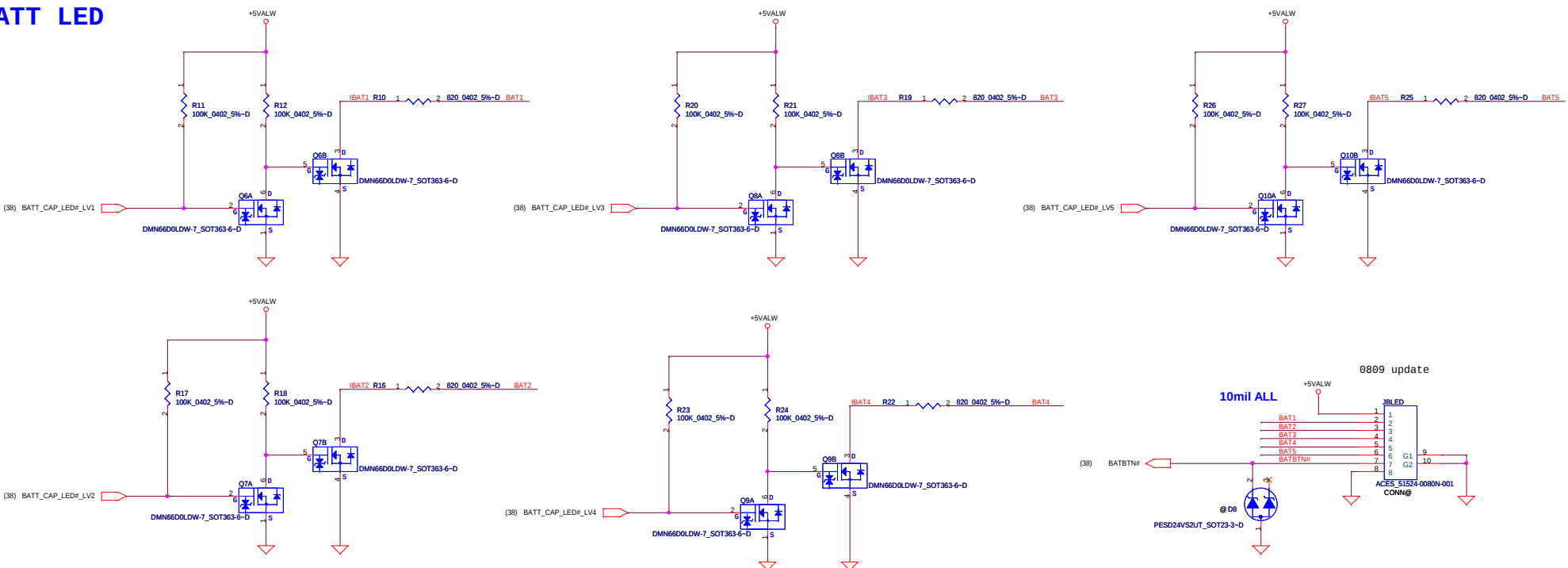
Security Classification		Compal Secret Data		Title	
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Date: Monday, March 26, 2012				Sheet	47 of 66

Compal Electronics, Inc.

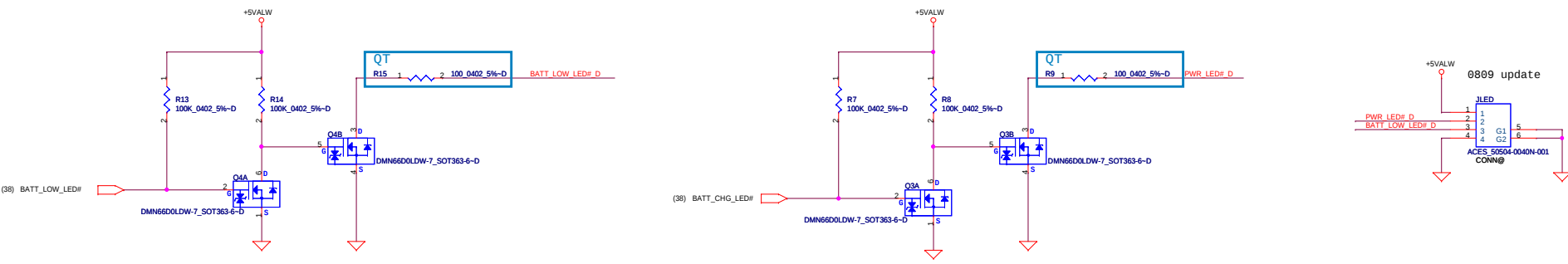
Speaker/Audio Jack

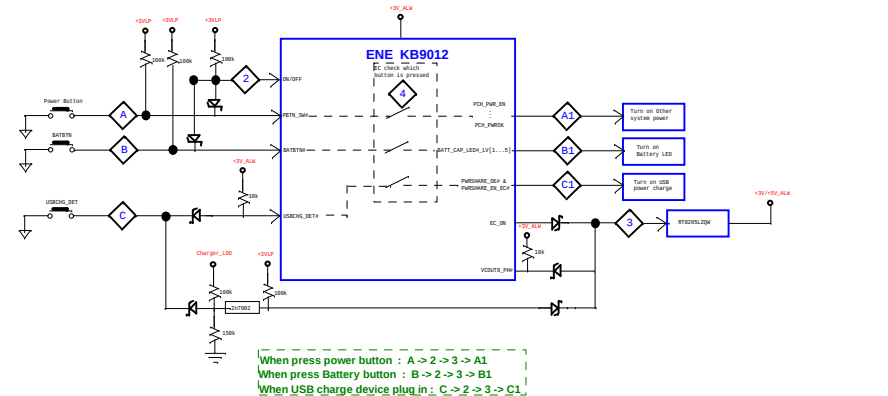
Rev 0.1

BATT LED



Charge LED





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EE change note for QBL00 Main Board

Item	Page	Title	Date	Issue Description	Solution Description	Rev.	BOM	Layout	Note
1	41	Transformer 1000P CAP	2011/8/29	PN upload BOM error	Change PN form SE120102K3L to SE120102K3L	0.1	V		BOM Change
2	46	Codec +5VS Bead	2011/8/29	PN upload BOM error	Change PN form SM010017800 to SM01001788L	0.1	V		BOM Change
3	47	Combo JACK Mic SW chip change to MB	2011/8/29		Add UA4	0.2		V	
4	40	IO Board pin define	2011/8/29		Modify JTB1 pin define for MB add Combo JACK SW cheip	0.2		V	
5	51-62	Update Power circuit	2011/8/29		Update Power circuit for QC & DC type	0.2		V	
6	38	EC_KB9012	2011/8/30	AC_STATUS	Modify DE7, DE10 and add AC_STATUS PD	0.2		V	
7	42	MINI CARD connector	2011/8/30	For AOAC function	Add DM1, RM24 and reserve RM25(PLT_RST#)	0.2		V	
8	42	EC_WLAN_WAKE	2011/8/30	For WLAN wake up function	Reserve RM26 PU +3V_WLAN	0.2		V	
9	39	JKBL CONN	2011/8/30	JKBL pin define reserve	JKBL pin define reserve (Pin1 PWM)	0.2		V	
10	47	Audio AMP 10uF CAP	2011/8/31	PJM suggestion change PN	Change PN form SE000000QKLO to SE000000QKOL	0.1	V		BOM Change
11	39	FAN Control IC	2011/9/1	CIS symbol PN error	Change UE4 PN from SA000035G00 to SA00002WS00	0.2		V	
12	47	AMP IC package	2011/9/1	Change package type	Change UA4 from BGA to QFN type	0.2		V	
13	47	AMP SPKR Bead	2011/9/1		Change PN from SM01000BP00 to SM01000BP0L	0.1	V		
14	38	EC_KB9012	2011/9/2	ODD_EJECT netname	Change GPI39 netname from ODD_EJECT to ODD_EJECT_R	0.2		V	
15	38	Power on Circuit	2011/9/2	USBCHG_DET# pin	Add QE1 on USBCHG_DET# signal	0.2		V	
16	43	Change JODD CONN	2011/9/4		Change PN from SP01000E400 to SP01001BF10	0.2		V	
17	38	Update EC GPIO table Rev.10	2011/9/4		Remove PCH_DPWROK(Pin D8) and Change pin name from PCIE_WAKE#(Pin29) to WAKE_PCH# Change pin name from EC_EAPD# to AMP_MUTE# Change pin name from AC_STATUS to AC_IN Change pin name from ACIN to EC_ON_CTRL1 Change pin name from ON/OFF# to EC_ON_CTRL2#	0.2		V	
18	38	EC_KB9012	2011/9/6	Reserve +3VLP	Reserve RE56	0.2		V	
19	38	Power on Circuit	2011/9/6	USBCHG_DET# pin	Remove AC_IN pin and change to control VL signal	0.2		V	
20	51-62	Update Power circuit	2011/9/6		Update Power circuit for QC & DC type	0.2		V	
21	35, 42	DC to DC Interface & WLAN power	2011/9/7	De-rating VGS issue	Add Z28, RZ29, RM27	0.2		V	
22	38	EC_KB9012	2011/9/7	Board ID Rb setting	Change RE12 to 8.2K	0.2	V		BOM Change
23	24, 59	NV PSI Function	2011/9/8		Add GPU_GPIO3, GPU_GPIO16 PU 10K and reserve 0 ohm to GPU CORE H_DPRS LPVR	0.2		V	
24	12	CPU VCCDQ power	2011/9/8	Intel suggestion	Add RU89	0.2		V	
25	38, 41	EN_WOL#	2011/9/9	Correct netname	Change Netname from EN_WOL to EN_WOL#	0.2		V	
26	38, 42	WLAN_EN#	2011/9/9	Correct netname	Change Netname from WLAN_EN to WLAN_EN#	0.2		V	
27	47	Combo Jack Mic SW circuit	2011/9/9	vendor suggestion	Change JACK_PLUG PU from +5VS to +3VS and add 10uF to GND ADDR_SEL add RA55 to GND Add RA56, RA57 reserve for I2C_SCL, I2C_SDA and add RA21, RA22 PU 10K for I2C_SCL, JACK_SW, I2C_SDA, JACK_SW	0.2		V	
28	43	Free Fall Sensor Pin11	2011/9/9	HDD pin 11 to be PU via internal PU	Mount RN23	0.2	V		BOM Change
29	16	2M SPI ROM	2011/9/9		Delete 2M SPI ROM circuit	0.2		V	
30	37, 44, 45	CONN Change	2011/9/14	CONN Change	Change JMDP PN to SP011109061 Change JUSB1, JUSB2 to SP011109062 Change JUSB3 to SP011109063	0.2		V	
31	38	EC_KB9012	2011/9/14	KS03 PD	Reserve RE43 for SSI rework item	0.2		V	
32	47	AMP	2011/9/14	AMP issue	Reserve RA12, RA29 for SSI rework item	0.2		V	
33	18, 38	PCH_DPWROK	2011/9/14		Add PCH_DPWROK for detect the ME request global reset	0.2		V	
34	24-32	GPU BOM Config	2011/9/14		Add GPU BOM Config	0.2	V		BOM Change
35	51-62	Update Power circuit	2011/9/19		Update Power circuit for DC type	0.2		V	
36	46	Layout footprint issue	2011/9/20	footprint issue	Change LA1 to SM01000BX0L	0.2		V	
37	40	PCIE Re-driver	2011/9/20	Redrive TX/RX swap	Swap U2 pin8/pin9 to pin11/pin12	0.2		V	
38	41	Update Power circuit	2011/9/21		Update power circuit for DC & QC type	0.2			
39	63	Add power on timing page	2011/9/21		Add page 63 power on timing	0.2			
40	38	Power on Sequence	2011/9/21	POK power sequence timing	Reserve RE24, mount PR910	0.2		V	
41	42	Debug card active	2011/9/21	EC_RX debug	Change RM11 to 1K	0.2	V		BOM Change
42	40	Screw	2011/9/21		Delete H16, H17	0.2		V	
43	40	Screw	2011/9/22		Add H14 and change H3, H4, H5 footprint	0.2		V	
44	51-62	Update Power circuit	2011/9/22		Update power circuit for DC & QC type	0.2		V	
45	20, 35	LCD DBC and CE behavio	2011/9/24		Change RH177, RH182 PD and reserve RV416, RV438 for LCD DBC, CE behavio	0.2		V	
46	22, 34	Back drive issue	2011/9/26	3V/5V PCH back drive issue	Delete JP4, add RZ230, CZ49 and change QH5 PN to SB53456003L, CH57 PN to SE064106MIL	0.2		V	
47	51-62	Update Power circuit	2011/9/26		Update power circuit for DC & QC type	0.2		V	
48	38	Update EC GPIO table Rev.11	2011/9/26	Update EC_GPIO table Rev.11	Change pin name from EC_ON_CTRL2 to EC_ON_CTRL# Change pin name from EC_ON_CTRL1 to AC_IN Change pin name from BATT_TEMP to EC_BATT_PRS Change pin name from EC_GPIOID to BATT_CAP_LED#_LV5 Change pin name from BATT_CAP_LED#_LV5 to EC_RX Remove PCH_DPWROK pin Add GPU_PROTECT pin	0.2		V	
49	47	AMP and Combo JACK SW	2011/9/26	AMP issue	Remove AMP circuit and reserve Combo JACK bypass circuit	0.2		V	
50	8	Back drive issue	2011/9/27	3V/5V PCH back drive issue	Change PM_DRAM_PWRGD PU to +3V_PCH	0.2		V	
51	46, 47	Audio FAE review	2011/9/28		Change CA17 to 4.7U, reserve RA43, RA44 for I2C_LRCK, I2C_MCK, reserve RA29 for EAPD Add RA12 PD and reserve RA39, QE5 for JACK_PLUG, change RA53 to 47K and reserve CA27 for SHP_HP	0.2		V	
52	42	WLAN power control for AOAC	2011/9/28	WLAN_EN can't control the 3VS_W	Change QM1 PN to SB00000NR00 and RM18 to 330K, RM27 to 2M	0.2		V	
53	42	MINI CARD connector	2011/9/28	For AOAC function	Remove RM24, DM1, RM25	0.2		V	
54	36	EMI	2011/9/28	EMI solution for HDMI issue	Reserve CV768, CV795, CV797, CV798, CV799, CV800, CV801, CV802, CV803, CV804	0.2		V	
55	38	ERP lot6 implementation	2011/9/28		Change EC 3VALW power rail to 3VALW_EC	0.2		V	
56	16, 17, 24, 41	Crystal change design for package size	2011/9/28		Change YH1, YH2, YV1, YL1 footprint	0.2		V	

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DRUCK Diagram

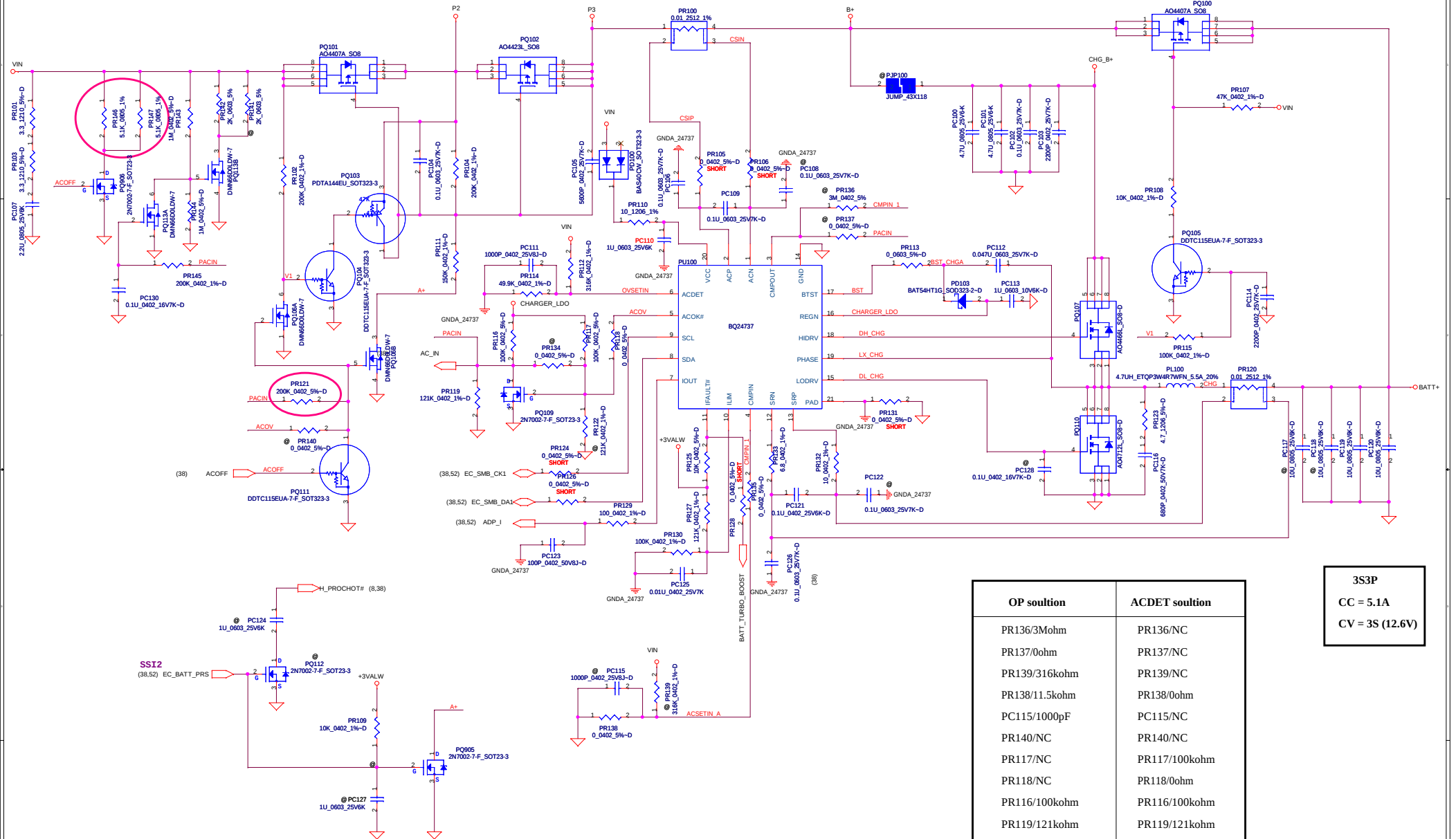
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Item	Page	Title	Date	Issue Description	Solution Description	Cause Category	Note	Rev.	BOM	Layout
1	18	SSI2 Power on issue	2011/10/23	PCH_DPWORK BOM error	Add RH101	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3	V	
2	37	Change Part PN	2011/10/23		Change QV37 PN to SB000006A00	Others				V
3	18, 38	SUSPWRDNACK signal	2011/10/23		SUSPWRDNACK signal from EC to PCH for ME reset function	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3	V	
4	35	MIC issue	2011/10/23	MIC record has background noise	Change ICCD pin7 to GND, remove CAM_DET pin and remove RH95, reserve CV755	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3		V
5	38	Modify netname	2011/10/23	Modify netname	USBCHG_DET_EC#, GPU_VR_HOT#, EAPD#	Others		0.3		V
6	10	Sandy Bridge CPU PEG*8	2011/10/24		Add RU85 for Sandy bridge sku	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3	V	
7	47	Amp circuit	2011/10/24	AMP	Add TI AMP 3113 circuit	Design issue-Improper circuit design	不適當的線路設計	0.3		V
8	47	Combo Jack SW	2011/10/24	Combo Jack SW no function	Change JACK_PLUG to SENSE A#, SHP_HP D to SENSE B#	Design issue-Improper circuit design	不適當的線路設計	0.3		V
9	40,43	PCIE Re-driver IC reserve bypass circuit	2011/10/25		Add RN44--RN51 for PCIE re-driver	Cost down		0.3		V
10	40,47	Combo Jack Saw	2011/10/25		Change Combo Jack SW circuit to Audio B and modify JTB pin define	Others		0.3		V
11	33	GPU power on sequence	2011/10/25		Change QZ1 from P-MOS to N-MOS	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3		V
12	33	dGPU timing tuning	2011/10/25	dGPU timing tuning	Change CH99 from 0.1u to 0.01u, delete RZ2, QZ3, RZ7, RZ9, QZ4, DZ1, RZ12 and reserve CZ3,	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3		V
13	18	Intel workshop add SLP_A# test point	2011/11/25		Add SLP_A# test point	Design issue-Check list coverage inadequate		0.3		V
14	46	Sourcer suggestion to change part	2011/10/30		Change UA16 footprint to 0402 and PN to SE000000K80	Cost down		0.3		V
15	46-47	Realtek review schematic suggestion	2011/10/30		HP1 & HP2 Jack exchange port, change RA22,RA23,RA25,RA26,RA35,RA36,RA27,RA34 to 137K1%, change CA15,CA30,CA28,CA31,CA44,CA65,CA67 to 30PF, change RA45,RA41,RA48,RA46 to 56K 1%, reserve RA49,RA51,RA52,RA58,CA32, change RA8 to	Vendor design issue	電子零件設計問題，需求設計變更	0.3		V
16	40	Reserve PCIE re-driver circuit	2011/10/30		Reserve U2,C20,C21,C22,C23,C24,C25,R441	Cost down		0.3	V	
17	37	Change Part PN	2011/11/1		Change QV38 PN SB3904008L to SB000006A00	Others		0.3	V	
18	52-64	Update power schematic	2011/11/1		Update power schematic	Others		0.3		V
19	39	Change Part PN	2011/11/1		Change SW1 PN SN100002M00 to SN100002M10	Others		0.3	V	
20	8	Change Part PN	2011/11/1		Change U03 PN SA00003Y000 to SA00003Y00L for buyer suggestion	Others		0.3	V	
21	34,47,8, 16,14	Change Part PN for non-HF part	2011/11/1		Change UZ1, UZ2 PN to SB000000DA10, change QD1, QD2, QH1, QU3 PN to SB051380050 Change UZ6,UZ8 PN to SB548000320, change QE1, QV34, QV36, QV37, QV39 PN to SB000008J00, change CA9, CA22, CA23, CA24 PN to SE000003H00, change LH4, LH6, LH7, LHS PN to SHI00008S0L	Others		0.3		V
22	38		2011/11/1	S3 Back drive issue	Change RE36,RE37 PU to +3VALW_EC for S3 back drive	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3	V	
23	21		2011/11/2	S3 Back drive issue	Change QH3 PU to +3V_PCH	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3		V
24	40	JTB1 Pin define	2011/11/4		Modify JTB1 pin define for add AGND pin	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3		V
25	38	Change PU resistor	2011/11/4		Change RE17,RE18,RE36,RE37 to 2.2K for EC checklist	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3	V	
26	39		2011/11/4	CAP_LED always on issue	Add RE84, delete RE53 and reserve CE58,CE50	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3		V
27	42		2011/11/4		Add RM28, QV40 for AOAC WLAN_Radio_On_Off implementation	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3		V
28	38		2011/11/4		Change RE12 to 18K for EC Board ID	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3	V	
29	35		2011/11/6	Panel screen flash or brightness no	Reserve DV10	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3	V	
30	35		2011/11/6		Reserve CV755 for +3V_CAM	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3	V	
31	41		2011/11/6		Reserve RL1 & QL4	Cost down		0.3	V	
32	8	Update CIS symbol	2011/11/6		Update U02 CIS symbol	Others		0.3		V
33	38		2011/11/7		Reserve RE16 and change to AUDIO control to AMP	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3		V
34	35	LVDS Timing Tuning	2011/11/7		Change RV401 to 22 ohm, RV412,RV413 to 1M and CV751 to 0.1u and change CV752 to 0402	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3		V
35	16		2011/11/7		Add RH95 for divide ODD_EJECT signal control by PCH & EC	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3	V	
36	17,41		2011/11/8		Mount RH102, RL10, reserve YL1, CL22, CL25 for use PCH 25M to LAN chip	Cost down		0.3	V	
37	17		2011/11/8		Change CH27, CH28, CL22, CL25 to 15P and CV575, CV576 change to 10P for vendor	Others		0.3	V	V
38	44		2011/11/10		Reserve CH1, CH7 and add CH18,CH19,CH20,CH21 for JUSB1,JUSB2, reserve CH22, CH23 for JUSB3	Cost down		0.3		V
39	33	dGPU timing tuning	2011/11/10		RZ8 change to 40.2K, RZ41 change to 150K, mount RZ6, RZ10, RZ11, RZ15, QZ15, QZ17 and change to 22 ohm, RZ5 change to 47K, RZ44 change to 20K	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3	V	
40	39		2011/11/10	CAP_LED always on issue	Add RE53,QE6,QE7,RE84 delete CE59	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3		V
41	40	ME NUT	2011/11/10		Change H5, H5 footprint	ME/SA request design change		0.3		V
42	19		2011/11/10	Back drive issue	Change UH4 power rail to +3V_DELAY	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3		V
43	40		2011/11/11		JTB1 pin define change	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3		V
44	35		2011/11/11		Change RV401 to 100 ohm 0805 package	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3		V
45	37		2011/11/13	Mdp Dongle issue	Change JMDP to footprint	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3		V
46	16,38	ODD_Ejection	2011/11/14		Reserve RH95 and mount RE31 for EC control ODD_EJECT, change QN6 to signal package	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3		V
47	25	GPU DID strap pin	2011/11/14		Change RV302, RV306, RV307, RV308, RV309, RV311, RV312, RV313, RC314, RV315, RV316 to 10K	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3	V	
48	40		2011/11/14		Modify JTB1 pin define	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3		V
49	39		2011/11/14	CAP_LED always on issue	Delete QE7 and reserve CE58	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3		V
50	38		2011/11/14	INT_SPKR_PO noise issue	Mount RE16 for EAPD# control	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3	V	
51	46	FAE suggestion	2011/11/14	Audio Precision fail	Change RA1 to 30.1K for adjusted LDO output voltage to 4.8V	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3	V	
52	46,47		2011/11/15		Add CA27 & CA33 for DB change to MB, delete QE5	Others		0.3		V
53	52-64	Update power schematic	2011/11/15		Update power circuit for DC & QC type	Others		0.3		V
54	35,41		2011/11/15		Update QV27, QL3 CIS symbol	Library Update	CIS 資料變更	0.3		V
55	41		2011/11/16		Change RL3 to 10K and delete CL15 for modify LAN_IO pwrwr design	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3		V
56	52		2011/11/16		Change EC_BATT_PRS PU to 3VALW_EC	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3		V
57	42,38,41		2011/11/16		Change EC_WLAN_WAKE netname to EC_WLAN_WAKE# and EC_LAN_WAKE netname to EC_LAN_WAKE#	Others		0.3		V
58	35	LVDS Timing Tuning	2011/11/16		Change RV402 to 10K, RV404 to 150K, CV475 to 0.1uF	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3	V	
59	36		2011/11/16		Change LV7-LV10 PN from SM070001E0L to SM070002S0L	Others		0.3	V	
60	1		2011/11/17		Change UV4-UV7 PN to SA00005B70L for D-die	Others		0.3	V	
61	42		2011/11/17		Delete T22, T23 test point	Others		0.3		V
62	44,45		2011/11/17		Reserve L12, L13, L15, L16, L18, L19 and mount RU3, RI4, RI5, RI7, RI10, RI11, RI12, RI13, reserve DI1, DI4, DI6, DI2, DI3	Cost down		0.3	V	
63	33	dGPU timing tuning	2011/11/17		Change RZ6 to 100 ohm 0603 package for NVIDIA suggestion	Vendor design issue	電子零件設計問題，需求設計變更	0.3		V
64	46		2011/11/17		Change CA15 to 0402 package,Delete RA43, RA44, RA28, RA29, RA42	Vendor design issue	電子零件設計問題，需求設計變更	0.3		V
65	43		2011/11/17		Delete RN15--RN22 HDD re-driver bypass circuit	Others		0.3		V
66	36	HDMI EA 7-2 item	2011/11/18		Change RV429-RV436 to 470 ohm	Design issue-Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.3	V	

Iada=0-4.62A(90W)

ADP_I = 19.9*Iadapter*Rsense

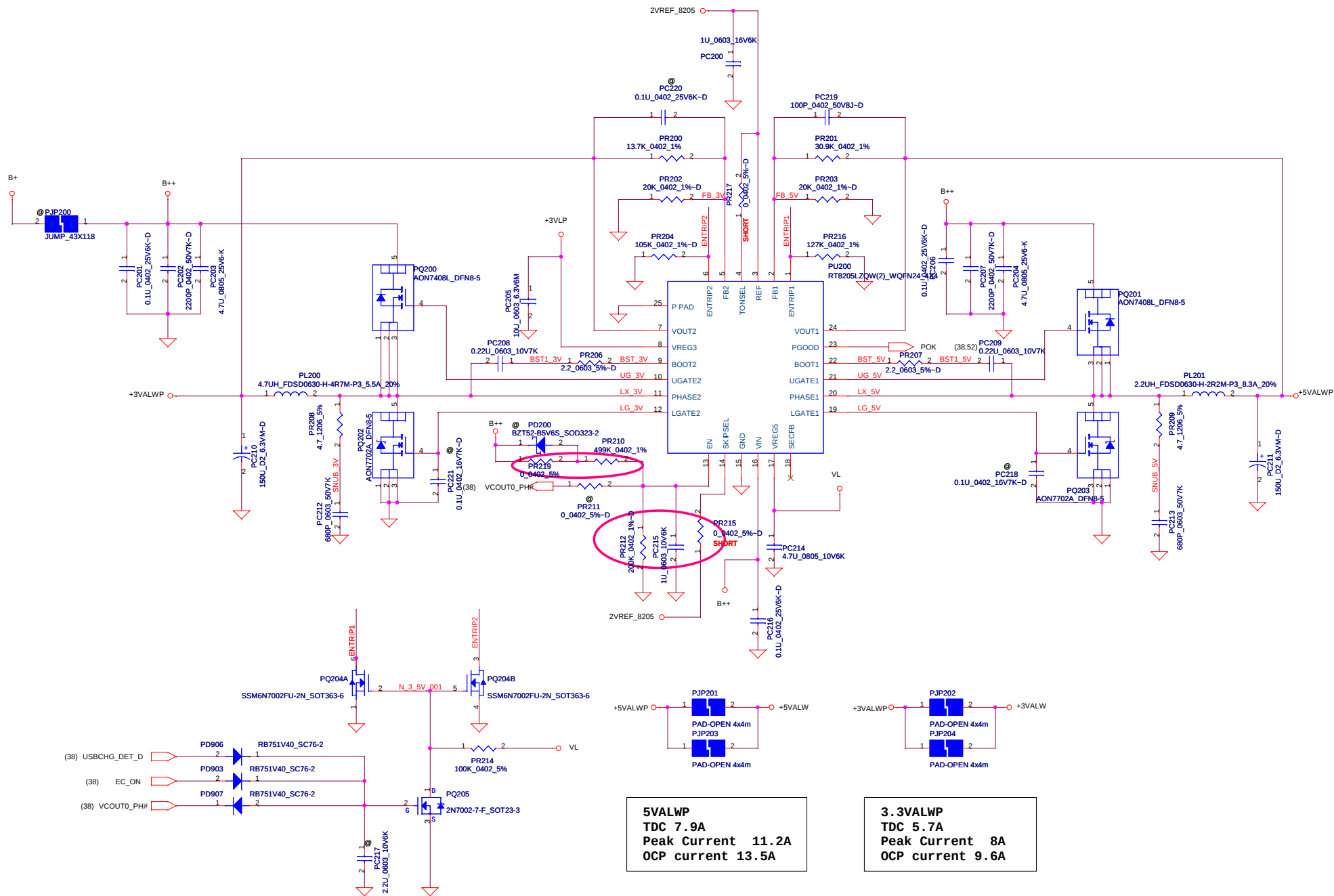


OP soution	ACDET soution
PR136/3Mohm	PR136/NC
PR137/0ohm	PR137/NC
PR139/316kohm	PR139/NC
PR138/11.5kohm	PR138/0ohm
PC115/1000pF	PC115/NC
PR140/NC	PR140/NC
PR117/NC	PR117/100kohm
PR118/NC	PR118/0ohm
PR116/100kohm	PR116/100kohm
PR119/121kohm	PR119/121kohm
PQ109/NC	PQ109/2N7002
PR121/47kohm	PR121/47kohm
PR134/NC	PR134/NC
PR122/NC	PR122/NC

3S3P
CC = 5.1A
CV = 3S (12.6V)

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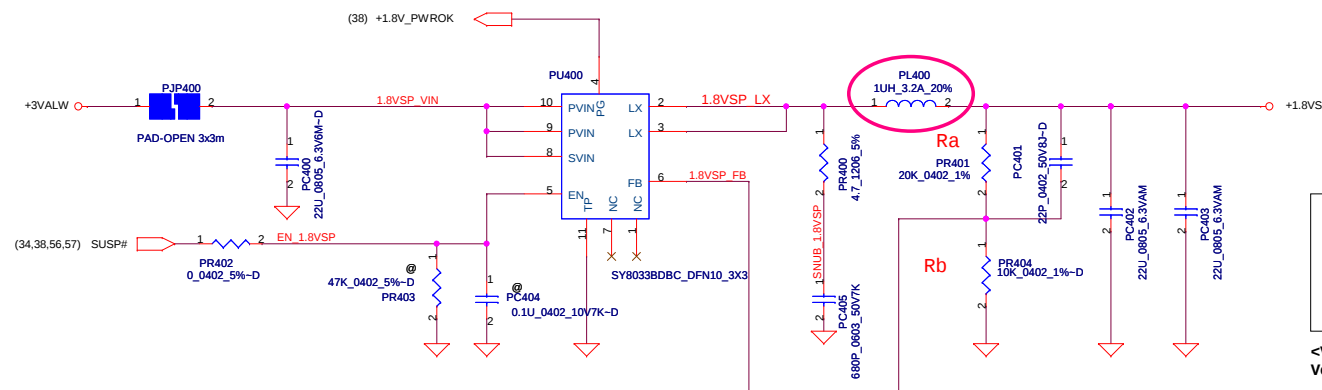




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+1.8VSP
TDC 1.3A
Peak Current 1.9A
OCP current 2.3A

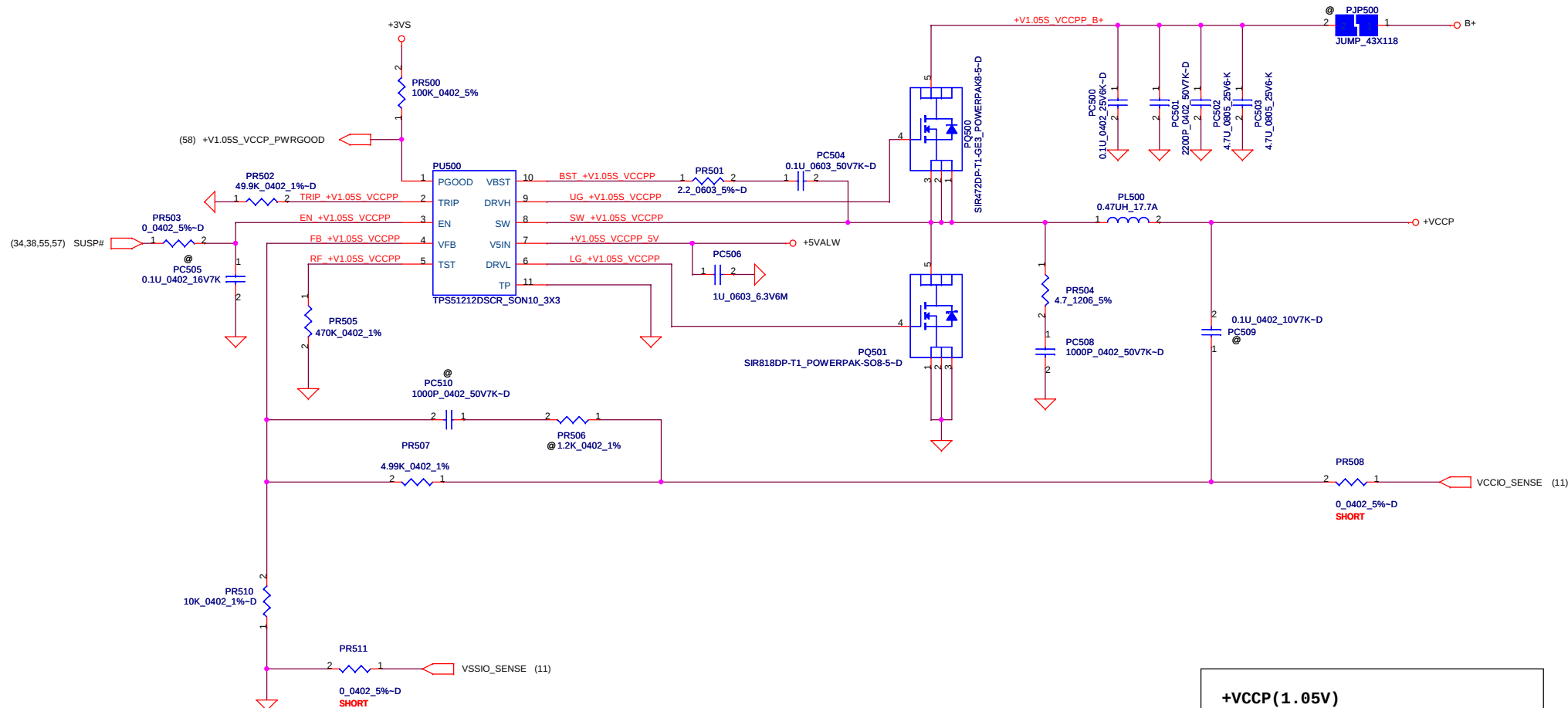
<Vo=1.8V> VFB=0.6V
 $V_o = V_{FB} * (1 + R_a/R_b) = 0.6 * (1 + 20K/10K) = 1.8V$

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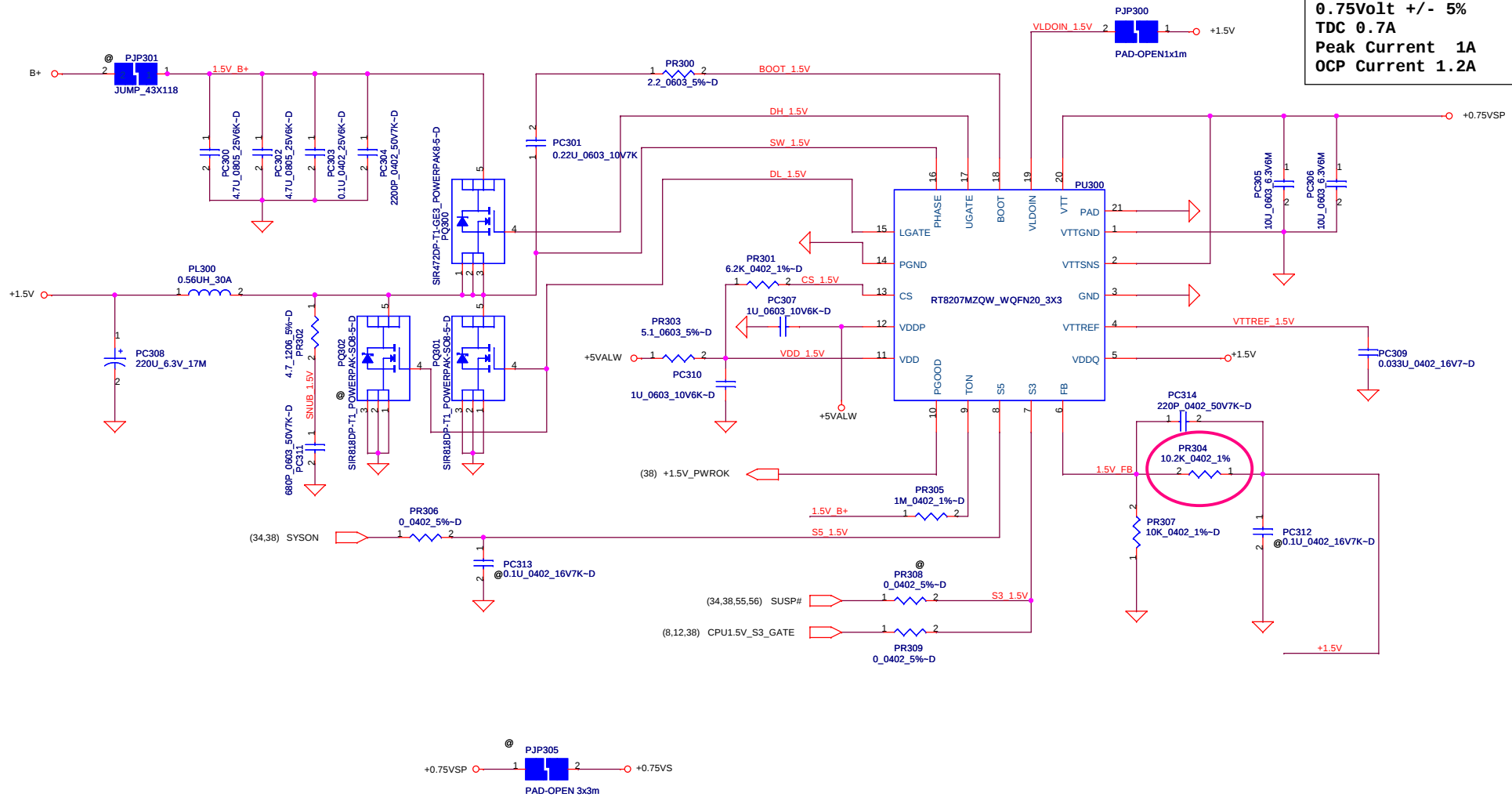
+VCCP(1.05V)
TDC 13A
Peak Current 19A
OCF current 22.8A
TYP MAX
H/S Rds(on) 10mohm , 14.5mohm
L/S Rds(on) :3mohm , 3.6mohm

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Title		
PWR-V1.05S_VCCPP		
Size	Document Number	Rev
	LA-7851P	0.1
Date:	Monday, March 26, 2012	Sheet 56 of 63

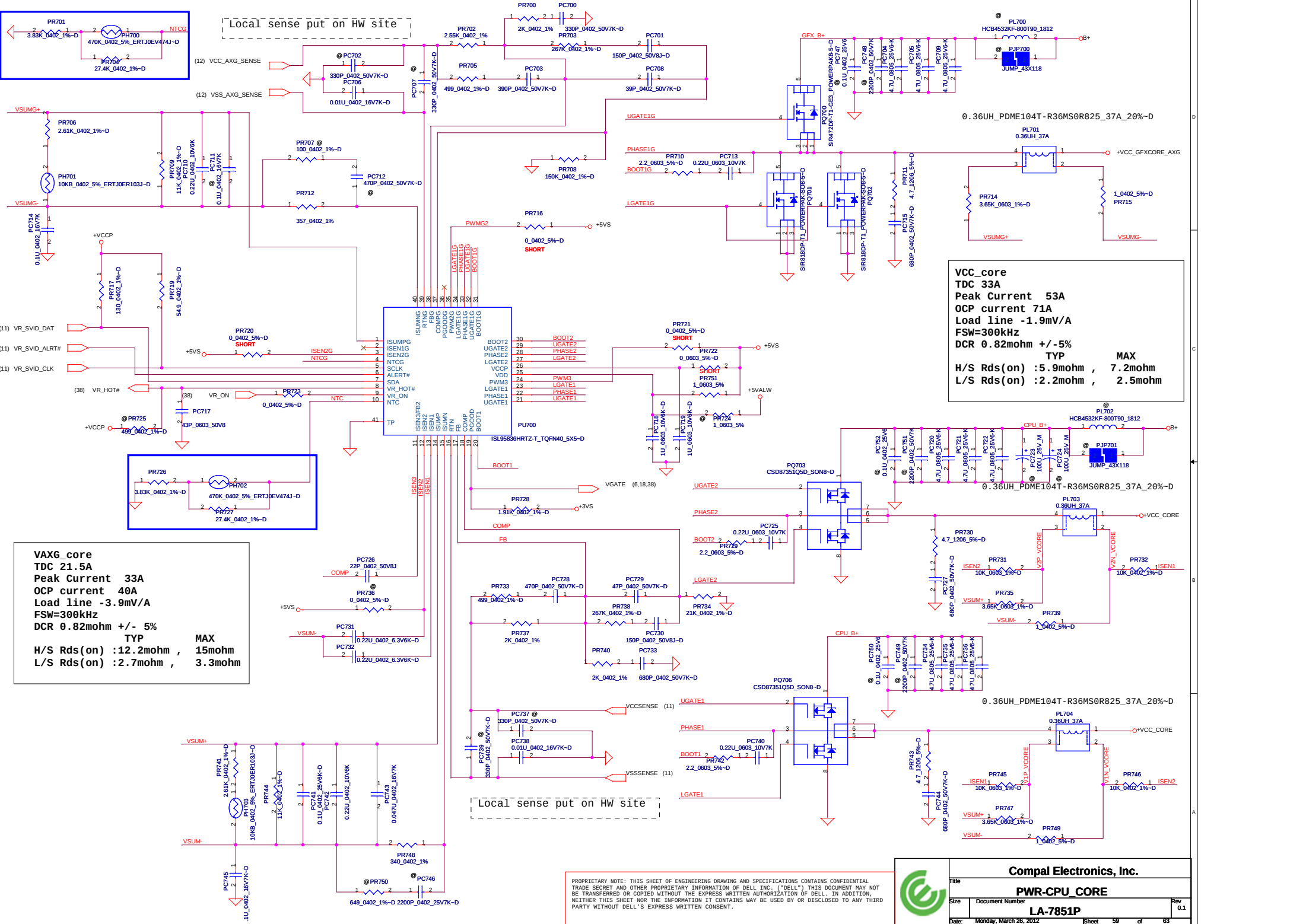


1.5VP	
TDC 14 A	
Peak Current 20 A	
OCP current 24A	
	TYP
H/S Rds(on)	:10mohm , 14.5mohm
L/S Rds(on)	:3mohm , 3.6mohm

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Title		
PWR-1.5VP/0.75VSP		
Size	Document Number	Rev
	LA-7851P	0.1
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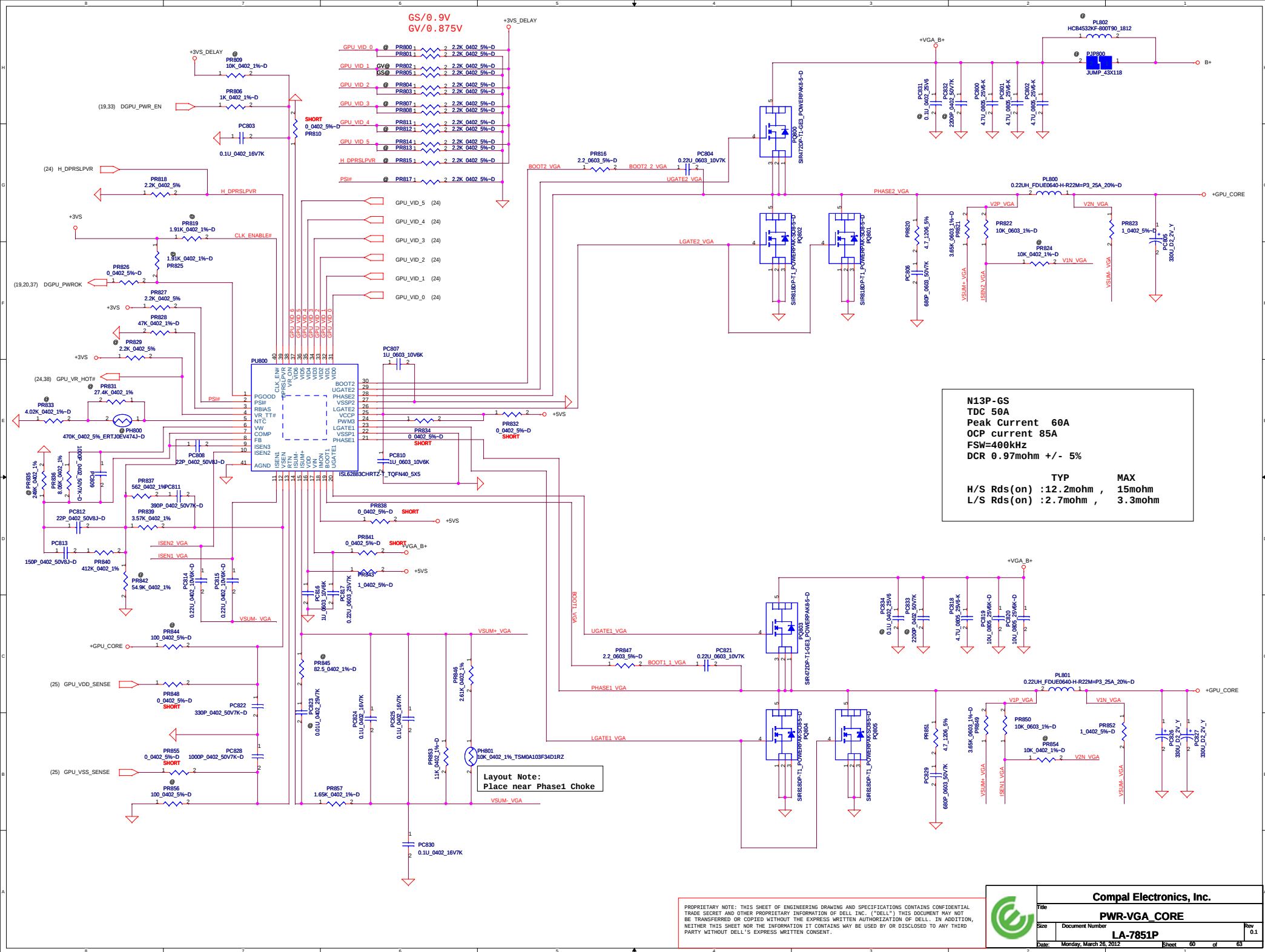


VAXG_core
TDC 21.5A
Peak Current 33A
OCP current 40A
Load line -3.9mV/A
FSW=300kHz
DCR 0.82mohm +/- 5%
TYP MAX
H/S Rds(on) :12.2mohm , 15mohm
L/S Rds(on) :2.7mohm , 3.3mohm

VCC_core
TDC 33A
Peak Current 53A
OCP current 71A
Load line -1.9mV/A
FSW=300kHz
DCR 0.82mohm +/- 5%
TYP MAX
H/S Rds(on) :5.9mohm , 7.2mohm
L/S Rds(on) :2.2mohm , 2.5mohm

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GS/0.9V
GV/0.875V



N13P-GS
TDC 50A
Peak Current 60A
OCP current 85A
FSW=400kHz
DCR 0.97mohm +/- 5%

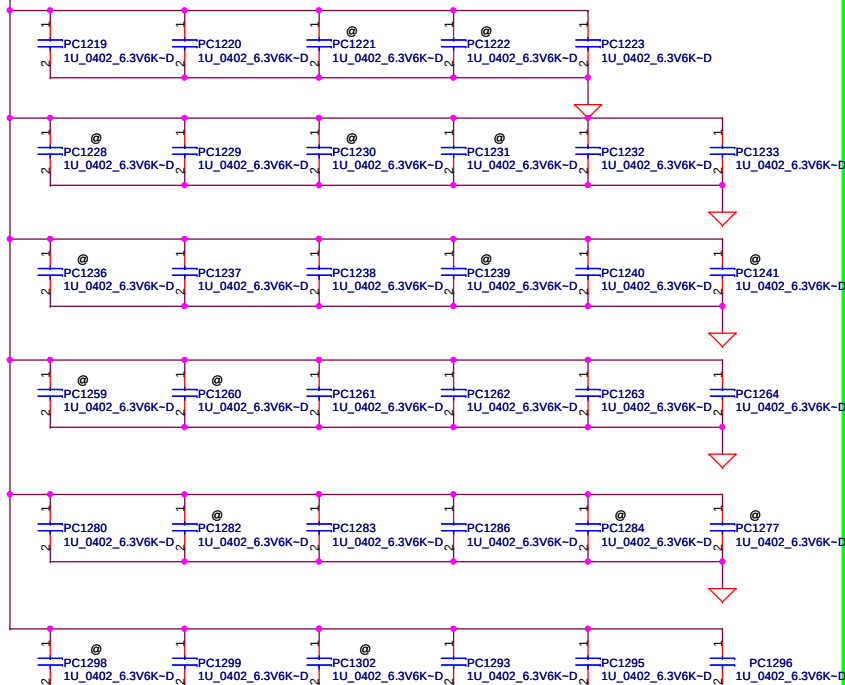
	TYP	MAX
H/S Rds(on)	:12.2mohm	15mohm
L/S Rds(on)	:2.7mohm	3.3mohm

Layout Note:
Place near Phase1 Choke

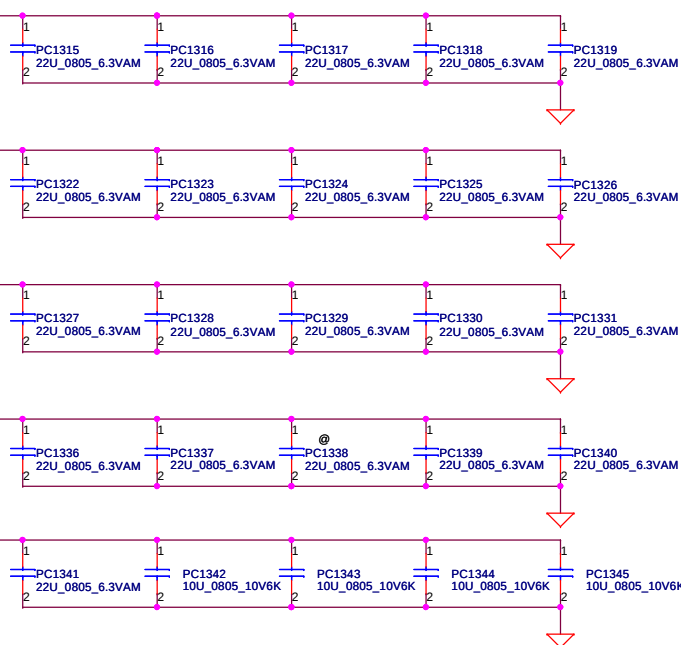
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+VCC_CORE

+VCC_CORE



+VCC_CORE



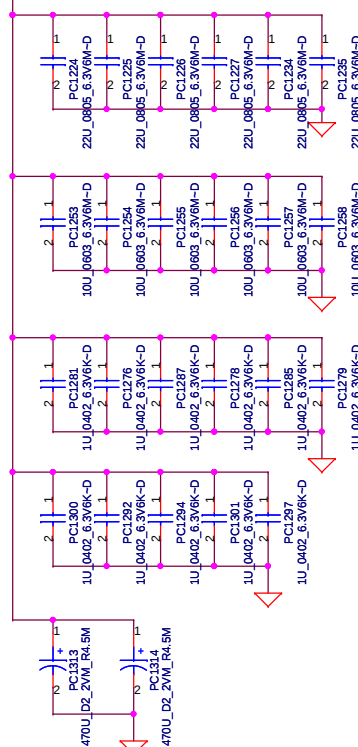
+VCC_GFXCORE_AXG

Design guide:

iGfx_Cout

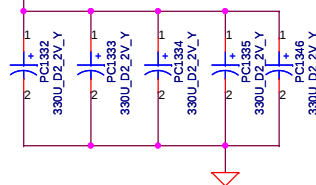
- 1.22uF*6 (SE000000I10)
- 2.10uF*8 (SE000005T8L)
- 3.1uF*9 (SE000000K8L)
- 4.470uF 4.5m *2 (SGA00004200)

+VCC_GFXCORE_AXG



+VCC_CORE

+VCC_CORE

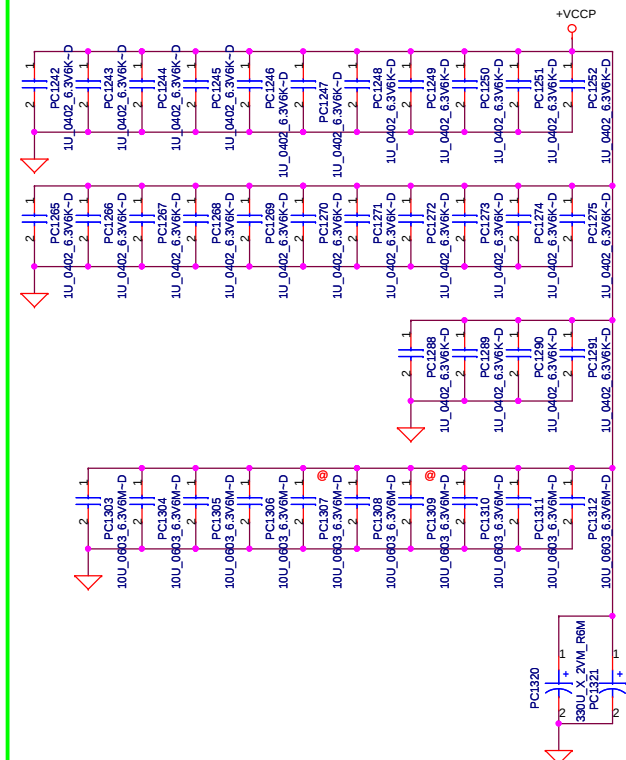


+VCCP

Design guide:

+1.05V_RUN_VTT

- 1.1uF*26 (SE000000K8L)
- 2.10uF*10 (SE000005T8L)
- 3.330uF 6m *2 (SGA00001Q80)



Design guide: Vcore_Cout

- 1.1uF*20 (SE00000888L), reserve 8pcs is not stuff
- 2.22uF*20 (SE000008L80)
- 3.470uF 4.5m *4 (SGA00004X80)
- 4.10uF*4 (SE000004880)

Red @ is for 20% Cap reduces

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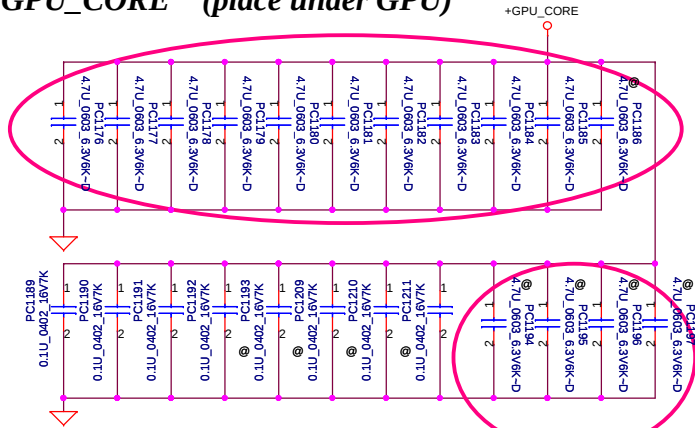
PROCESSOR DECOUPLING

LA-7851P

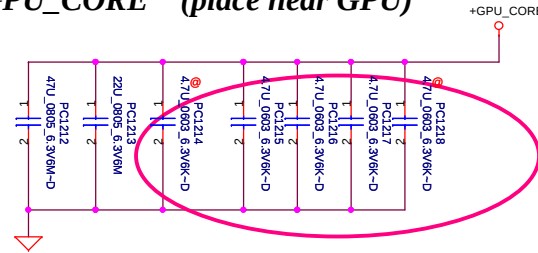
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+GPU_CORE (place under GPU)



+GPU_CORE (place near GPU)



Red @ is for 20% Cap reduces

Design guild: +GPU_CORE_Cout
Under GPU

1.4.7uF*10 (SE00000G30L),.reserve 5pcs is not stuff
2.0.1uF*4 (SE076104K80),.reserve 4pcs is not stuff

Near GPU

1.47uF*1 (SE000001120)
2.22uF*1 (SE00000PL0L)
3.4.7uF*5 (SE00000G30L)
4.reserve D-case cap is not stuff

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X02

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Title		
PWR-PIR		
Size	Document Number	Rev
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EE change note for QBL00 Main Board													
Item	Page	Title	Date	Issue Description	Solution Description	Cause Category	Note	Rev.	BOM	Layout			
1	46, 47, 38, 17, 24, 39	PT SMT MEMO change part	2011/12/21		Change RA22, RA23, RA35, RA36, RA25, RA26, RA27, RA34 PN to SD034330280(33K) Change CA15, CA30, CA28, CA31, CA44, CA65, CA66, CA67 PN to SE071121J8L(120P) Change RA45, RA41, RA48, RA46 PN to SD034150380(150K) Change YH2 PN to SJ10000EF00(25MHz) Change YV1 PN to SJ10000970L(27MHz) Change RE84 PN to SD02847008L(470 ohm) Change R45 PN to SD03447028L(47K) Change CA43, CA45, CA46 PN to SE000000QK0L(10U_0805)	Design issue--Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.4	V				
2	47	Change to X7R part	2011/12/21		Change CA61, CA62, CA72, CA73 to X7R part	Design issue--Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.4	V				
3	17	Reserve CLK_CPU_IPT signal	2011/12/21		Reserve RH91, RH92 for CLK_CPU_IPT	Design issue--Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.4	V				
4	12		2011/12/21		Delete JP7	Design issue--Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.4		V			
5	40		2011/12/21		Change JTB1 PIN11 to +RTCVCC	Design issue--Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.4		V			
6	42, 44, 45		2011/12/22	USB port and MiniCard will flash of light when AC plug in	Add USB_PWR_EN# PU 10K(RJ14) to +3VALW Add PWRSHARE_EN_EC# PU 10K(RJ15) to +3VALW Add WLAN_EN# PU 10K(RM24) to +3VALW	Design issue--Check list coverage inadequate	檢視清單中，未能涵蓋的問題	0.4		V			
7	43	Derating	2011/12/23		Change RN24 to 330K and add RN27 1.5M	Design issue--Check list coverage inadequate	檢視清單中，未能涵蓋的問題			V			
8	38	Board ID Table for AD channel	2011/12/23		Change RE12 to 33K	Design issue--Check list coverage inadequate	檢視清單中，未能涵蓋的問題			V			
9	46		2011/12/28	AUD_SPK Netname duplicate	Modify netname to AUD_SPK_RC_L+/AUD_SPK_RC_L-	Design issue--Check list coverage inadequate	檢視清單中，未能涵蓋的問題			V			
10	47		2011/12/28		Change RA47 package to 0805	Design issue--Check list coverage inadequate	檢視清單中，未能涵蓋的問題			V			
11	47		2011/12/30	For S5 power saving in AC mode	Change RZ38 PU to +5VS	Design issue--Check list coverage inadequate	檢視清單中，未能涵蓋的問題			V			
12	38		2011/12/30	3V/5V_ALW on in DC mode	Change RE50 PU to +3VLP and reserve RE44	Design issue--Check list coverage inadequate	檢視清單中，未能涵蓋的問題			V			
13	7~13	Modify CPU PN	2012/1/2		LA7851 QC sku Change UV1 PN to SA000051Z0L for LA7852 DC sku	Others				V			
14	24~28	Modify GPU PN	2012/1/2		Change UV1 PN to SA00005180L for GS, change UV1 PN to SA00005690L for GV	Others				V			
15	16~23	Modify PCH PN	2012/1/2		Change UH1 PN to SA00005AG1L	Others				V			
16	40	Modify TPM PN and add BOM optional	2012/1/2		Change U1 PN to SA00004WQ10 and add TPM@ in value for BOM optional C1~C6 add TPM@ in value for BOM optional	Others				V			
17	35		2012/1/4	Ambient light sensor abnormal	Change RV417 to 100 ohm for DMIC_CLK signal	Design issue--Check list coverage inadequate	檢視清單中，未能涵蓋的問題			V			
18	47		2012/1/4	Audio Precision SPRK Fail	Change LA7, LA8 to 0 ohm	Design issue--Check list coverage inadequate	檢視清單中，未能涵蓋的問題			V			
19	45	Cost down	2012/1/4		Reserve CI14(150uF) and add CI22(10uF), CI23(10uF)	Cost down				V			
20	8, 11, 12, 17, 18, 21, 22, 26, 33, 35, 37, 38, 40, 41, 42, 43, 44, 45, 46, 47	Change 0 ohm footprint to shortpad	2012/1/4		Change RU31, RU34, RU75, RU62, RU88, RU97, RU98, RU100, RU108, RU109, RU111, RU118, RU94, RH44, RH105, RH106, RH108, RH110, RH112, RH101, RH103, RH111, RH197, RH222, RH199, RV337, RZ4, RV415, RV424, RI27, RI26, RV449, RE60, RE34, RE35, RE61, RE39, RE41, RE27, RE45, RE46, RE10, RE31, RE16, RE25, RE22, RE26, RN44, RN45, RN46, RN48, RN49, RN50, RN51, RL5, RL6, RM10, RM13, RM20, RM21, RN29, RJ3, RJ4, RJ5, RI7, RI10, RI11, RI12, RI13, RI17, RI22, RI23, RI24, RI25, RA5, RA50 to shortpad	Cost down				V			
21	40, 46		2012/1/5	Audio Precision Headphone out	Modify JTB1 Pin9 to UA2 Pin31 (CPVREF)	Design issue--Check list coverage inadequate	檢視清單中，未能涵蓋的問題			V			
22	45	For buyer suggestion change to PI5USB1457	2012/1/9		Change U13 PN to SA00004RE0L and reserve RI28 for PWRSHARE_EN_EC# signal from EC	Design issue--Check list coverage inadequate	檢視清單中，未能涵蓋的問題			V			
23	46	For Audio precision EA	2012/1/9		Change CA27, CA33 PN to SGA00004D00	Design issue--Check list coverage inadequate	檢視清單中，未能涵蓋的問題			V			
24	35	Change LVDS CONN Footprint	2012/1/10		Change JLVDS PN and Footprint to SP01001BT00&ACES_59003-04006-001_40P Add RA17 and reserve RA12 to AGND for CPVREF signal	Others				V			
25	46	Audio Vendor review suggestion	2012/1/10		Change LA1 to 0 ohm Add RA18 for MIC1 signal	Others				V			
26	47				Change RA41, RA43, RA46, RA48 to 33K, RA49, RA51, RA52, RA58 to 60.4K Change RA50 to 0 ohm	Others				V			
27	17, 25, 35, 38		2012/1/11	Battery can't Charge	Change Ambient Light Sensor, GPU SMBus to PCH_SMLCLK_PCH_SMLDATA Reserve QH3 for EC to PCH SMBus Change QV21, QM4 from EC_SMB_CK1/EC_SMB_DA1 to PCH_SMLCLK_PCH_SMLDATA Change RV303 to 10K, RV302 to 4.99K and RV309, RV310 value add GV@. Add RV309 45.3K for GS@	Design issue--Check list coverage inadequate	檢視清單中，未能涵蓋的問題			V			
28	25	Nvidia vendor strap pin suggestion	2012/1/11		Update power circuit Add LA9	Vendor design issue		V					
29	52~64	Update power circuit	2012/1/11		Update power circuit	Others				V			
30	47	For breakdowns	2012/1/11		Update power circuit	Others				V			
31	52~64	Update power circuit	2012/1/12		Update power circuit	Others				V			
32	25, 12	Layout placement	2012/1/12		Change RV337 to 0.0605, delete RU94	Others				V			
33	34	Follow XPS14 design	2012/1/12		Change RZ17 to 100K	Others				V			
34	58, 42	For QT reserve it	2012/1/12		Change RE61, RE22, RM10, RM13 to 0.0402	Others				V			
35	35	Cost down	2012/1/12		Reserve QM4, RH56, RH54 and mount RM23, RM15	Others				V			
36	35		2012/1/13	GPU 1.5VSDGPU voltage drop	Change U22 PN to SB0000030L	Design issue--Check list coverage inadequate	檢視清單中，未能涵蓋的問題			V			
37	38		2012/1/13	USB Charge can't wake up system	Change RE32 PU to +3VLP	Design issue--Check list coverage inadequate	檢視清單中，未能涵蓋的問題			V			
38	39	EMI reset reserve for ESD	2012/1/13		Reserve DE6	ME.SA request design change				V			
39	40		2012/1/13		Change H3 footprint to H_3P3	ME.SA request design change				V			
40	52~64	Update power circuit	2012/1/13		Update power circuit	Others				V			
41	46	Layout placement	2012/1/13		Change CA27, CA33 footprint to C_B2	Others				V			
42	39	Cost down	2012/1/13		Change SV1 PN to SJ1000003100	ME.SA request design change				V			
43	25	Nvidia vendor strap pin suggestion	2012/1/13		Change RV315 to 4.99K	Vendor design issue				V			
44	33	HF part	2012/1/13		Change RZ10, RZ11, RZ15 PN to SD028220ASL	Others				V			
45	52~64	Update power circuit	2012/1/16		Update power circuit	Others				V			
46	19, 34, 35, 39, 41, 36, 47, 48	流水燈與電	2012/1/18		Change QE4, QE6, QH6, QL6, QV33, QZ9, QZ11 PN to SB000000M700 Change DE7, DES, DE9, DE10, DES PN to SC500002G00 Change DV9 PN to SC500002G00	Others				V			
47	44, 45		2012/1/18	Can't detect the [Glasier] USB3.0 HDD BOX on USB port	Mount CI1, CI7, CI14 and reserve CI18, CI19, CI20, CI21, CI22, CI23	Others				V			
48	52~64	Update power circuit	2012/1/19		Update power circuit	Others				V			
49	49	Tune system LED brightness	2012/1/30		Change R9 to 220 ohm	ME.SA request design change				V			
50	37, 24, 39	HF part	2012/1/30		Change QV38 PN to SB339040310 Change QV24 PN to SB0000008100 Change F1 PN to SP040003200	Others				V			
51	52~64	Update power circuit	2012/2/1		Update power circuit	Others				V			
52	35, 40, 45	Change Y3V CAP PN	2012/2/6		Change CI11, CV3508 PN to SE064106MSL Change CM33 PN to SE076104KSL Change CM31 PN to SE076473KSL	Others				V			
53	14	Change CAP PN	2012/7/1		Change CD7 PN to SGA00005H0L	Others				V			

EE change note for QBL00 Main Board

Item	Page	Title	Date	Issue Description	Solution Description	Cause Category	Note	Rev.	BOM	Layout
1	47	ST build MEMO change	2012/2/23	CA47 footprint not match with BOM	Change CA47 footprint to 0402 in LA7851 MB	Design issue--Check list coverage inadequate	檢視清單中，未能涵蓋的問題	1.00	V	V
2	24			CV575, CV576 PN is not match Value	Change CV575, CV576 PN to SE07110078L	Design issue--Check list coverage inadequate	檢視清單中，未能涵蓋的問題	1.00	V	V
3	12, 19, 41	0 ohm shortpad	2012/2/23		Change RU118, RH152, RL15 footprint to shortpad	Others		1.00	V	V
4	38	Board ID Table for AD channel	2012/3/2		Change RE12 to 56K	Others		1.00	V	
5	20	TPM board ID for BOM optional	2012/3/2		Add RH164 (1K) PD for WO TPM and RH163 PU for W/TPM	Design issue--Check list coverage inadequate	檢視清單中，未能涵蓋的問題	1.00	V	V
6	7	R1 & R3 BOM control for CPU PN	2012/3/5		Add U11 BOM symbol QCR1@ & QCR3@ for LA7851 Add U11 BOM symbol IVBR1@, IVBR3@, SNBR1@ and SNBR3@ for LA7852	Others		1.00	V	
7	16	Change SPI ROM PN R1 & R3 BOM control for PCH PN	2012/3/5		Change UH2 PN to SA000039A2L Add UH1 BOM symbol R1@ & R3@ for PCH PN	Others		1.00	V	
8	1	VRAM X76 BOM control for HYN1G & HYN2	2012/3/5		Add UV4, UV5, UV6, UV7, UV8, UV9, UV10, UV11 BOM symbol HYN2G@ for VRAM X76	Others		1.00	V	
9	45	Change Powershare IC to SILEGO	2012/3/5	Used Samsung i9100 phone can't detected by OS issue	Change U13 PN to SA00004VH00	Design issue--Check list coverage inadequate	檢視清單中，未能涵蓋的問題	1.00	V	
10	14	Change 330U CAP	2012/3/5		Change CD7 PN to SGA19331D0L(ESR=15)	Others		1.00	V	
11	24	R1 & R3 BOM control for GPU GV & GS PN	2012/3/5		Add U11 BOM symbol GVR1@, GVR3@, GSR1@ and GSR3@ for GPU	Others		1.00	V	
12	25	GPU strap pin setting	2012/3/5		GVHA@	Vendor design issue		1.00	V	
13	2	R1 & R3 BOM control for PCB-MB	2012/3/5		Add ZZZ BOM symbol for PCB-MB	Others		1.00	V	
14	52-62	Update power circuit	2012/3/5		Update Power circuit	Others		1.00	V	V
15	47	Change AMP chip power rail	2012/3/5	S5 power consumption in DC mode	Change UA5 power rail from B+ to +VSBP	Design issue--Check list coverage inadequate	檢視清單中，未能涵蓋的問題	1.00	V	V
16	37	0 ohm shortpad	2012/3/6		Change RV464 footprint to shortpad	Others		1.00	V	V
17	52	Update power circuit	2012/3/7	PD901 Layout footprint error	Change PD901 footprint to RHU002N06_SOT323-3(same to XPS14)	Others		1.00	V	V
18	52-62	Update power circuit	2012/3/12		Change 1.8V choke	Others		1.00	V	
19	19, 38, 17 40	EMI Request	2012/3/13	EMI_Fails at 99MHz @-1.19dB it is harmonic of PCI clo	Mount CH14, RE13, CE11 and add CE15 for CLK_PCI_LPC signal Mount R2, C8, CH13 for CLK_PCI_TPM signal	Others		1.00	V	V
20	39, 34, 46	EMI Request	2012/3/13		Add CE59 for KB_DET# signal Add CZ42 for SYSON signal and add CZ43 for SYSON# signal Mount CA20, RA14 and change to 33 ohm CA20 for HDA_BITCLK_AUDIO signal Mount CA21 for HDA_SDOUT_AUDIO signal Add CA35 for CPVREF_R signal	Others		1.00	V	V
21	35, 46, 47	0 ohm shortpad	2012/3/13		Change RM15, RM23 footprint to shortpad Change LA1 footprint to shortpad Change RA50, RA53, LA7, LA8 footprint to shortpad	Others		1.00	V	V
22	52-62	Update power circuit	2012/3/14		Update Power circuit	Others		1.00	V	V
23	38	0 ohm shortpad	2012/3/14		Change RE61, RE22 footprint to shortpad	Others		1.00	V	V
24	37	Update JMDP footprint	2012/3/14		Change JMDP footprint	ME/SA request design change	其他設計單位要求的設計變更	1.00	V	V
25	14	Change 330U CAP	2012/3/15		Change CD7 PN to SGA00002281(ESR=15) and footprint to C_SX	Others		1.00	V	V
26	46		2012/3/16	DTM issue (Ti switch 在 inbox driver 下，combo Jack 偵測	Mount RA12 and reverse CA35	ME/SA request design change	其他設計單位要求的設計變更	1.00	V	
27	16	Sourcer request to remove TXC 32.768K crystal in BOM	2012/3/19		Change YH1 PN to SJ10000BM00	Others		1.00	V	
28	48		2012/3/19	System LED Brightness	Change R15 to 100 ohm	ME/SA request design change	其他設計單位要求的設計變更	1.00	V	
29	48		2012/3/21	Fine tune system LED Brightness	Change R9 to 100 ohm	ME/SA request design change	其他設計單位要求的設計變更	1.00	V	
30	39		2012/3/22		Change SW1 PN to SN100002M10	ME/SA request design change	其他設計單位要求的設計變更	1.00	V	
31	38, 40		2012/3/22	PCI clock EA fail for EMI soulation	Change C8, CE11 to 10P for CLK_PCI_TPM	Design issue--Check list coverage inadequate	檢視清單中，未能涵蓋的問題	1.00	V	
32	38		2012/3/22	OTP fail for PQ205 2nd source	Change RE59 to 1M and RE32 to 100K	Design issue--Check list coverage inadequate	檢視清單中，未能涵蓋的問題	1.00	V	
33	46	Change FSOV back to 300mV	2012/3/23		Change CA27, CA33 to 150uF	Others		1.00	V	
34	19, 38		2012/3/23	PCI clock EA fail for EMI soulation	Reserve CH14, CE15	Others		1.00	V	
35	41, 43, 52	SB000009610 turned to EL	2012/3/26		Change QL5, QN5, QN6, PQ904 PN to SB00000960L	Others		1.00	V	

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